

[BQ79606A-Q1](http://www.tij.co.jp/product/jp/bq79606a-q1?qgpn=bq79606a-q1) JAJSH94 –APRIL 2019

BQ79606A-Q1 車載バッテリ・パック・アプリケーション用のハードウェ ア・プロテクタ内蔵 **SafeTI™** 高精度モニタ

1 特長

TEXAS

INSTRUMENTS

- ¹ 車載アプリケーションに対応
- 下記内容で AEC-Q100 認定済み
	- デバイス温度グレード 2:動作時周囲温度範囲 -40℃~+105℃
	- デバイス HBM ESD 分類レベル 2
	- デバイス CDM ESD 分類レベル C4B
- 電圧モニタ、温度モニタ、および通信機能: SafeTI™-26262 ASIL-D 準拠
- • オフセット付きで ±1.1mV のセル電圧測定精度
- 最小 1.2Hz の構成可能なデジタル・ローパス・ フィルタ
- セル電圧の同時測定をサポート
	- 1ms 未満で完全な精度でスタックを測定 (96 セル の場合)
- オプションのリング型アーキテクチャにより、通 信ケーブルが破損した場合でもスタック通信を保 証
- 3~6 セルの接続と、最大 6 つの NTC/補助チャネ ルを監視
	- 16 ビットのアナログ / デジタル・コンバータ (ADC) を内蔵
- 高電圧 AFE フィルタ・コンポーネントを内蔵
- 堅牢なホットプラグ性能を備えるように設計
- 最大 64 デバイスのスタック構成 (1 ベース + 63 スタック、384 直列セル)
- 絶縁差動デイジー・チェーン通信 – 変圧器またはコンデンサ・ベースの絶縁をサポート
- 設定可能な SINC3 デジタル・フィルタ
- ハードウェア保護機能を内蔵
	- セルの過熱および低温に対する 2 次的保護
	- セルの過電圧および低電圧に対する 2 次的保護
- ハードウェア保護機能:SafeTI™-26262 ASIL-B 準拠
- 最大 150mA のセル・バランス用 MOSFET を内 蔵
- BCI テストに合格するように設計
- UART ホスト・インターフェイス
- **2** アプリケーション
- 電気自動車、プラグイン・ハイブリッドおよびハ イブリッド自動車
- 車載用 12V および 48V リチウムイオン・バッテ リ・システム
- グリッド・ストレージ・バッテリ・システム
- 無停電電源 (UPS)
- 電動自転車と電動スクーター

3 概要

BQ79606A-Q1デバイスは3~6のバッテリ・セルについ て、同時に高精度でチャネル測定を行えます。 BQ79606A-Q1 デバイスはデイジー・チェーン通信ポート を内蔵しているため、スタック可能 (最大 64 デバイス) で あり、電気自動車のドライブ・トレイン用バッテリ・パックに 見られるような大きなスタック構成に対応できます。セル入 力ごとにデルタ・シグマ・コンバータを備えているため、 BQ79606A-Q1 を使うと各バッテリ電圧を同時に測定でき ます。

BQ79606A-Q1には補助ADCが内蔵されており、最大6 つまでのNTCおよび内部レールのセル温度を測定できる ため、デバイスの安全性チェックが可能です。ダイ温度の 測定用ADCも内蔵されており、温度補正によって拡張温 度範囲全体で高精度の結果が得られます。

製品情報**[\(1\)](#page-0-0)**

(1) 利用可能なすべてのパッケージについては、このデータシートの末 尾にある注文情報を参照してください。

単純化したシステム図

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4 改訂履歴

5 概要**(**続き**)**

BQ79606A-Q1 デバイスへのホスト通信は、専用の UART インターフェイスで行います。さらに、コンデンサと変圧器の両 方の絶縁に対応する絶縁型差動デイジー・チェーン通信インターフェイスにより、ホストはバッテリ・スタック全体と通信でき ます。このデイジー・チェーン通信インターフェイスは、通信ラインが破損した場合にホストがスタックのどちらの端のデバイ スとでも通信できるように、オプションでリング型アーキテクチャに構成することもできます。

6 Pin Configuration and Functions

Pin Functions

Pin Functions (continued)

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Pin Functions (continued)

Pin Functions (continued)

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Specified for voltage spikes less than 100µs in duration for a maximum cumulative lifetime of 1000hours above 33 V.

7.2 ESD Ratings

(1) AEC Q100–002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS–001 specification.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)

7.4 Thermal Information

7.5 Electrical Characteristics

 $\rm{V_{BAT}}$ = 5.5V to 30V, all LDOs operating in regulation, Typical Applications Circuit used, 3 to 6 cells connected, –40°C to +105°C free-air temperature range (unless otherwise noted)

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 $V_{BAT} = 5.5V$ to 30V, all LDOs operating in regulation, Typical Applications Circuit used, 3 to 6 cells connected, -40°C to +105°C free-air temperature range (unless otherwise noted)

7.6 Timing Requirements

 $V_{BAT} = 5.5V$ to 30V, all LDOs operating in regulation, Typical Applications Circuit used, 3 to 6 cells connected, -40°C to +105°C free-air temperature range (unless otherwise noted)

7.7 Typical Characteristics

8 Detailed Description

8.1 Overview

The BQ79606A-Q1 is a voltage monitoring device for large battery stack systems. The device has the ability to measure single cell voltages as well as the voltage across any connector used to create larger battery stacks in a module. The BQ79606A-Q1 is designed with low voltage differential daisy chain communication, allowing for the connection of up to 64 (1 base and 63 stack) BQ79606A-Q1 devices. The combination of devices allows for easy combination of batteries to achieve the desired voltage of the system.

> 注 Throughout the document, '*' are used as wild cards (typically to indicate numbers such as CELL* means CELL1-CELL6. Additionally, bits are referred to in the following convention REGNAME[BITNAME].

> > 注

Throughout the document, Bridge, Base, and Stack devices terminology are used. Bridge is used for devices connecting the uC with stack devices through UART and DO NOT monitor cell voltages. Base is used for devices connecting the uC with the stack devices through UART and monitors cell voltages at the same time. Stack devices monitors the cell but do not communication directly with uC through UART.

8.2 Functional Block Diagram

8.3 Feature Description

This section includes the descriptions of the individual blocks found in the BQ79606A-Q1 device.

8.3.1 Power Supplies

The BQ79606A-Q1 generates all of the required supplies for operation. There are 3 integrated LDO supplies as well as a buffered reference to supply the bias for the GPIO* NTC monitoring linearization ciruits (for temperature sensing).

8.3.1.1 AVDD LDO

The AVDD low dropout regulator (LDO) is the supply for the analog circuits in the BQ79606A-Q1. The supply for AVDD comes from LDOIN. AVDD contains an over-voltage comparator that signals a fault (RAIL_FAULT[AVDDOV]) when the voltage at AVDD rises above V_{AVDDOV} . Additionally, AVDD contains an under-voltage circuit that sends the IC into Digital Reset when AVDD drops below V_{AVDDUV} . Upon restarting, a fault is indicated (RAIL_FAULT[AVDDUV_DRST]) to inform the host why the IC failed. Additionally, AVDD is continuously monitored for abnormal oscillations that can result in undesired operation. If such an oscillation occurs, the SYS_FAULT2[AVDD_OSC] bit is set.

8.3.1.2 VLDO LDO

The VLDO low dropout regulator (LDO) is the supply for the daisy chain transceiver circuits in the BQ79606A-Q1. The supply for VLDO comes from LDOIN. VLDO contains an overvoltage comparator that signals a fault (RAIL_FAULT[VLDOOV]) when the voltage at VLDO rises above V_{VLDOOV} .

8.3.1.3 DVDD LDO

The DVDD low dropout regulator (LDO) is the supply for the digital circuits in the BQ79606A-Q1. The supply for DVDD comes from LDOIN. DVDD contains an overvoltage comparator that signals a fault (RAIL_FAULT[DVDDOV]) when the voltage at DVDD rises above V_{DVDDOV} . Additionally, DVDD contains a comparator that sets digital in reset mode if DVDD drops below V_{DRDVDD}. Additionally, the DVSS pin is monitored continuously and the SYS_FAULT2[DVSS_OPEN] bit is set if an 'open' condition is detected for DVSS.

8.3.1.4 TSREF

The TSREF is a 2.5V buffered REF1 reference that supplies the GPIO* linearization circuits when measuring external temperature sensors. This allows the ADC to operate from the same reference and provide a ratiometric result for GPIO*. TSREF is capable of supplying up to I_{TSREF} current limit and must not be used to power any circuits other than the resistor dividers for GPIO*. Enable TSREF using the CONTROL2[TSREF_EN] bit. The startup time for TSREF is determined by the external capacitance and the current limit. The time is calculated using the simple capacitor charging equation. No GPIO measurements should be taken until TSREF is settled at the regulation point.

See *Ratiometric [Measurement](#page-234-0) Configuration* for details on selecting the resistors. TSREF contains an overvoltage comparator that signals a fault (RAIL_FAULT[TSREFOV]) when the voltage at TSREF rises above V_{TSREFOV}. Additionally, TSREF contains an under-voltage circuit that signals a fault (RAIL_FAULT[TSREFUV]) when TSREF drops below $V_{TSREFUV}$. Additionally, TSREF is continuously monitored for abnormal oscillations that can result in undersired operation. If such an oscillation occurs, the SYS_FAULT2[TSREF_OSC] bit is set.

8.3.1.5 Internal Supply Rails

AVAO_REF (Analog Voltage Always On) is a fully internal rail that runs from the BAT input. It powers low current circuits that are required in all modes. AVAO_REF is continuously monitored for over and under voltage conditions. The overvoltage comparator signals a fault (SYS_FAULT1[AVAO_REF_OV]) when the voltage at AVAO_REF rises above V_{AVAO_REF_OV}. Additionally, AVAO_REF contains an under-voltage circuit that puts the IC into POR mode if V_{AVAO} REF drops below V_{AVAO} REF_UV.

8.3.1.6 CVDD and VIO Supplies

CVDD is the supply input for the daisy chain transceiver circuits. CVDD receives it's power externally from VLDO. This allows for external filtering for noisy applications. CVDD is monitored for under-voltage constantly. If V_{CVDD} < V_{CVDDUV} the RAIL_FAULT[CVDDUV] bit is set. Additionally, the CVSS pin is monitored continuously, and the SYS_FAULT2[CVSS_OPEN] bit is set if an 'open' condition is detected for CVSS.

VIO is the supply for digital inputs. The RX, WAKEUP (for base) and NFAULT (if used) pins are all referenced to VIO (TX must be pulled high at host side). VIO is supplied from the system logic supply, or is connected to VLDO or CVDD for stack devices (for systems without a logic supply). VIO is monitored for under-voltage constantly. If V_{VIO} < V_{VIOUV} the SYS_FAULT3[VIOUV] bit is set. Do not toggle VIO in shut down mode, otherwise a device could exit shutdown mode.

8.3.1.7 Startup

The LDOs are on in the different modes as described in *Device [Functional](#page-43-0) Modes*. Upon power up, the startup is shown in $\boxed{2}$ 2.

図 **2. Startup Diagram**

NSTRUMENTS

FXAS

Feature Description (continued)

図 **3. Startup Diagram (Bridge Configuration)**

After power up and the wake up (tone or command) is sent, the following steps are required to sync the DLL (Delay-Locked Loop) ramp in both direction:

- 1. Broadcast write command to write "0x00" hex value to ECC_TEST register
- 2. Perform auto addressing by sending a broadcast command to set CONTROL1[ADD_WRITE_EN]=1 (to enable addressing)
- 3. Broadcast write consecutive addresses to DEVADD_USR[ADD] until all parts have been assigned a valid address
- 4. Set the Base by writing 0 to CONFIG[STACK_DEV] of the first device
- 5. Set the Stack by writing 1 to CONFIG[STACK_DEV] of the other device (other than first and last)
- 6. Set Top of Stack to the top device by writing 1 to CONFIG[TOP_STACK] of the top device
- 7. Broadcast dummy read attempts such as reading register ECC_TEST (host may not get the data)
- 8. Clear the faults if DLL causes any COMH and COML errors.

注

The host must wait for the device to fully wake up ($t_{\text{SU(WAKE)}}$) before sending shutdown, sleep, wake up commands.

8.3.2 Precision References

REF1 and REF2 are precision references used by the BQ79606A-Q1 to achieve high performance. REF1 is used for the ADC functions as well as providing the TSREF reference. REF2 is used for the protector functionality and used to check accuracy and diagnostics. REF1 is active whenever the BQ79606A-Q1 is in ACTIVE mode and REF2 is active in both SLEEP and ACTIVE. The REF1 reference is not active in SLEEP mode however the REF1 pin is powered from the AVDD through an internal voltage divider.

An oscillation detector monitors REF1 and sets the SYS_FAULT2[REF1_OSC] bit whenever it senses a REF1 oscillation. To avoid false trips during startup, the oscillation detection is disabled for the first 10ms of REF1 startup (IC transitions into ACTIVE state).

注

Contact TI Sales Associate or Applications Engineer for further information about long term drift.

8.3.3 Analog Front End

The BQ79606A-Q1 AFE allows monitoring of up to 6 cells. The interface to these cells is provided using seven VC inputs, labeled VC0 through VC6. The cell monitoring is programmable for on-demand or continuous sampling of all, or a subset, of the connected cells. When multiple cell conversions are selected, either ondemand or continuous, the cell voltages are read simultaneously to provide a snapshot of the stack voltage at a particular point in time. This allows for measurements to be synchronized with current readings and enable a more accurate gauging solution.

Nearly all of the components required for analog front end filtering and surviving hot-plug testing are integrated into the BQ79606A-Q1. Additionally, for hot-plug requirements, the device can handle high voltage spikes of up to +/-33 V, therefore no Zener and regular diode clamps are required for voltage spikes below that level. For voltage spikes that may be higher than the absolute maximum rating of the device, additional clamping is required. An external RC filter on VC* and CB* is required to filter out high frequency voltage spike and hot-plug events. The pins are internally clamped to facilitate the use of the inexpensive, low voltage (10V) ceramic capacitors. See *VC* [Inputs](#page-231-0)* for more details on selecting these components.

8.3.3.1 VC Current Sinks and Sources

The VC_CS_CTRL register allows the host to enable current sinks (VC1-VC6) or current source (VC0) to attempt to pull the pin up/down to diagnose a VC open-wire condition. There are no internal comparisons done on the pins, it is up to the host to diagnose an open-wire condition using the ADC's. The current sources/sinks are limited to I_{OWSNK} and I_{OWSRC} , therefore special attention must be paid to the size of the external components and the time it takes to discharge any external capacitance.

8.3.4 Delta-Sigma (ΔΣ) Converters

The BQ79606A-Q1 integrates 8, high accuracy Delta-Sigma ADCs for measuring the cell and other voltages in the system. The cell voltages are monitored using 6 independent ADCs to enable simultaneous measurements. An additional ADC is integrated to measure external NTCs or voltages as well as other internal rails. The DIE temperature is monitored using a dedicated ADC. Each sense input, VC0 to VC6, is intended to connect to the single cell of a battery stack or the module connector of a sub-stack in the system. Each block contains a Delta-Sigma analog to digital converter (ADC) that samples and converters the voltage present between the pins VCn and VCn-1 during a sample.

- Cell Voltage ADC one ADC per Channel
- DIE Temperature ADC
- Auxiliary ADC
	- Cell Voltage (selected by AUX_CELL_SEL bits)
	- Total Stack Voltage (BAT voltage)
	- REF2
	- ZERO (0V) Reference
	- AVDD LDO
	- GPIO1-GPIO6
	- REF3
	- OV DAC
	- UV DAC
	- OT DAC
	- $-$ UT DAC
	- VPTAT
	- DVDD LDO

- TSREF LDO
- CVDD
- AVAO_REF

8.3.4.1 ADC Architecture

The entire signal chain, as seen in \boxtimes 4, consists of an internal input filter, a modulator, a SINC³ filter, and a digital low pass filter; each of these is described in more detail below.

図 **4. Battery Voltage Signal Chain**

8.3.4.1.1 Internal Input Filter

The purpose of the internal input filter is to limit the bandwidth seen by the modulator to ensure aliasing effects seen at multiples of the modulator's sample frequency are significantly reduced. The corner frequency of this internal input filter is 1.5kHz, significantly below the sample frequency of the modulator to avoid aliasing effects.

8.3.4.1.2 Modulator

The modulator has a functional block diagram as shown in \boxtimes 5. The Delta Sigma used is a second order modulator and consists of a difference amplifier, the "Delta," and an integrator, the "Sigma," followed by a second difference amplifier and integrator. The output of the second integrator is the input to a comparator that produces a pulse train with the density of pulses proportional to the voltage at the input. This pulse train is converted back to a voltage through the 1-bit DAC to be fed into the Delta stages.

図 **5. Simplified Modulator Block Diagram**

8.3.4.1.3 SINC³ Digital Filter (CIC)

The digital filter used in the BQ79606A-Q1 is a Cascaded Integrating Comb (CIC) filter, often referred to as a SINC^x filter, where the "x" represents the order of the filter. The simplified block diagram of the filter is shown in **[図](#page-24-0) 6**. The BQ79606A-Q1 contains a 3rd order CIC filter, meaning there are three storage elements on both sides of the decimation switch. The Decimation Ratio, or DR, references to the rate of reduction applied to the sample clock of the modulator. The front half of any SINC³ filter, which integrates the modulator output, is run at the same clock rate as the modulator. The back half of the SINC³ filter, which generates the comb, runs at the decimated clock rate, as shown.

図 **6. Simplified CIC Digital Filter Block Diagram**

The SINC³ filter will result in the frequency response. Note that the decimation ratio, DR, impacts the width of the passband; the higher DR the lower the corner frequency of the filter. The order of the filter also sets the gain, as $G = -20^{\text{ORDER}}$ dB/Decade.

注

Decimation Ratio is also called Over-Sampling Rate, or OSR, in other descriptions of a SINC^x filter. The SINC^x filter name is historic, as the transfer response, which is beyond the scope of this document to derive, is similar to the classic definition of sinc (x) , or $sin(x)/x$.

8.3.4.1.3.1 Example Frequency Response of a Delta-Sigma Converter

The decimation ratio (DR) directly correlates to how quickly a conversion result is available to be read from the ADC. Lower DR corresponds to faster conversion time and lower effective number of bits (ENOB).

The reference voltage used in the modulator has an internal correction that is applied automatically. This correction is shown in \boxtimes 4 as occurring immediately after the SINC³ filter. This correction becomes overhead to the conversion time. The uncorrected value is also made available for host access in the event that external correction is required to account for reference voltage shifts. See Register: [VC3COEFF5](#page-136-0) for details about the conversion times and ENOB at different DRs.

The decimation ratio is configured using the CELL_ADC_CONF1[DR] (for the cell ADCs) and AUX ADC CONF[DR] (for the AUX ADC). The temperature ADC settings match the CELL ADC settings.

8.3.4.1.4 Single Pole Digital Filter

In addition to the SINC³ filter, a digital implementation of a simple, first-order, single pole (RC) filter is also included. The implementation is shown in \boxtimes 7. This filter allows for much lower corner frequencies for the digital filter and the implementation does not require a fixed point multiplication stage. This filter always uses the corrected VREF value coming from the SINC³ filter. When enabled, the cell ADCs are run in continuous mode with the minimum interval setting, updating the uncorrected non filtered (VCELL*_HU, VCELL*_MU, and VCELL^{*} LU), the corrected non filtered (VCELL^{*}H and VCELL^{*}L), and the corrected and filtered (VCELL^{*} LF and VCELL*_HF) registers every time the host reads High byte (H).

図 **7. Single Pole Digital Filter Implementation**

The corner frequency of the single pole digital filter is set with the CELL_ADC_CONF1[FILSHIFT] bits, as shown in [表](#page-25-1) 2.

NF1[FILSHIFT]	CELL_ADC_CO Typical Corner Frequency (Hz) DR=256	Typical Corner Frequency (Hz) DR=128	Typical Corner Frequency (Hz) DR=64	Typical Corner Frequency (Hz) DR=32
0b000	180.1	360.2	720.4	1440.8
0b001	83.1	166.2	332.4	664.8
0b010	40.1	80.2	160.4	320.8
0b011	19.7	39.4	78.8	157.6
0b100	9.8	19.6	39.2	78.4
0b101	4.9	9.8	19.6	39.2
0b110	2.4	4.8	9.6	19.2
0b111	1.2	2.4	4.8	9.6

表 **2. Digital RC Corner Frequencies (Does not include correction time in calculation)**

The single pole digital filter responds in the same way as an analog RC circuit responds, meaning that unless conversions are run continuously through the filter there is a step response that must be taken into account before reading the value for the first time. The step response of each corner frequency setting is shown below. This step response should be taken into account whenever starting up the conversions after coming out of SLEEP or SHUTDOWN modes or a significant jump in the input. Once the output voltage gets through the step response the host can read the voltage at any time interval to have a snapshot of the cell voltage.

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VCELL* LU (lower byte) registers. See $\frac{1}{\sqrt{6}}$ 3 for more details.

表 **3. CELL ADC**

The VC* inputs measure voltages of -2V to 5V (cells 2-6, VC1 to VC6 and CB pins not connected) and 0V to 5V (cell 1, VC0 to VC1). Connect unused inputs to the highest-connected cell. For example, in a 4-cells system, connect the unused VC5 and VC6 inputs to VC4. Channels are used from lowest to highest, with VC0 connected to the (–) terminal of the bottom cell. To achieve the highest accuracy over temperature, the BQ79606A-Q1 samples the die temperature whenever a VC^{*} measurement is taken and then applies temperature correction to the ADC result to correct for any changes in the reference over temperature. Both the corrected and uncorrected values are available to be read by the host. The corrected non filtered values are in the VCELL*H (higher byte)

and VCELL^{*}L (lower byte) registers, and the lowpass filtered corrected results are contained in the VCELL^{*} HF (higher byte) and VCELL*_LF (lower byte). See the Single Pole [Digital](#page-25-2) Filter for more details on the digital lowpass filter. The uncorrected non filtered values are in the VCELL^{*}_HU (higher byte), VCELL^{*}_MU (middle byte) and VCELL^{*} LU (lower byte) registers. The uncorrected values are available for the host to use to apply different correction coefficients. The uncorrected data also can be filtered if DIAG_CTRL4[VCFILTSEL]=1 and DIAG_CTRL4[CELUSEL]=1, the values are in the VCELL*_HU (higher byte), VCELL*_MU (middle byte) and

The measurement results require multiple registers. Reads must be done starting with the H byte register. This locks the M (when applicable) and L registers to ensure that the read values come from the same measurement and do not change mid-read. Best practice is to "burst read" all of the registers of interest. This note applies for AUX and DIE temperature ADCs as well.

ADC measurements for the cell voltages inputs are available either on-demand (single conversion) or continuously (with optional programmed delay between conversions). The ADCs integrated into the BQ79606A-Q1 are capable of 16-bit resolution for the corrected measurement or 24-bit resolution for the uncorrected measurements. Corrected values are 16 bits and are presented in H and L registers. Uncorrected values are 24 bit and are presented in H, M, and L registers.

8.3.4.2 CELL ADC

注

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The values returned from the ADC conversion for these channels are in 2's complement form. When converting the register value to a voltage, first the number must be converted from 2's complement to a decimal number as follows for 16-bits :

$$
2\,scomp = -a_{15} \times 2^{15} + \sum_{i=0}^{14} a_i \times 2^{i}
$$

and for 24-bits

$$
2\,scomp = -a_{23} \times 2^{23} + \sum_{i=0}^{22} a_i \times 2^i
$$

Where a_i is the bit value (a_{15} MSB to a_0 LSB) of the measurement results from the ADC. The same equations applies for CELL ADC, AUX ADC, and DIE temperature ADC.

In order to provide the host a way to diagnose a "stuck value" in the result registers, the ADC output registers are initialized to 0x8000 for 16 bit data and 0x800000 for 24 bit data value with every ADC_GO command. The 0x8000 and 0x800000 value are an impossible results to read under normal operating conditions and if read, the host easily recognizes this as an incorrect value and can act accordingly.

The host selects which measurements are to be done using the CELL_ADC_CTRL register. For the cell measurements (CELL_ADC_CTRL), enabling the channel, enables the internal level shifter to prepare for the ADC measurement. For best accuracy measurements, the host must wait at least $t_{DLY(COM)}$ after enabling the cell channels before requesting a measurement to ensure proper settling time. The cells do not require enabling/disabling with every measurement. It is recommended that the cells are enabled and left on while the host is actively requesting ADC samples to avoid repeated delay times.

Once the channels are selected and settled, the CONTROL2[CELL_ADC_GO] is used to start the conversions. Additionally, a time delay may be added from when the CELL_ADC_GO bits are written to when the conversion starts using the ADC_DELAY[DLY] bits. This allows the host to synchronize multiple measurements between separate devices (for example, synchronizing the cell measurements with an external current measurement).

8.3.4.2.1 Continuous CELL ADC Conversions

To setup continuous ADC conversion, the host enables the cells using the CELL_ADC_CTRL register as with the single conversion case. Additionally, the host must set the CELL_ADC_CONF2[CELL_CONT] bit. The conversion interval between cell ADC conversions is programmed using the CELL_ADC_CONF2[CELL_INT] bit. After these registers are updated, the host must send a second write to set the CONTROL2[CELL_ADC_GO] bit.

Once the first conversion is complete, the ADC waits the programmed interval time (set by CELL_ADC_CONF2[CELL_INT]) and starts the next conversion.

Once all of the cell conversions are complete for the first interval, the DEV STAT[DRDY CELL] is set. The DEV_STAT[DRDY_CELL] bit remains set after the first conversion during continuous conversions. The flag is cleared only when a new ADC conversion is initiated by writing the CONTROL2[CELL_ADC_GO] bit. Additionally, a 14-bit counter (CONV_CNT*) keeps track of the number of conversions done during the continuous conversion mode. The counter is incremented with every conversion. During continuous conversions, the last valid conversion results are always available in the results registers after the H byte register is read. To stop continuous conversions, the host must clear the ADC_CONF2[CELL_CONT] bit and then write the CONTROL2[CELL_ADC_GO] bit. This will begin one additional conversion, but the continuous conversions are discontinued.

During continuous conversions, any changes to the CELL_ADC_CONF* and CELL_ADC_CTRL registers are ignored. To make changes during continuous conversions, the host must stop ADC conversions by clearing the CELL_ADC_CONF2[CELL_CONT] bit and then writing the CONTROL2[CELL_ADC_GO] bit to stop the continuous conversions, update the CELL_ADC_CONF*, and CELL_ADC_CTRL registers, and then set the CONTROL2[CELL_ADC_GO] bit to restart continuous conversions. For best results when using the single pole lowpass digital filter, the cell conversions must be set to continuous conversions with the minimum interval setting.

(1)

(2)

8.3.4.2.2 On-Demand CELL ADC Conversion (Single Conversion)

During on-demand reads, the host enables the desired cells using the CELL_ADC_CTRL register. After this register is updated, the host must wait at least t_{DLY(COM)} before sending a second write to set the CONTROL2[CELL_ADC_GO] bit to start the cell conversion. When the CELL_ADC_GO bit is set, the CELL ADCs simultaneously start the conversion with the enabled cell channels. The cell voltage conversions happen simultaneously. The results are available as the individual conversions complete. The DEV STAT[CELL STAT] bit is set while the respective ADCs are running. Once all of the cell conversions are complete, the CELL_STAT bit is cleared and after the result(s) are updated in the registers the DEV_STAT[DRDY_CELL] bit is set. The host is ensured that the register information is current and may read the results from the conversion (read the H byte register to update the M and L bytes). If the host reads from the register prior to the conversion finishing, the 0x8000 diagnostic result is read. Writing to the CONTROL2[CELL_ADC_GO] bit during a cell conversion terminates the current conversion and begins a new conversion.

8.3.4.3 DIE Temperature ADC Measurement

To get maximum accuracy, an independent ADC (DIE temperature ADC) is used to measure the BQ79606A-Q1 die temperature. A die temperature reading is taken simultaneously with the cell measurements and used to correct the other ADC results for temperature variations in the die. To ensure the most accurate results, a cell ADC conversion must be done whenever an auxiliary ADC conversion is done to ensure the most recent temperature conversion is obtained. Otherwise, the last temperature result is used in the correction and may not be valid.

The junction temperature of the die is measured with every cell conversion (using CELL ADC). The reported result in the DIE_TEMPL and DIE_TEMPH registers is the voltage from the temperature sensor. Similar to the voltages, the value in DIE TEMP^{*} is in 2's complement format. The die temperature is calculated using the equation listed in $\frac{1}{6}$ 4

表 **4. DIE Temperature ADC**

8.3.4.4 AUX ADC

8.3.4.4.1 On-Demand AUX ADC Conversion (Single Conversion)

The AUX ADC does not support continuous conversion (unlike the CELL ADC). During on-demand reads, the host enables the desired cells or auxiliary inputs to convert using the AUX_ADC_CTRL^{*} registers. After these registers are updated, the host must send a second write to set the CONTROL2[AUX_ADC_GO] bit to start the auxiliary ADC conversion. When the AUX_ADC_GO bit is set, the AUX ADC starts the conversion with the first auxiliary ADC channel. The auxiliary conversions must sequence through each of the enabled channels in the sequence shown in $\boxed{8}$ [16](#page-30-0).

注

Reads must be done starting with the H byte register. This locks the M (when applicable) and L registers to ensure that the read values come from the same measurement and do not change mid-read. Best practice is to "burst read" all of the registers of interest.

The DEV_STAT[AUX_STAT] bit is set while the AUX ADC is running. Once all of the auxiliary ADC conversions are complete, the AUX_STAT bit is cleared and after ALL of the results(s) are updated in the registers the DEV_STAT[DRDY_AUX] bit is set. Once the DRDY_AUX bit is set, the host is ensured that the register information is current and may read the results from the conversion. If the host reads from a register prior to the conversion finishing, the 0x8000 diagnostic result will be read. Writing to the CONTROL2[AUX_ADC_GO] bit during an AUX conversion terminates the current conversion and restarts the full round-robin.

注

If multiple channels are selected on the auxiliary ADC, the host must provide enough time for the measurements to finish before writing to the CONTROL2[AUX_ADC_GO] bit again. Otherwise, the auxiliary ADC resets and any unfinished conversions are not completed.

図 **16. Auxiliary ADC Conversion Sequence**

The following table summarizes all the AUX ADC parameters and the corresponding registers and the equation required to convert to voltage or temperature:

表 **5. AUX ADC**

EXAS NSTRUMENTS

表 **5. AUX ADC (continued)**

8.3.4.4.2 AUX CELL Voltage

The AUX ADC has an input for a selected cell voltage. The cell voltage is measured through the CB1-6 pins. This is useful for comparing to the VC1-6 results from CELL ADC to ensure correct operation of the cell ADCs. Each cell is selectable using the DIAG CTRL2[AUX CELL SEL] bit. This bit should be cleared first whenever AUX CELL SEL is changed. Selecting a cell using the AUX CELL SEL bits and enabling the function with DIAG_CTRL2[AUX_CELL_SEL_EN] routes the cell voltage from the OVUV level shifter to the AUX ADC. Additionally, selecting a cell enables the AUX CELL measurement for the auxiliary ADC. Refer to $\frac{1}{\sqrt{6}}$ 5 for more detail about AUX CELL1-6 measurements details. While the DIAG_CTRL2[AUX_CELL_SEL] bit is set to 1, the OVUV function is suspended.

注

The AUX ADC only supports positive voltage readings. When comparing the AUX_CELL measurement, only voltages from 0V to 5V are supported.

The data for the cell voltages is 16-bit (spread over two registers). To prevent the condition where a read of the full data results in data split between two reads (i.e. AUX_CELLH from first conversion and AUX_CELLL from second ADC conversion due to conversion update in the middle of a read), data for all registers for a single input are locked. For example, AUX_CELLL is locked for updates until AUX_CELLH is read. The BQ79606A-Q1 does not support reading only the MSB or LSB. The best practice is to group read all registers for a particular input.

8.3.4.4.3 AUX GPIO Input Measurement

The GPIO1 to GPIO6 input channels are available to be used to measure either ratiometric inputs (when in TS mode) or external analog voltages from 0 V to 5 V. Select the absolute or ratiometric for the individual GPIOs using the GPIO_ADC_CONF register. The GPIOs are enabled using the AUX_ADC_CTRL1[GPIO*_EN] bits.

When in Temperature Sensing "TS" operation, a resistor divider is connected from TSREF to AVSS with GPIO connected to the center tap. This linearizes the NTC curve and improves the resolution at extreme temperatures. The circuit is shown in 図 [17.](#page-32-0) Ensure that TSREF is enabled (using CONTROL2[TSREF_EN]) and settled before running any GPIO conversions.

図 **17. NTC Linearization Circuit**

The GPIO^{*} voltage measurements are available with uncorrected values (to registers AUX GPIO1 HU (MSB), AUX GPIO1 MU (middle byte) and AUX GPIO1 LU (LSB) for GPIO1 and AUX GPIO*HU (MSB) and AUX GPIO^{*} LU (LSB) for GPIO2-6)). The ratiometric ADC conversion result when in TS operation is calculated as:

$$
\%_{TSREF} = 0.00007628\% \times 2scomp
$$

To achieve the highest accuracy over temperature, a cell measurement must be taken to ensure the latest die temperature information is available for the correction. The absolute ADC conversion result when in absolute operation is calculated as:

$$
V_{\text{CHANNEL}} = 190.7349 \,\mu\text{V} \times 2 \,\text{scomp}
$$

The data for the GPIO1-6 voltages is 16-bit (spread over two registers) for the corrected and the uncorrected data (24-bit for the uncorrected data for GPIO1 only). To prevent the condition where a read of the full data results in data split between two reads (i.e. AUX GPIO*H from first conversion and AUX GPIO*L from second ADC conversion due to conversion update in the middle of a read), data for all registers for a single input are locked. For example, AUX_GPIO1_LU and AUX_GPIO1_MU are locked for updates until AUX_GPIO1_HU is read. The best practice is to group read all registers for a particular input.

8.3.4.4.4 AUX BAT Measurement

 V_{BAT} is the voltage measured from BAT to AVSS. Set the AUX_ADC_CTRL1[BAT_EN] bit to enable the BAT voltage monitoring. The stack voltage measurement is available with corrected values (registers AUX_BATH (MSB) and AUX_BATL (LSB)) and uncorrected values (to registers AUX_BAT_HU (MSB) and AUX_BAT_LU (LSB)). The values returned from an ADC conversion for this channel is converted to voltage as in $\frac{1}{3}$ 5.

(3)

(4)

The data for the BAT voltage is 16-bit (spread over two registers) for the corrected data and 24-bit (spread over three registers) for the uncorrected data. To prevent the condition where a read of the full data results in data split between two reads (i.e. AUX_BATH from first conversion and AUX_BATL from second ADC conversion due to conversion update in the middle of a read), data for all registers for a single input are locked. For example, AUX_BATL and is locked for updates until AUX_BATH is read. The best practice is to group read all registers for a particular input. The BQ79606A-Q1 does not support reading only the MSB or LSB.

8.3.4.4.5 Power Rail, DAC, References, and 0V Measurements

The auxiliary ADC has inputs for the power supplies: AVDD (result in AUX_AVDD*), CVDD (result in AUX CVDD^{*}), DVDD (result in AUX_DVDD^{*}), and TSREF (result in AUX_TSREF^{*}) voltages. The value returned from an ADC conversion for AVDD and CVDD channels is converted to voltage by:

$$
V_{\text{CVD}} = 548 \, \mu \text{V} \times 2 \text{scomp} \tag{5}
$$

 V_{AVDD} = 381.622 µV \times 2scomp (6)

The auxiliary ADC has inputs for several important references for use with diagnostics and during developmental debugging: 0V (result in AUX ZERO*), REF2 (result in AUX REF2*), REF3 (result in AUX REF3*), the AVAO_REF reference (result in AUX_AVAO*), and half of the OVUV reference (1/2 OVUV reference) and the OTUT reference results in AUX_UV_DAC*, AUX_OV_DAC*, AUX_UT_DAC*, and AUX_OT_DAC*, respectively. The value returned from an ADC conversion for these channels (including DVDD) is converted to voltage as shown in $\bar{\mathbf{\mathcal{R}}}$ 5

There is no internal threshold checking of these values. The expectation is that the microcontroller checks that the values are within the appropriate ranges.

注 The AUX_UV_DAC and AUX_OV_DAC reports 1/2 of the OVUV reference voltage.

8.3.4.4.6 VWARN PTAT measurement

The input for the TWARN PTAT voltage (result in AUX TWARN PTAT*) for use with diagnostics and during developmental debugging. VWARN PTAT can be related directly to the temperature using this equation:

TWARN_PTAT (C) =25C +($[V_{WARMPTAT}$ mV - 330mV - V_{PTAT_OFFSET} mV] / (1.17mV/C)) (7)

V_{PTAT_OFFSET} is programmed offset in hex and located in register SPARE_ 6 and converted to mV using this equation:

 $V_{\text{PTAT_OFFSET}}$ mV = 1mV \times 2scomp (8)

In addition to the normal channel selection in the AUX_ADC_CTRL^{*} register, the VPTAT input must be enabled. Before a measurement is taken for TWARN PTAT, set the CONTROL2[VPTAT_EN] bit to enable the input. After the conversion is complete, disable the input by clearing the CONTROL2[VPTAT_EN] bit. This prevents noise from coupling on to internal circuits during normal operation.

8.3.5 Cell Balancing

The BQ79606A-Q1 integrates a MOSFET for each cell to enable passive balancing with a minimum of external components. Passive cell balancing slowly discharges individual higher voltage cells to balance the voltage across all of the cells in the stack. Cell balancing reduces the aging rate differences between cells to extend the battery pack overall lifetime. The drawback to passive balancing is heat generation. The energy during discharge is dissipated across an external resistor generating heat. The cell balancing current must be chosen as a tradeoff between the time it takes to balance and the heat generated in the process. The cell balancing algorithm is fully configurable and runs autonomously once enabled. Cell balancing is terminated either when the individual timer expires, or the cell voltage reaches a programmed threshold.

External resistors set the cell balancing current. \boxtimes [18](#page-35-0) illustrates the circuit and current flow during balancing. Cell balancing is available with a CBDONE comparator function for cell voltages greater than 2.8V. ADC reads are available during cell balancing. Cell balancing sequencing is programmable to balance cells in two banks, the odd cells and the even cells. Additionally, a cell balancing comparator is integrated that monitors the cell voltages and terminates cell balancing once the voltage V_{CBDONE} threshold is reached. The cell balancing time is programmable for each individual cell. Additionally, a duty cycle timing function is built into the BQ79606A-Q1 to switch between banks during balancing to achieve a simultaneous stack balance. Using these timing features, the host microcontroller controls the specific algorithm used for cell balancing.

While active, the status of the individual cell balancing switch is indicated in the CB_SW_STAT register. As the cell balancing for each cell completes, the CB_DONE register is updated. When the timer or voltage is satisfied for a particular cell, the switch is disabled and the corresponding CB_DONE[CELL*] bit is set.

注

The CB pins must NEVER be connected to cell voltages (module connectors) that are expected to be negative. The internal FET diode will conduct and likely damage the FET in reverse voltage conditions.

図 **18. Cell Balancing Circuit**

8.3.5.1 Cell Balancing Setup and Sequencing

To setup balancing, voltage thresholds, the timers, and sequencing must all be programmed. The sequence of the cell balancing is programmed using CB_CONFIG[SEQ] bit. The sequencing can be selected to do odd cells only, even cells only, odd then even cells, or even then odd cells. Additionally, the CB_CONFIG[DUTY] and CB_CONFIG[DUTY_UNIT] bits select the duty cycle between the odd and even cells. When the odd then even or even then odd sequence is selected, setting a non-zero code to CB_CONFIG[DUTY] enables the duty cycling. The CB_CONFIG[FLTSTOP] bit controls the cell balancing behavior during fault conditions. When set, cell balancing is terminated for all cells when any UNMASKED fault occurs and the CB_DONE[ABORTFLT] bit is set.

8.3.5.1.1 Cell Voltage Monitoring Setup

The cell balancing done comparator threshold (V_{CBDONE}) is configurable using the CB_DONE_THRESH register. The voltage selected is set for all cells. The cells that are being balanced are monitored by a single comparator in a "round robin" fashion. The comparator tests the voltage for t_{CYCLE} . Additionally, the comparator signal is deglitched for $t_{doOVUVCB}$ (set using the COMP_DG[OVUV_DG] bits). The deglitch is a count up/down style deglitch. During the monitoring cycle, the comparator checks the voltage. A counter is incremented when the comparator is tripped, and decremented when the comparator is not tripped. Once the counter reaches the threshold, the cell balancing switch is disabled and the corresponding CB_DONE[CELL*] bit is set. Once the cell balancing for that cell is terminated, the cell balancing does not restart for the remainder of the cell balancing sequence regardless of the cell voltage. Similar to the hardware comparators, the cell balancing comparator may be programmed to perform BIST as it is monitoring the cell voltages. The BIST is identical to the OVUV BIST as described in [CB_DONE,](#page-41-0) OVUV, and OTUT Built-In Self Test (BIST). Once the cell balancing is enabled (CONTROL2[BAL_GO]=1), changes to the CB_DONE_THRESH and CB_DONE registers are ignored until the cycle is completed (CB_DONE is cleared when CONTROL2[BAL_GO] is set). Cell balancing must be disabled and then restarted to be able to change the settings.

The CBDONE function overrides the OVUV function (if enabled). During the cell balancing cycle, with CBDONE enabled, the OVUV function is paused (if enabled).

CB_DONE_THRESH[ENABLE] bit controls the CBDONE comparator function, when the bit is set to 0 it disables the CBDONE comparator.

8.3.5.1.2 Timer Setup and Configuration

The individual cell balancing timers are programmable using the CB_CELL* CTRL registers. The cell balancing time is programmable from 0 (no balance) to 127min. Once the cell balancing is enabled (CONTROL2[BAL_GO]=1), changes to the CB_CELL*_CTRL registers are ignored. Cell balancing must be disabled and then restarted to be able to change the timer settings. To stop cell balancing before completion, all timers must be set to 0 and then write CONTROL2[BAL_GO] = 1.

> 注 Writing a **0** to the cell balance timer bit field in the register disables cell balancing for that cell for a given CONTROL2[BAL_GO]=1 command and does not execute the balancing sequence .

Balancing is available during SLEEP mode. To enable balancing during SLEEP mode, configure the balancing timers and thresholds first and then execute cell balancing using the CONTROL2[BAL_GO] command. Finally, set the CONTROL1[GOTO_SLEEP] bit. To stop balancing while in SLEEP mode, a SLEEPtoACT or WAKE (wake tone for stack devices or hold WAKEUP pin low for base device for t_{HDL_WAKE}) must be sent to the device before disabling balancing. Note that if a WAKE is sent, it is unnecessary to disable balancing as the device is reset.

8.3.5.1.3 Cell Balance Sequencing

Once all of the parameters are set and the sequencing is selected, write the CONTROL2[BAL_GO] bit to 1 to start the cell balancing. When the BAL_GO bit is set, all of the configuration registers are sampled. Any changes to the configuration registers are ignored during the balancing cycle. A second BAL_GO must be performed to change any settings. Once enabled, balancing proceeds according to the flowchart in \boxtimes [19.](#page-38-0) The DEV STATICB RUNI bit is set for the entire cell balancing cycle, regardless if paused. It is cleared once the DEV_STATICB_DONE] bit is set.

During non-duty cycle operation CB_CONFIG[DUTY]=00, when an individual cell's balancing timer expires or the voltage falls to the programmed threshold, the balancing FET for that cell is disabled, the CB_DONE[CELL*] bit is set for that cell, and any cells with remaining time continue to balance. Once all of the selected bank of cells have completed balancing (either by timer expiration or voltage), the second bank (if selected) are balanced using the same procedure. Once all of the cells in that bank are balanced, the DEV_STAT[CB_DONE] bit is set, indicating that balancing is complete. The host is not required to monitor the balancing once the CONTROL2[BAL_GO] bit is set, allowing the host to enter a low power mode. Note that when cell balancing is disabled for a cell that is in a bank to be balanced (by setting the timer to 0), the corresponding

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CB_DONE[CELL*] bit is set immediately after the BAL_GO bit is set. When only balancing even or odd cells $(CB_CONFIG[SEQ] = 0b00$ or 0b01), only the bank that is balanced updates the CB_DONE[CELL*] bits. The CB_DONE[CELL*] bits for the non-balanced bank of cells are reset with the BAL_GO command, but are not modified during the balancing operation. For instance, after a completed cell balancing cycle where only the odd cells are balanced, the CB_DONE register reads (assuming no faults during the cell balancing) 0x15.

With duty cycle operation enabled (CB_CONFIG[DUTY] ≠00), the sequence follows the CB_CONFIG[SEQ] programming. The duty cycle timer runs in parallel with the cell timers. The odd or even cell balancing runs for the time programmed in CB_CONFIG[DUTY] and CB_CONFIG[DUTY_UNIT] and then switches to the other bank for the programmed time. The process continues switching back and forth until all of the cells are balanced. If all cells in a particular bank have completed, while some remain in the second bank, the device does not switch to the completed bank and, instead remains on the unfinished bank until all cells complete.

Cell balancing is paused using the CB_SW_EN[CB_PAUSE] bit. When set, the cell balancing state machine is frozen and all switches are turned off and the DEV_STAT[CB_PAUSE] bit is set. Cell balancing must be paused before doing diagnostics. If a fault occurs while cell balancing is in the pause state, nothing happens to the cell balancing logic, regardless of the state of the CB_CONFIG[FLTSTOP] bit. If the fault exists when the CB PAUSE bit is cleared, the cell balancing takes action at that point based on the state of the FLTSTOP bit.

> 注 The CB_CONFIG[DUTY_UNIT] and the CB_CELL1_CTRL[TIME_UNIT] unit must be the same. If minutes is selected for CB_CONFIG[DUTY_UNIT] minutes must be selected for CB_CELL1_CTRL[TIME_UNIT] as well.

図 **19. Flow Diagram for Cell Balancing**

8.3.5.1.4 Manual Cell Balance Switch Enable

The cell balancing switches may be enabled separately from the normal cell balancing cycle. Use the CB_SW_EN[CELL*_EN] bits to select the individual cell balancing switches. Do not select adjacent switches to be enabled simultaneously. Setting the CB_SW_EN[SW_EN] bit enables the selected switches. If adjacent switches are selected, none of the switches are enabled. As with the normal cell balancing cycle, the state of the cell balance switch is read using the CB_SW_STAT register. The manual cell balance switch function does not work if normal cell balancing is running. The normal cell balance cycle must either be stopped, done, or paused. If cell balancing is running, writing the CB_SW_EN[SW_EN] has no effect. Note that the settings are read and the selected switches enabled when SW_EN is written from '0' to '1'. Cell balancing must be paused or disabled and then SW_EN must be written to '0' and then rewritten to '1' to enable the function.

8.3.5.2 Cell Balance Diagnostics

The cell balancing circuits integrate features that enable the user to diagnose issues with CB and VC open-wire as well as cell balance switch damage. In addition to the normal cell balancing flow, the cell balance switches can be manually enabled. Additionally, there are integrated comparators to diagnose the switch damage.

8.3.5.2.1 Cell Balance Switch Comparators

There are two comparators integrated with each switch (CBVC and VCLOW). The comparators are enabled with the CBVC_COMP_CTRL[CELL*] bits. The first comparator tests the voltage across CBn to CBn-1 and compares it to (VCn to VCn-1)/3. If the CB voltage is greater than the VC/3 voltage, a flag (CBVC_COMP_STAT[CELL*]) is set. After the comparator is turned on, it takes up to 2.5ms to update the CBVC_COMP_STAT[CELL*] register status bits. Give 2.5ms delay time before reading the status register. The second comparator checks if the cell voltage (VCn - VCn-1) is above V_{VCLOW} . If the cell voltage is less than V_{VCLOW} , a flag (CBVC_VCLOW_STAT[CELL*]) is set. If the cell voltage is low, the result from CBVC_COM_STAT must not be trusted. Charge the cells further before retrying the test.

8.3.5.2.2 CB Current Sinks and Sources

The CB_CS_CTRL register allows the host to enable current sinks (CB1-CB6) or current source (CB0) to attempt to pull the pin up/down to diagnose a CB open-wire condition. There are no internal comparisons done on the pins, it is up to the host to diagnose an open-wire condition using the ADC. The current sources/sinks are limited to I_{OWSNK} and I_{OWSRC} , therefore special attention must be paid to the size of the external components and the time it takes to discharge any external capacitance.

8.3.6 Integrated Hardware Protector

The BQ79606A-Q1 integrates secondary hardware protections along with the ADC monitoring functions. A window comparator is integrated for each cell to check over-voltage and under-voltage. Additionally, a thermal shutdown function is included to disable operation under extreme thermal stresses.

8.3.6.1 Cell Voltage Window Comparators

A set of window comparators provides cell voltage monitoring for all six channels that is separate from the main acquisition path and works in parallel with the main ADC route. This comparator function is entirely separate from the ADC function and as such, even if the ADC function fails, the analog comparators still flag the crossing of the (register selectable) under-voltage and over-voltage comparator thresholds. The thresholds, and deglitch timing are programmable and are the same for all cells. Each cell has independent on/off control. An internal DAC sets the over-voltage and under-voltage thresholds. The DAC uses a separate reference circuit REF2 from the ADC reference REF1. The OV threshold is programmable to OFF or from 2V to 5V in steps of 25 mV using the OV_THRESH register. The UV threshold is programmable to OFF or from 0.7 V to 3.875 V in steps of 25 mV using the UV_THRESH register.

Use the OVUV CTRL[CELL^{*} EN] bits to enable the cells that are required for OV/UV monitoring. Use the CONTROL2[OVUV_EN] bit to enable the comparators. When enabled, all of the configuration bits are read. Further changes to the registers have no effect until the OVUV EN bit is cleared and set again.

Once enabled, the cells are monitored in a "round-robin" fashion, starting with CELL1 and cycling through to CELL6. The total time taken to do the round-robin cycle is t_{CYCLE} . The monitoring time for each CELL input is $t_{RR-SLOT}$. The LOOP_STAT[OVUV_LOOP_DONE] bit is updated at the end of each round-robin cycle (including the BIST, if enabled. See [CB_DONE,](#page-41-0) OVUV, and OTUT Built-In Self Test (BIST) for details). If already set, the bit remains as 1 until cleared by a read.

The deglitch time is programmed using the COMP_DG[OVUV_DG] bits. The deglitch is a count up/down style deglitch. During the monitoring cycle, the comparator checks the voltage. A counter is incremented when the comparator is tripped, and decremented when the comparator is not tripped. Once the counter reaches the programmed threshold, the OV_FAULT[CELL*] or UV_FAULT[CELL*] bit (depending on which comparator trips) is updated, and, if unmasked, the NFAULT output and/or the FAULT* interface signals the fault to the host. Note that due to the round-robin architecture, the total delay for an OV or UV event may be as high as $(t_{\text{CYCLE}}\text{-}$ t_{RR_SLOT} + 0.7ms.

図 **20. Window Comparator Circuit**

The OVUV function will not function if enabled during cell balancing as it uses the CB* inputs for sensing. Additionally, during the cell balancing cycle, with CBDONE enabled, the OVUV function is paused (if enabled). The UVOV comparators stop running during cell diagnostics.

8.3.6.2 Cell Over/Under-Temperature Comparators

A window comparator is integrated to monitor the GPIO1 to GPIO6 inputs for over-temperature and undertemperature conditions in the cells. When enabled, the comparator cycles through each of the temperature sense inputs and compares the voltage to thresholds programmed in the OTUT_THRESH register. This comparator function is entirely separated from the ADC function and as such, even if the ADC function fails, the analog comparators flag the crossing of the (register selectable) under-temperature and over-temperature comparator thresholds. The thresholds and deglitch timing are programmable and apply for all six inputs. Two internal DACs set the separate over-temperature and under-temperature thresholds. The OT threshold is programmable to OFF or from 20% to 35% of TSREF in steps of 1% using the OTUT_THRESH[OT_THRESH] bits. The UT threshold is programmable to OFF or from 60% to 75% of TSREF in steps of 1% using the OTUT THRESH[UT_THRESH] bits. TSREF must be enabled (CONTROL2[TSREF_EN]=1) for at least 2ms (for the recommended capacitor value, larger capacitors may lead to longer startup time) before enabling the OT/UT function. Failure to do so results in all of the OT_FAULT and UT_FAULT bits being set. Additionally, if a TSREF OV/UV fault happens at any time during OT/UT operation, all of the OT_FAULT and UT_FAULT bits are set.

Use the OTUT CTRL register to enable the GPIOs that are required for OT/UT monitoring. Use the CONTROL2[OTUT_EN] bit to enable the comparators. When enabled, all of the configuration bits are read. Further changes to the registers have no effect until the OTUT_EN bit is cleared and set again.

Once enabled, the comparators are monitored in a "round-robin" fashion, starting with GPIO1 and cycling through to GPIO6. The total time taken to do the round-robin cycle is t_{CYCLE} . The monitoring time for each GPIO input is t_{RR_SLOT}. The LOOP_STAT[OTUT_LOOP_DONE] bit is updated at the end of each round-robin cycle (including the BIST, if enabled. See [CB_DONE,](#page-41-0) OVUV, and OTUT Built-In Self Test (BIST) for details). If already set, the bit remains as 1 until cleared by a read.

The deglitch time for the OT and UT comparators is programmed using the COMP_DG[TEMP_DG] bits. The deglitch is a count up/down style deglitch. During the monitoring cycle, the comparator checks the voltage. A counter is incremented when the comparator is tripped, and decremented when the comparator is not tripped. Once the counter reaches the programmed threshold, the OT_FAULT[GPIO*] or UT_FAULT[GPIO*] bit (depending on which comparator trips) is updated, and, if unmasked, the NFAULT output (for base device) and/or the FAULT* interface (for the stack device) signals the fault. Note that due to the round-robin architecture, the total delay for an OT or UT event may be as high as: $(t_{CYCLE}$ -t_{RR} $_{SLOT}$)+ 0.1ms.

8.3.6.3 CB_DONE, OVUV, and OTUT Built-In Self Test (BIST)

The CBDONE, OVUV and OTUT comparators contain a BIST function for diagnostic purposes. When enabled, the BIST tests each of the individual comparators. The BIST is enabled for the OVUV comparators using the DIAG_CTRL1[OVUV_MODE] and DIAG_CTRL1[OTUT_MODE] bits. There are three options: Perform the roundrobin with BIST enabled, perform the round robin with BIST disabled, and single channel mode, where the comparators remain fixed on a selected input. When the BIST is enabled (DIAG_CTRL1[OVUV_MODE] = 0b00, DIAG_CTRL1[OTUT_MODE] = 0b00), the BIST is run on every other round robin cycle. This ensures that the BIST is run within two times t_{CYCIF} .

The comparator is tested by comparing a diagnostic DAC voltage (generated from REF2) to the selected threshold. The diagnostic DAC voltage is switched from 2 LSB below the threshold to 2 LSB above the threshold and the output of the comparator is checked to ensure it switches. If the comparator does not switch, the corresponding bit is set as follow:

- For OV comparator: OVUV_BIST_FAULT[OVCOMP]
- For UV comparator: OVUV_BIST_FAULT[UVCOMP]
- For OT comparator: OTUT_BIST_FAULT[OTCOMP]
- For UT comparator: OTUT_BIST_FAULT[UTCOMP].

The VCBDONE comparator BIST follows the same process and is enabled by the DIAG_CTRL1[OVUV_MODE] bits. If the BIST fails during the VCBDONE comparator BIST test, the SYS FAULT3[CB_VDONE] bit is set. All signals during BIST are deglitched by t_{BISTDG} .

8.3.6.4 Single Comparator Mode

When the OVUV or OTUT comparators are programmed to single channel mode (DIAG_CTRL1[OTUT_MODE] = 0b10 or 0b11, DIAG_CTRL1[OVUV_MODE] = 0b10 or 0b11), the comparators are on for the lowest selected channel. The channel is selected using OVUV_CTRL[CELL*_EN] bits for OVUV and OTUT_CTRL[GPIO*_EN] bits for OTUT bits. It continuously monitors that channel and does not perform the BIST function. Cell Balancing should not be enabled during OVUV single comparator mode and also make sure to set the DIAG CTRL1[OVUV_MODE] to 0b00 once the OVUV single mode is done.

8.3.6.4.1 OTUT DAC Measurmenent

This mode is intended for OTUT DAC reference (detection threshold level) measurement in the AUX ADC. The sequence listed below should be followed for proper measurements. If OTUT is transitioned to the enabled state after the AUX ADC input is enabled and OTUT is set to single mode, the OTUT logic masks the output from the comparators. This ensures the DAC outputs only the detection threshold level during the ADC measurement. Transitioning the OTUT enable bit from disabled to enabled latches the mode configuration signals, therefore it is required whenever a configuration change is requested.

- 1. Set ADC input enable (OT_DAC_EN=1 or/and UT_DAC_EN=1 in AUX_ADC_CTRL2)
- 2. Set OTUT in single channel (set OTUT MODE in DIAG CTRL1 to 0b10)
- 3. Set at least one of channel enable (GPIO1 EN=1 in OTUT CTRL for example)
- 4. Set OTUT disable (OTUT_EN =0 in CONTROL2) if it is already enabled
- 5. Set OTUT enable (OTUT_EN=1 in CONTROL2)
- 6. Enable TSREF (TSREF_EN=1 in CONTROL2)
- 7. wait for TSREF to settle
- 8. Start AUX ADC conversion (AUX_ADC_GO=1 in CONTROL2)
- 9. Wait for AUX ADC to finish
- 10. Re-configure OTUT as required.

8.3.6.4.2 OVUV DAC Measurment

This mode is intended for OVUV DAC reference (detection threshold level) measurement in AUX ADC. The sequence listed below should be followed for proper measurements. If OVUV is transitioned to the enabled state after the AUX ADC input is enabled and OVUV is set to single mode, the OVUV logic masks the output from the comparators. This ensures the DAC outputs only the detection threshold level during the ADC measurement. Transitioning the OVUV enable bit from disabled to enabled latches the mode configuration signals, therefore it is required whenever a configuration change is requested.

- 1. Set ADC input enable (OV_DAC_EN=1 or/and UV_DAC_EN=1 in AUX_ADC_CTRL2)
- 2. If the AUX_CELL is enabled make sure to set AUX_CELL__SEL_EN=0 and AUX_CELL_SEL[2:0]=00 on the DIAG_CTRL2 register
- 3. Set OVUV in single channel (set OVUV_MODE in DIAG_CTRL1 to 10)
- 4. Set at least one of channel enable (CELL1_EN=1 in OVUV_CTRL for example)
- 5. Set OVUV disable (OVUV EN =0 in CONTROL2) if it is already enabled
- 6. Set OVUV enable (OVUV_EN=1 in CONTROL2)
- 7. Start AUX ADC conversion (AUX_ADC_GO=1 in CONTROL2)
- 8. Wait for AUX ADC to finish
- 9. Re-configure OVUV as required

8.3.7 Thermal Shutdown and Warning

Thermal shutdown occurs when the Thermal Shutdown (TSD) sensor senses an over-temperature condition. The sensor operates without interaction and is separated from the ADC measured die sensor. The TSD function has a register-status indicator flag (SYS_FAULT1[TSD]) that is saved during the shutdown event and can be read after the WAKEUP procedure. When a TSD fault occurs, the part immediately enters the SHUTDOWN state. Any pending transactions on UART or daisy chain are discarded. There is no fault signaling done when a thermal

shutdown event occurs, as the device immediately shuts down. The BQ79606A-Q1 does not exit SHUTDOWN automatically. To awaken the part, follow the normal WAKEUP procedure and make sure the ambient temperature is below thermal T_{SDFALL} . Once the die temperature falls below T_{SDFALL} and the WAKEUP command is received, the BQ79606A-Q1 follows the normal startup procedure. Upon waking up, the SYS FAULT1[TSD] bit is set and, if unmasked, a FAULT Is indicated.

To warn the host of an impending thermal overload, the BQ79606A-Q1 includes an over-temperature warning that signals a fault when the die temperature approaches thermal shutdown. With every cell ADC conversion, the temperature read is compared against the thermal warning threshold (Twarn). A fault is signaled when the read die temperature is greater than the threshold. When an unmasked temperature warning fault occurs, the SYS_FAULT1[TWARN] bit is set. If unmasked, the NFAULT (base device) or FAULT* interface (stack device) signals the fault. The application must utilize the thermal warning and die temperature ADC measurements to avoid thermal shutdown events.

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- 1. The uC should always monitor the ambient temperature of the system.
- 2. The uC should take appropriate actions to reduce the thermal rise if SYS_FAULT1[TWARN] bit is set.
- 3. The uC should not wake the device if the ambient temperature is above T_{SDFALL} .

8.3.8 Oscillator Watchdogs

The oscillators used in the BQ79606A-Q1 are monitored by watchdog circuits. There are two oscillators in the device, the HFO and the LFO. If these oscillators are not functioning, the IC does not operate. If the HFO does not transition within t_{HFOWD} or the LFO does not transition within t_{LFOWD}, the watchdog circuits causes Digital Reset. It is recommended that the user sends a hardware shutdown command (using WAKEUP pin for a base device, or using the CONTROL1[SEND_SHUTDOWN] command for stack devices from the next lower device). Then the user must follow the WAKEUP procedure to restart the devices. If the oscillators are truly damaged, the device will not restart and must be replaced.

In addition to the watchdog, the LFO frequency is monitored to ensure it stays within acceptable limits. If the LFO frequency falls outside of the f_{LFO} $_{CHECK}$ specification, the SYS_FAULT3[LFO] bit is set.

8.3.9 Digital Reset

The BQ79606A-Q1 is in digital reset when one of the following conditions is satisfied:

- 1. When the DVDD is not valid and falls below V_{DRDVDD} threshold.
- 2. When V_{REF3} , used by V_{DRDVD} monitor, is not valid.
- 3. When Internal bandgap voltage, used by POR circuits is not valid.
- 4. When one of the oscillator watchdogs is tripped.
- 5. When CONTROL[SOFT_RESET]=1 command occurred.
- 6. For stack device, a wake up tone.
- 7. For base device, a WAKEUP pin hold low for $t_{HLD-WAKE}$ then released.

If the digital reset occurred due to DVDD, bandgap voltage, or VREF3, recovering from digital reset requires all of these voltages to go above the under voltage threshold listed above.

8.4 Device Functional Modes

8.4.1 Power Modes

The BQ79606A-Q1 always operates in one of four modes. The mode depends on the stack voltage and the operational requirements of the system. A high level description of the modes is as follows:

- 1. POR Pack voltage too low for functionality.
- 2. SHUTDOWN Extremely low power operation. Limited functionality.
- 3. SLEEP Low power operation. Some functionality available.

Device Functional Modes (continued)

4. ACTIVE - Full power operation. All functionality available.

 \boxtimes [21](#page-44-0) is a flow diagram of the transition between each of the modes. The modes are described in greater detail in the following sections.

図 **21. Power States Flow**

8.4.1.1 POR (Power On Reset)

The BQ79606A-Q1 is in POR when AVAO_REF voltage falls below $V_{AVAO_REF_UV}$. In POR, all of the circuits are shut down and held in RESET. When $\rm V_{AVAO_REF}$ rises above $\rm V_{UVLO_REF_UV+V_{UVLO_REF_UVHYS},$ the BQ79606A-Q1 transitions to SHUTDOWN mode. The SYS_FAULT1[DRST] bit is set and is not cleared upon startup to signal to the host that a reset has occurred.

8.4.1.2 SHUTDOWN Mode

In SHUTDOWN mode, most of the circuits in the BQ79606A-Q1 are disabled. The functionality is limited in this mode and the quiescent current is very low as a result. While in SHUTDOWN, the BQ79606A-Q1 remains idle and strictly monitors the WAKEUP input (for a stand-alone or base/bridge device) for a low pulse or the COMx inputs (for stack devices) for a WAKE tone (*Stack Device Wakeup and Hardware [Shutdown](#page-66-0)*). Once a WAKEUP signal or WAKE tone is received, the BQ79606A-Q1 transitions to ACTIVE mode. $\frac{1}{36}$ 6 specifies all of the circuits and functionality that are enabled or available in SHUTDOWN mode. $\frac{1}{32}$ [24](#page-66-1) specifies the mode transition for SHUTDOWN mode response to the different tones for stack devices. $\frac{1}{36}$ [23](#page-66-2) specifies the mode transition for SHUTDOWN mode response to the different signals for base devices. Additionally, the SYS_FAULT1[DRST] bit is set and is not cleared upon startup to signal to the host that a reset has occurred.

8.4.1.3 SLEEP Mode

In SLEEP mode, the BQ79606A-Q1 has limited functionality. The functions are limited to :

Device Functional Modes (continued)

- OV/UV and OT/UT Comparator
- Cell balancing
- **SHUTDOWN Detection**
- Fault Tone monitoring for the daisy chain interface (*[Daisy-Chain](#page-71-0) FAULT* Interface (Stack Devices)*)
- SLEEPtoACTIVE monitoring (signal on UART for base device or SLEEPtoACTIVE tone for stack device)
- WAKEUP (base device)/ WAKE tone (stack device) detection.
- **GPIO FAULT**
- NVM CRC

The comparators and Fault Tone monitoring must be enabled in ACTIVE mode before entering SLEEP mode. Once enabled, these functions remain active in SLEEP mode. If the functions are required to be disabled, the BQ79606A-Q1 must be commanded to ACTIVE mode to disable the functions.

While in SLEEP, the BQ79606A-Q1 monitors the WAKEUP input and the UART interface (for a stand-alone or base device) or the COMx inputs (for stack devices) for a WAKE or SLEEPtoACTIVE signal (*Stack [Device](#page-66-0) Wakeup and Hardware [Shutdown](#page-66-0)*). When a SLEEPtoACTIVE signal is received, either by UART interface or a SLEEPtoACTIVE tone on the daisy-chain, the BQ79606A-Q1 transitions to ACTIVE mode without resetting any internal settings. If a WAKEUP signal is received, either by the WAKEUP input or the WAKE tone on the daisychain, the BQ79606A-Q1 resets all of its settings to the system defaults and transitions to ACTIVE mode. $\frac{1}{36}$ 6 specifies all of the circuits and functionality that are enabled or available in SLEEP mode. $\frac{1}{32}$ [24](#page-66-1) specifies the mode transition for SLEEP mode response to the different tones for stack devices. $\frac{1}{32}$ specifies the mode transition for SLEEP mode response to the different signals for base devices.

8.4.1.4 ACTIVE Mode

As the name suggests, ACTIVE mode enables the full functionality of the BQ79606A-Q1. All of the LDOs and references are enabled and the BQ79606A-Q1 is ready to do ADC conversions, cell balancing, and full communication to all of the devices in the daisy chain. Before enabling any of these functions, the host must wait for the BQ79606A-Q1 to fully start up. It takes approximately t_{SU(WAKE)} for the BQ79606A-Q1 to transition to ACTIVE mode and have full functionality available. Following a SOFT_RESET, Digital Reset , or normal WAKEUP from SHUTDOWN, the host must clear the SYS_FAULT1[DRST] bit (using the SYS_FLT1_RST[DRST_RST] bit) to clear NFAULT and start the heartbeat (if enabled). ADVDD OSC fault may be also be triggered and must be cleared. $\frac{1}{36}$ 6 specifies all of the functionality that are enabled or available in ACTIVE mode.

The flow diagram (\boxtimes [21](#page-44-0)) indicates several different ACTIVE states. These are not actual states, but correspond to the possible actions done while in ACTIVE. These correspond with the specifications in the Electrical Characteristics table that are split into these items:

- 1. IACT(IDLE) specifies the current while in ACTIVE mode, but not doing any cell-balancing, ADC conversions, or communication. This is the baseline quiescent current in ACTIVE mode.
- 2. $I_{\text{ACT(BAL)}}$ specifies the additional quiescent current during cell balancing.
- 3. $I_{\text{ACT/CONVERT}}$ specifies the additional quiescent current during ADC conversions.
- 4. I_{ACT(COMC)} and I_{ACT(COMT)}specifies the additional quiescent current during ADC communication.

During ACTIVE mode, if a WAKEUP command (either WAKEUP toggle on base device or WAKE tone on stack device) is received, the BQ79606A-Q1 resets to the system default values and forwards it to the next device and sets the SYS_FAULT1[DRST] bit to signal to the host that a reset has occurred. If a SLEEPtoACTIVE command is received, the BQ79606A-Q1 forwards it up the stack and continues operating with no changes.

The BQ79606A-Q1 exits ACTIVE mode and enters SLEEP mode if the SLEEP command is set (CONTROL1[GOTO_SLEEP]). The BQ79606A-Q1 exits ACTIVE mode and enters SHUTDOWN mode if no valid communication frames are received for the time set in the register (COMM_TO[LONG]) if enabled. Additionally, the IC enters SHUTDOWN mode if a thermal shutdown event occurs, or if the SHUTDOWN command is set (CONTROL1IGOTO SHUTDOWNI). $\frac{1}{36}$ [24](#page-66-1) specifies the mode transition for ACTIVE mode response to the different tones for stack devices. $\frac{1}{3}$ [23](#page-66-2) specifies the mode transition for ACTIVE mode response to the different signals for base devices.

Device Functional Modes (continued)

8.5 Communication, Programming, GPIO, and Safety

8.5.1 Communication Interfaces and Programming

The BQ79606A-Q1 operates as a stand alone device or as a stack of up to 64 devices (1 base device and 63 stack devices) to monitor large stacks of Li-Ion cells. In a stack configuration, the single host, such as a microcontroller, communicates with a single "base" device to interface with the entire stack. The BQ79606A-Q1 integrates a daisy chain interface to allow all devices to communicate with the base device. The base device interfaces with the host through a UART communication interface and a fault signaling output (NFAULT). In stand-alone operation, the daisy-chain communication is disabled and the host communicates only with the single device.

8.5.1.1 UART Communication Physical Layer

The BQ79606A-Q1 utilizes a UART interface to enable communication with a single host to one or more BQ79606A-Q1 devices. The factory OTP reset baud rate is set to 1Mbps as in the COMM_CTRL register.

8.5.1.1.1 UART Interface

The UART interface follows the standard serial protocol of 8-N-1 (see \boxtimes [22\)](#page-47-0), where it sends information as a START bit, followed by eight data bits, and then one STOP bit. The STOP bit indicates the end of the byte. If a byte is received that does not have the STOP bit set, the COMM_UART_FAULT[STOP] bit is set, indicating there may be a baud rate issue between the host and the device. In all, 10 bits comprise a character time. Received data bits are over-sampled by 16 times to improve communication reliability.

The UART sends data on the TX pin and receives data on the RX pin. When idle, the TX and RX are high. The UART interface requires that RX are pulled-up to VIO through a 10KΩ to 100-KΩ resistor. Do not leave RX unconnected. Ensure RX is connected directly to VIO for stack devices. The TX must be pulled high on the hostside on base/bridge devices to prevent triggering an invalid communications frame when the communication cable is not attached, or during power-off or the shutdown state when TX is high impedance. TX is always pulled to VIO internally while in ACTIVE or SLEEP mode, whether enabled or disabled. Leave TX unconnected if not used in stack devices. When using a serial cable to connect to the host controller, connect the TX pullup on the host side and the RX pullup on the BQ79606A-Q1 side.

The UART interface is strictly a half-duplex interface. While transmitting, any attempted communication on RX is ignored. The only exceptions are COMM CLEAR and COMM RESET. Receiving one of these commands immediately terminates the communication and performs the required action. See [Communication](#page-48-0) Clear (Break) [Detection](#page-48-0) and [Communication](#page-49-0) Reset Detection for more details.

8.5.1.1.1.1 UART Transmitter

The transmitter is configurable to wait a specified number of bit periods after the last bit reception before starting transmission using the TX_HOLD_OFF register. This provides time for the host to switch the bus direction at the end of its transmission. The TX hold off time for base and stack can be calculated as below:

- 1. Generic formulas to calculate the actual TX hold (bit period) of time for STACK devices:
	- 1. Minimum=TX_HOLD_OFF x Bit Period
	- 2. Typical= 22.5+7x(Number of Devices-2)+(TX_HOLD_OFF+1.5) x Bit Period
	- 3. Maximum= 24.5+9x(Number of Devices-2)+(TX_HOLD_OFF+4.5) x Bit Period

Communication, Programming, GPIO, and Safety (continued)

- 2. Generic formulas to calculate the actual TX hold (bit period) of time for BASE devices:
	- 1. Minimum=TX_HOLD_OFF x Bit Period
	- 2. Typical= 1.5+(TX_HOLD_OFF+1.5) x Bit Period
	- 3. Maximum= 2.5+(TX_HOLD_OFF+2.5) x Bit Period

Note that the total number of devices includes all stack devices and the base. Also note that the Bit Period depends on the baud rate.

When the device receives a communications reset, the baud rate for the UART is reset to 250kbps. The baud rate is programmable by the host to a higher or lower rate by writing to COMM_CTRL[BAUD]. The UART TX is disabled/enabled using the COMM_CTRL[UARTTX_EN]. Once disabled, no responses are transmitted. The transmitter is disabled immediately following the disable command.

8.5.1.1.1.2 UART Receiver

The UART interface design works in half-duplex. While the device is transmitting data on TX, RX is ignored except when receiving a Communication Clear or Communication Reset. To avoid collisions during data transmission up the daisy-chain interface, the host microcontroller must wait until all bytes of a transmission are received from the device before attempting additional communication. If the microcontroller starts a transaction without waiting to receive the preceding transaction's response, the communication is not considered reliable and the microcontroller must send a Communication Clear (see Communication Clear (Break) Detection) or Communication Reset (see Communication Reset Detection) to restore normal communications to the base device. Breaks and communication resets are not sent to the stack devices. A Communication Clear or Communication Reset can be sent at any time. RX cannot be disabled, and is active even when the transmitter (TX) is disabled (COMM_CTRL[TX_EN] = 0).

8.5.1.1.1.3 UART Baud Rate Selection

The baud rate of the communications channel to the host is selectable between 125k-250k-500k-1Mbps baud rates. The default rate after a communications reset is 250kMbps. The default rate after a Digital Reset is the rate selected by the value stored in OTP for the COMM_CTRL[BAUD] bits. When a new baud rate is selected, the new rate takes effect after the complete reception of a valid frame containing the new setting including the CRC. The next frame is sent at the new baud rate and all further frames are transmitted at the new rate. It is possible to change the baud rate at any time. After changing the baud rate, wait a minimum of 10μs before sending the first frame at the new baud rate. The value in the COMM_CTRL[BAUD] affects the baud rate used in microcontroller communications on the TX and RX pins and the response baud rate of the daisy chain. The current baud rate setting for the device is read in the COMM_STAT[BAUD_STAT] bits. This reflects the actual baud rate used whether it be set by COMM_CTRL[BAUD] or to hardware default (after communications reset).

表 **7. UART BAUD COMM_CTRL[BAUD] Setting**

8.5.1.1.1.4 Communication Clear (Break) Detection

Use the Communication Clear command to clear the receiver and instruct it to look for a new start of frame. The next byte following the Break is considered a "start of frame" byte. The receiver continuously monitors the RX line for break condition. A communication clear is detected when the RX line is held low for a least a min value of $t_{UART(BRK)}$ bit periods. Ensure that the break does not exceed the max value of $t_{UART(BRK)}$ bit periods, as this may result in recognition of a SLEEPtoACTIVE and/or communication reset (if RX held low long enough to satisfy t_{UART(RST)}. When detected, a communication clear sets the COMM_UART_FAULT[COMMCLR_DET] flag. The host must wait at least $t_{UART(RXMIN)}$ after the communication clear to start sending the frame. It should be noted that in addition to the COMM_UART_FAULT[COMMCLR_DET] flag, the COMM_UART_FAULT[STOP] flag is also set because the communication clear timing violates the typical byte timing and the STOP bit is seen as '0'.

While using the daisy-chain configuration (CONFIG[MULTIDROP_EN] = 0), if a communication clear is received (Base or Bridge) while waiting to respond to a read command, the device response is discarded and the COMM_UART_TR_FAULT[WAIT] or COMM_UART_TR_FAULT[SOF] bit is set (depending on the timing of receiving the communication clear). The stack devices do NOT see the communication clear and continue to send their responses which are forwarded to the host. In the stack configuration, the host should avoid this condition by waiting until all responses are received from the stack before sending a communication clear. Failure to do so results in the host receiving unexpected response frames.

When using the multi-drop configuration (CONFIG[MULTIDROP EN] = 1), a communication clear must be used before every frame to ensure consistent communication. If a communication clear is received during a response, or while waiting to respond, the responses are immediately discarded (if waiting to transmit) or stopped (if currently transmitting) and the COMM_UART_TR_FAULT[WAIT] bit is set.

Note that for a device in sleep mode, sleep to active causes only communication clear detect COMM_UART_FAULT[COMMCLR_DET], but no COMM_UART_FAULT[STOP]. For a device in active mode, sleep to active causes both communication clear detect and STOP

8.5.1.1.1.5 Communication Reset Detection

A Communication Reset command is sent by holding the RX line low of the base device for $t_{UART(RST)}$. The primary purpose of sending a communications reset is to recover the device in the event the baud rate is inadvertently changed or unknown. The baud rate of the base device resets to 250Kbps regardless of the value stored in the COMM_CTRL[BAUD] register. This sets the baud rate to a known, fixed rate (250Kbps), and the COMM_UART_FAULT[COMMRST_DET] bit is set. The baud rate register COMM_CTRL[BAUD] will not be affected by communication reset. This communication reset does not affect the stack devices (only the base will reset to 250Kbps). Writing to stack devices with an 1Mbps or 500Kbps baud rate should not be an issue. Therefore even if a stack device is set to 1Mbps baud, and base is reset to 250Kbps baud, the host can write to a stack device using 250Kbps. Only for read from stack the baud rate of stack device matters and then it must meet the baud of base and host. Therefore in this case, the host can still do a broadcast write at 250Kbps to set entire stack and base whatever new baud it wants them to be at.

Holding the RX line of the base device low for more than $t_{\text{UART(RST)}}$ will also cause the base to send Sleep to active tones and Communications clear (break). The sleep to active and communication clear are inclusive in the communication reset.

In a case a communication reset is received while waiting to respond to a broadcast read or stack read command, the device response is discarded and the COMM_UART_TR_FAULT[WAIT] bit is set. The stack devices do NOT see the reset and continue to send their responses which are forwarded to the host. In the stack configuration, the host should avoid this condition by waiting until all responses are received from the stack before sending a reset. Failure to do so results in the host receiving unexpected response frames. Note that performing a reset in the middle of receiving responses may result in buffer overflow errors if the baud rate for the base device is reset to a lower rate that the stack devices. It should be noted that in addition to the COMM_UART_FAULT[COMMRST_DET] flag, the COMM_UART_FAULT[STOP] flag is also set because the reset timing violates the typical byte timing and the STOP bit is seen as '0'.

8.5.1.2 Command and Response Protocol Layer

The host initiates every transaction between the host and the BQ79606A-Q1. The BQ79606A-Q1 never transmits data without first receiving a command frame from the host. After a command frame is transmitted, the initiator must wait for all expected responses to be returned (or a timeout in case of error) before initiating a new command frame. There are multiple types of commands:

- 1. Single Device Read This command is used to read a register(s) from a single device in the stack or base/bridge devices.
- 2. Single Device Write This command is used to write a register(s) to a single device in the stack or base/bridge devices.
- 3. Stack Read This command is used to read a register(s) from the stack devices only. The CONFIG[STACK_DEV] bit is used to configure a device as a stack device. The IC must be configured as a stack device (CONFIG[STACK_DEV] = 1) to respond to Stack Read commands.
- 4. Stack Write This command is used to write a register(s) for only the stack devices. The CONFIG[STACK_DEV] bit is used to configure a device as a stack device. The IC must be configured as a stack device (CONFIG[STACK_DEV] = 1) to respond to Stack Write commands.

- 5. Broadcast Read This command is used to read a register(s) for all of the devices in the stack (including base and bridge devices).
- 6. Broadcast Write This command is used to write a register(s) for all of the devices in the stack (including base and bridge devices).
- 7. Broadcast Write Reverse Direction This command is used to send a broadcast write in the reverse direction from the direction selected using the CONTROL1[DIR_SEL] bit. This command is intended to be used for switching the communication direction for the stack interface.

 x enerated | Slave generated

Command Frame

(B) Single Device Read

図 **23. Example Command and Response Frames**

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A response frame is not mandatary as part of the protocol. A response frame is only received from a read command frame.

8.5.1.2.1 Transaction Frame Description

The protocol layer is made up of transaction frames. There are two basic types of transaction frames; Command Frames (transactions from Host) and Response Frames (transactions from Slave). The transaction frames are made up of the following five field types:

- Frame Initialization
- Device Address ID
- Register Address
- Data
- Cyclic Redundancy Check (CRC).

The following sections detail the field types.

8.5.1.2.1.1 Frame Initialization Byte

The Frame Initialization Byte is used in both Command and Response Frames. It is always the first byte of the frame. The Frame Initialization Bytes performs two functions. First, it defines the frame as either a Command Frame (host) or a Response Frame (slave). Second, it defines the length of the frame that follows after the Frame Initialization Byte. This provides the receiver an exact number of bytes to expect for a complete command/response. If the transmission does not complete the correct number of bytes before the timeout occurs, an communication time out is generated if enabled. The Frame Initialization Byte for both the Command and Response frame is defined in $\frac{1}{\sqrt{6}}$ 8.

表 **8. Command Frame Initialization Byte Definition**

表 **9. Response Frame Initialization Byte Definition**

8.5.1.2.1.2 Device Address Byte

The Device Address Byte identifies the device targeted by the command. This byte is omitted for Broadcast, Stack, and Broadcast Reverse Direction command frames. The devices that contain a matching value in their Device Address Status register (DEV_ADD_STAT[ADD]) may respond to the command and cause collision.

8.5.1.2.1.3 Register Address Bytes

Register addresses are two bytes in length. Any write command done to an invalid register address is ignored. Any read from an invalid register returns a 0x00 response. This is true for command frames sent to an individual register with invalid address, or as part of command sent to multiple registers with invalid addresses. When read/write addresses a block of registers with only some invalid addresses, the valid addresses respond as normal, while the invalid addresses respond as previously described.

8.5.1.2.1.4 Data Byte(s)

The number of data bytes and the relevant information they convey is determined by the data size of command frame sent and the target register specified in that command frame. When part of a Command Frame, the data bytes contain the values to be written to the registers. When part of a Response Frame, the data bytes contain the values returned from the registers.

Bit	Name	Description
$\overline{7}$	Data Byte [0]	0b00000000 - 0b11111111: Data Byte
6		
5		
4		
3		
2		
1		
0		
\sim	\cdots	\cdots
7		
6		
5		
4	Data Byte [n]	0b00000000 - 0b11111111: Data Byte
3		
2		
1		
0		

表 **12. Data Byte(s) Definition**

Read command frames (single device read, stack read, and broadcast read) always contain a single data byte that indicates how many registers to read from the starting address. The BQ79606A-Q1 support up to 128 byte reads. The valid data byte for read command frame is 0b0000000 - 0b1111111. The MSB of the data byte is ignored for read command frames. For example, 0b10011001 is read as 0b0011001 and returns data from 26 registers.

8.5.1.2.1.5 CRC Bytes

The BQ79606A-Q1 uses a CRC (cyclic redundancy check) to protect data integrity during transmission. The CRC represents the remainder of a process analogous to polynomial long division, where the frame being checked is "divided" by the generator. The CRC appended to the frame is the "remainder". Because of this process, when the device receives a frame, the CRC calculated by the receiver across the entire frame including the transmitted CRC will be zero, indicating a correct transmission and reception. A non-zero result indicates a communication error. Specifically, the BQ79606A-Q1 uses the CRC-16-IBM polynomial (x^{16} + x^{15} + x^2 + 1) with 0xFFFF initialization.

The CRC value is checked as the first step after receiving the communication frame. If the CRC is incorrect, the entire frame is discarded and not processed. Any additional frame errors are not checked and any errors are not indicated other than CRC error. The bytes are still transferred up/down the stack, thus every device that processed the frame will indicate a CRC error. This results in multiple devices indicating CRC faults on the same communication frame.

8.5.1.2.1.5.1 Calculating Frame CRC Value

The CRC calculation by the transmitter is in bit-stream order across the entire transmission frame (except for the CRC). When determining bit-stream order for implementing the CRC algorithm, it is important to note that protocol bytes transmit serially, least-significant bit first. \boxtimes [24](#page-53-0) illustrates the bit-stream order concept.

The CRC (0x0000) is appended to the end of the bit-stream. This bit-stream is then initialized by XOR'ing with 0xFFFF to catch any leading 0 errors. This new bit-stream is then divided by the polynomial (0xC002) until only the 2 byte CRC remains. During this process, the most significant 17-bits of the bit stream are XOR'd with the polynomial. The leading zero's of the result are removed and that result XOR'd with the polynomial once again. The process is repeated until only the 2 byte CRC remains. For example:

Command Frame = 0x80 00 02 0F 0B (0b1000 0000 0000 0000 0000 0010 0000 1111 0000 1011) Command Frame in bit stream order = 0x01 00 40 F0 D0 (0b0000 0001 0000 0000 0100 0000 1111 0000 1101 0000)

After Initialization (XOR with 0xFFFF) = 0b1111 1110 1111 1111 0100 0000 1111 0000 1101 0000

1111 1110 1111 1111 0100 0000 1111 0000 1101 0000 0000 0000 0000 0000 #append 0x0000 for CRC 1100 0000 0000 0010 1 #XOR with polynomial 0011 1110 1111 1101 1100 0000 1111 0000 1101 0000 0000 0000 0000 0000

11 1110 1111 1101 1100 0000 1111 0000 1101 0000 0000 0000 0000 0000 #delete leading zeros from previous result 11 0000 0000 0000 101 #XOR with polynomial 00 1110 1111 1101 0110 0000 1111 0000 1101 0000

1100 0110 0000 0001 0000 0000 1100 0000 0000 0010 1 #XOR with polynomial 0000 0110 0000 0011 1000 0000

110 0000 0011 1000 0000 110 0000 0000 0001 01 #XOR with polynomial 000 0000 0011 1001 0100

0000 0011 1001 0100 #CRC result in bit stream order 1100 0000 0010 1001 #final CRC result in normal order

CRC final 0xC029

図 **25. Example 1. CRC Calculation Using Polynomial Division**

8.5.1.2.1.5.2 Verifying Frame CRC

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There are several methods for checking the CRC of a frame. One method is to simply calculate the CRC for the transmitted command except the last two bytes (CRC bytes) using the method described in the previous section, and then compare that result with the transmitted CRC bytes. A more simple option is to run the entire transmission through the CRC algorithm. If the CRC is correct, the result is '0000'. In this case, the initial zero padding of the bit-stream with sixteen zeroes is not necessary. Using the previous result and running through the algorithm produces the following results:

Command Frame = 0x80 00 02 0F 0B (0b1000 0000 0000 0000 0000 0010 0000 1111 0000 1011) CRC to Check = 0xC029 Command Frame w/ CRC in bit stream order = 0x80 00 02 0F 0B C0 29 (0b1000 0000 0000 0000 0000 0010 0000 1111 0000 1011 0000 0011 1001 0100)

After Initialization (XOR with 0xFFFF) = 0b0 1111 1110 1111 1111 0100 0000 1111 0000 1101 0000 0000 0011 1001 0100

1111 1110 1111 1111 0100 0000 1111 0000 1101 0000 0000 0011 1001 010 #delete leading zeros from previous result 1100 0000 0000 0010 1 #XOR with polynomial 0011 1110 1111 1101 1100 0000 1111 0000 1101 0000 0000 0011 1001 0100

11 1110 1111 1101 1100 0000 1111 0000 1101 0000 0000 0011 1001 0100 #delete leading zeros from previous result 11 0000 0000 0000 101 #XOR with polynomial 00 1110 1111 1101 0110 0000 1111 0000 1101 0000 0000 0011 1001 0100 \cdots \cdots 1100 0110 0000 0010 1001 0100 1100 0000 0000 0010 1 #XOR with polynomial 0000 0110 0000 0000 0001 0100

1 1000 0000 0000 0101 00 1 1000 0000 0000 0101 #XOR with polynomial 0 0000 0000 0000 0000 00

0x0000 #verifies that CRC checks out valid

図 **26. CRC Verification Using Polynomial Division**

Note the result of '0b0000 0000 0000 0000' for the CRC, indicating a successful check.

8.5.1.2.1.5.3 Communication CRC Diagnostics

To test the CRC check for the communication path is functionally, the CRC in response packets can be purposely set incorrectly. Use the DIAG_CTRL1[FLIP_TR_CRC] bit to invert all bits of the CRC for response frames.

8.5.1.2.2 Transaction Frame Examples

Transaction frames are created using the frames discussed in the previous sections. The following sections outline all of the ways transaction frames are created using the individual frames. The CRC values in the examples are correct and are used to verify the customer CRC algorithm. The CRC is verified by the device with every received command frame and the command is not executed unless the CRC is valid. Command Frames fall into two general categories:

- 1. Write command frames that do not generate any response frames
- 2. Read command frames that generate at least one response frame.

The REQ_TYPE field in the Frame Initialization byte determines the category to which a command frame belongs. Category 1 contains the Single Device Write, Stack Write, Broadcast Reverse direction, and Broadcast Write request types. Category 2 contains the Single Device Read, Stack Write Read, and Broadcast Read. The number of response frames generated by the Category 2 command frames depends on the number of devices addressed by the command frame. In the case where more than one response frame is received in response to a single command frame, each response frame is a complete frame containing the Frame Initialization, Device address, Register address, Data, and CRC bytes. A single device does not respond with more than a single response frame in response to any single command frame. \boxtimes [27](#page-56-0) illustrates all of the different command and response frames.

(G) Broadcast Write Reverse Direction

図 **27. Transaction Frame Structures**

8.5.1.2.2.1 Single Device Read Command Frame

A read command for a single device generates a response frame whose length depends on the requested number of register bytes read. For example, the cell voltage registers are grouped such that all of the cell voltages can be read with a single command frame. The single device read command frame must contain the register address to start at (address field) and the number of bytes to return (number of registers to read). The DATA SIZE field in the initialization byte for the single device read command is always be 0b000 as the maximum number of readable bytes is 128 (1 byte worth of addresses). The command frame for a burst read of all of the cell voltages is configured as in $\frac{1}{3}$ [13.](#page-57-0)

表 **13. Single Device Read Command Frame**

8.5.1.2.2.2 Single Device Write Command Frame

A write command for a single device enables the customer to update up to 8 consecutive registers with one command. Some register writes, OTP_PROG_UNLOCK1* and OTP_PROG_UNLOCK2* for example, require that multiple registers be written with one command. The single device write command frame must contain the register address to start at (address field) and the data bytes to write to the registers. The DATA_SIZE field in the initialization byte for the single device write command is the number of registers to update. The command frame for a single device write to the OTP_PROG_UNLOCK1^{*} registers is configured as in $\frac{1}{\sqrt{6}}$ [14](#page-57-1) Initialization byte is 0x90 for 1 byte data read, 0x91 for 2 bytes data read, 0x92 for 3 bytes data read and so on.

表 **14. Single Device Write Command Frame**

8.5.1.2.2.3 Stack Read Command Frame

A read command for the stack devices (it does not include the base or bridge device) generates a number of response frames depending on the number of devices in the stack, whose length depends on the requested number of register bytes read. For example, using the same cell voltage register example as above, but now addressing a stack of 3 devices, the response to this command is 3 separate response frames, each with a length of 18 bytes (12 data bytes + 6 protocol bytes). The stack device read command frame must contain the register address to start at (address field) and the number of bytes to return (number of registers to read). The DATA SIZE field in the initialization byte for the read command is always 0b000 as the maximum number of readable bytes is 128 (1 byte worth of addresses). The command frame for a burst read of all of the cell voltages is configured as in $\frac{1}{\sqrt{2}}$ [15](#page-58-0).

During the response, each device (address N) in the stack waits until the device above (address N+1) it responds before appending its message to the full response frame. The CRC is validated while receiving the responses. If a CRC error occurs in the response frame from address N+1, device N does NOT append its message and an invalid CRC fault is generated.

A stack read/ is the same as the broadcast read except that it applies only for stack devices (excludes the base and the bridge).

表 **15. Stack Read Command Frame**

8.5.1.2.2.4 Stack Write Command Frame

A write command for a stack devices (it does not include the base or bridge device) enables the customer to update up to 8 consecutive registers for an entire stack of devices with one command. As in the previous example, some register writes, OTP_PROG_UNLOCK1* and OTP_PROG_UNLOCK2* for example, require that multiple registers be written with one command. The stack write command frame must contain the register address to start at (address field) and the data bytes to write to the registers. The DATA_SIZE field in the initialization frame for the single device write command is the number of registers to update. The command frame for a stack write to the OTP_PROG_UNLOCK1* registers is configured as in $\frac{1}{36}$ [16.](#page-58-1)

A stack write is the same as the broadcast write except that it applies only for stack devices (excludes the base and the bridge).

表 **16. Stack Write Command Frame**

8.5.1.2.2.5 Broadcast Read Command Frame

A broadcast read command generates a number of response frames depending on the number of devices in the stack (plus the base and the bridge), whose length depends on the requested number of register bytes read. For example, using the same cell voltage register example as above, but now broadcasting to 20 devices, the response to this command is 20 separate response frames, each with a length of 18 bytes (12 data bytes + 6 protocol bytes). The broadcast read command frame must contain the register address to start at (address field) and the number of bytes to return (number of registers to read). The DATA_SIZE field in the initialization frame for the broadcast read command is always 0b000 as the maximum number of readable bytes is 128 (1 byte worth of addresses). The command frame for a burst read of all of the cell voltages is configured as in $\frac{1}{5}$ [17](#page-58-2).

During the response, each device (address N) in the stack waits until the device above (address N+1) it responds before appending its message to the full response frame. The CRC is validated while receiving the responses. If a CRC error occurs in the response frame from address N+1, device N does NOT append its message and an invalid CRC fault is generated.

表 **17. Broadcast Read Command Frame**

Data 0x0B Oxor Send 12bytes worth of data back (register contents

CRC 20xD2B3

from 0x215 to 0x220)

8.5.1.2.2.6 Broadcast Write Command Frame

A broadcast write command enables the customer to update up to 8 consecutive registers for an entire stack of devices (including the base and the bridge devices) with one command. As in the previous example, some register writes, OTP_PROG_UNLOCK1* and OTP_PROG_UNLOCK2* for example, require that multiple registers be written with one command. The broadcast write command frame must contain the register address to start at (address field) and the data bytes to write to the registers. The DATA_SIZE field in the initialization frame for the single device write command is the number of registers to update. The command frame for a broadcast write to the OTP_PROG_UNLOCK1^{*} registers is configured as in $\frac{1}{\sqrt{6}}$ [18](#page-59-0)

表 **18. Broadcast Write Command Frame**

8.5.1.2.2.7 Broadcast Write Reverse Direction

A broadcast write reverse direction command enables the customer to switch the daisy chain communication direction for stack devices. The broadcast write reverse direction command is always the same as it is only used with the CONTROL1[DIR_SEL] bit. The command frame for a broadcast write reverse direction is configured as in 表 [19.](#page-59-1)

表 **19. Broadcast Write Reverse Direction Command Frame**

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The broadcast write reverse direction allows any write command to be sent in the reverse direction. It is not recommended to send any command other than the CONTROL1[DIR_SEL] to avoid communication collisions. Communication collisions are not detected and result in corrupted communication on the stack interface.

8.5.1.2.2.8 Response Frame

Response frames are generated in response to read command frames. For multiple device command frames, stack reads and broadcast reads, the response is broken into individual response frames from each device addressed. The size of each response frame is limited to 128 bytes, but must be at least 1. The example in $\frac{1}{32}$ [20](#page-59-2) shows a response to a read command from device at address 5 for all cell voltages (as in the previous read examples).

表 **20. Response Command Frame**

表 **20. Response Command Frame (continued)**

8.5.1.3 Daisy Chain Communication

The daisy chain communication is created using differential signaling to minimize Electro-Magnetic Susceptibility (EMS) and Bulk Current Injection (BCI) immunity. The differential communication transmits true and complement data on the COM*P and COM*N pins respectively. In a multiple device stack, there are configurations where the BQ79606A-Q1 are physically located on the same board or located in entirely separate packs connected with twisted-pair wiring.

The BQ79606A-Q1 supports the use of transformers or capacitors to electrically isolate the signals between devices in the stack. For applications that have multiple devices on the same PCB, a single level-shifting capacitor is connected between the COM* pins of the devices. For extremely noisy environments, additional filtering may be necessary. For devices that are separated by cabling, additional isolation components must be used. See *[Daisy-Chain](#page-236-0) Differential Bus* for specific details on selecting components. The individual transmitters and receivers are enabled/disabled using the DAISY_CHAIN_CTRL register.

8.5.1.3.1 Daisy Chain Transmitter and Receiver Functionality

The daisy chain is bi-directional and half duplex, and therefore, has a transmitter (TX) and receiver (RX) on both interfaces (COMH and COML). The TX and RX functions are controlled automatically by the hardware (under certain conditions, typically during startup and reset) and by the user (under other conditions). The DAISY CHAIN CTRL register provides user controls for the individual interfaces. The hardware control is determined by the startup conditions: if WAKEUP is high after startup, the COML TX and COML RX are disabled and upon wakeup from a hardware shutdown (only using the WAKEUP input), the COMH and COML receivers and the COML transmitter are disabled. More information on these conditions is outlined in the Base [Device](#page-65-0)
Wakeup and Hardware Shutdown section. Once startup has completed, use the Wakeup and Hardware [Shutdown](#page-65-0) section. Once startup has completed, use the CONTROL2[DAISY_CHAIN_CTRL_EN] bit to select the user configurable settings in the DAISY_CHAIN_CTRL register. The DAISY_CHAIN_STAT register shows the current enable/disable status for both COMH and COML interfaces as well as the status of the control for the interfaces (Hardware vs. User). Note that after enabling COM RX, wait for at least 100usec before start communication.

表 **21. COM RX Data and Tone Status**

表 **22. COM TX Data and Tone Status**

- 1. The Tone includes Wake tone, SLEEPtoActive tone, and Shutdown tone.
- 2. After startup or reset and the WAKEUP pin is High, the COMH RX data and tone are controlled by DAISY_CHAIN_CTRL[COMHRX_EN] bit. However, if the device wakeup from a hardware shutdown only using the WAKEUP input, the COMH RX data and tone are disabled. Once the wake up is completed, the user can control the COMH RX through DAISY_CHAIN_CTRL[COMHRX_EN] bit and by setting CONTROL2[DAISY_CHAIN_CTRL_EN]=1.
- 3. After startup or reset and the WAKEUP pin is High, the COML RX data and tone are disabled. Once the startup and reset is completed, the user can control the COML RX through DAISY_CHAIN_CTRL[COMLRX_EN] bit and by setting CONTROL2[DAISY_CHAIN_CTRL_EN]=1.
- 4. After startup or reset and the WAKEUP pin is High, the COML TX data and tone are disabled. Once the startup and reset is completed, the user can control the COML TX through DAISY_CHAIN_CTRL[COMLTX_EN] bit and by setting CONTROL2[DAISY_CHAIN_CTRL_EN]=1.

8.5.1.3.2 Daisy Chain Protocol Description

The differential stack interface uses an asynchronous 12-bit byte-transfer protocol that operates at baud_{DC}. Data is transferred LSB first and every bit is duplicated (with a complement) to ensure the transmission has no DC content. The receiver samples the signal 8 times per half bit time. A zero is transmitted as one half-bit period low followed by one half-bit period high, while transmission of a one is a half-bit period high followed by a half-bit period low. See 図 [28](#page-62-0)A for a graphical representation of the bit definitions. Two synchronization bits are used to extract timing information. If the timing information extracted from the demodulation of the preamble half-bit and the two full bits of synchronization is outside of the expected window, the COMM_COM*_FAULT[SYNC2] bit is set and the byte is not processed. If the demodulation of the preamble half-bit and the two full bits of synchronization data have errors and the timing is likely not correct, the COMM_COM*_FAULT[SYNC1] bit is set and the byte is not processed.

A byte contains two SYNC bits, a start-of-frame bit, eight data bits starting from the LSB "D0" to MSB "D7" (D0 is transmitted just after State-Of-Frame and D7 comes last before the Byte Error and Postamble) , and byte error bit as shown in the figure below. Additionally, a preamble and postamble are always used to ensure DC balance for transformer applications. The SYNC bits are always two zeros. See \boxtimes [28B](#page-62-0) for a graphical representation of the protocol. Once two valid SYNC bits are received, the additional bits are decoded and sent to the command processor. If, during the demodulation of the bus traffic, a bit is decoded that is not a "strong" '1' or '0' (meaning there were not sufficient samples to indicate the logic level with certainty), the COMM_COM*_FAULT[BIT] bit is set and the byte is not decoded. If, during the demodulation of the bus traffic, one or more of the received data bits does not have the expected complement bit structure, the COMM_COM*_FAULT[DATA_ORDER] bit is set and the byte is not decoded. If, during the communication, there is a failure to detect a valid '1' or '0' on the bus when one is expected (every bit time), the COMM COM* FAULT[DATA_MISS] bit is set and the byte is not decoded.

Each byte is transmitted at 2MHz (250ns per pulse or 500ns per couplet). The throughput is determined by the baud rate set by the COMM_CTRL[BAUD] bits. The time between each byte depends on this setting, but the byte time is always the same. See $\overline{\otimes}$ [29.](#page-62-1)

The daisy chain retransmits the data on a bit level to improve daisy-chain robustness. If an error is detected in the received data (any error indicated in the COMM_COM*_FAULT register), the data is still forwarded, but the byte error bit is set to indicate to the devices up the stack that the data is likely corrupted and must be ignored. The COMM_COM*_FAULT[BERR] bit is set and the byte is ignored whenever a byte is received with the byte error set. The ignored byte likely also causes other errors as well depending on where in the frame it occurs.

The start-of-frame bit defines the byte as the first in the frame (the frame initialization byte). The first frame bit is analogous to receiving a communication clear (break) from the UART interface. Receiving a frame start bit in the middle of a frame causes the frame to be discarded, and a new frame started. The unexpected SOF flag (COMM_COM*_*_FAULT[SOF]) is set. For situations where sync in the datastream is lost, the start frame bit enables re-syncing the datastream. The frame start bit is set whenever a communication clear is signaled on the UART interface (also it is set based on the framing event .

Data is forwarded up/down the stack and to the host (from the base device) even if the byte is tagged with a byte error. Each device recognizes the byte error and sets the appropriate BERR bit (register depends on the interface and what kind of frame is received) and then signals a fault (if unmasked). The host must rely on CRC errors and the BERR fault to determine that a byte error has occurred and take the appropriate action.

8.5.1.3.3 Ring Architecture

The daisy chain communication for the BQ79606A-Q1 utilizes a "ring" architecture. In this architecture, a break between two modules does not prevent communication to all upstream devices as in a normal non-ring scheme. When the host detects a communication break, the BQ79606A-Q1 allows the host to switch the communication direction to communicate with devices on both side of the break. This allows for safe operation until the break in the lines is repaired.

Once the host determines there is a break in the daisy-chain (there is no response received during a predetermined timeout and after multiple tries) the host follows the following procedure. The following procedures assume the initial transmit direction was set to North (COML to COMH) CONTROL1[DIR_SEL]=0.

- 1. For the base device: Disable daisy chain high COM RX and COM TX by writing DAISY_CHAIN_CTRL[COMHRX_EN]=0 and DAISY_CHAIN_CTRL [COMHTX_EN]=0.
- 2. For the base device: Enable daisy chain Low COM RX and COM TX by writing DAISY_CHAIN_CTRL[COMLRX_EN]=1 and DAISY_CHAIN_CTRL [COMLTX_EN]=1.
- 3. For the base device: Write 1 to DAISY_CHAIN_CTRL_EN in CONTROL2 register to ensure the COMH/COML TX/RX function is controlled by DAISY_CHAIN_CTRL register.
- 4. For the base device: Write 1 to CONTROL1[DIR_SEL] to reverse the direction of the base and the next subsequent commands go to low side.
- 5. Send Broadcast Write Reverse Direction Command Frame to all devices to switch their direction.
- 6. Send a Broadcast command to clear the CONFIG register of all devices to ensure earlier setting is cleared and the CONFIG[TOP_STACK] is cleared.
- 7. Perform auto addressing by sending a broadcast command to set CONTROL1[ADD_WRITE_EN]=1 (to enable addressing) and ensure the CONTROL1[DIR_SEL]=1.
- 8. Broadcast address of each device using DEVADD_USR register.
- 9. Set the first device as a base by writing 0 to CONFIG[STACK_DEV] of the top device.
- 10. Set as stack the other devices by writing 1 to CONFIG[STACK_DEV] of the top device.
- 11. Set Top of Stack to the top device by writing 1 to CONFIG[TOP_STACK] of the top device.

These devices accept commands from the north direction and forward them in the south direction. Responses are sent on north bus and received on the south bus. The host repeats the process to communicate with the devices in the segment below the communication line break.

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Reverse direction in Ring Architecture after power up requires the host first to do normal direction auto addressing. At power up, all the devices are addressed as 0 by default, and the first step above can result in disabling all devices RX's and TX's. Normal auto addressing prevent this from happening.

Devices in the stack do NOT transmit commands in both the north and south directions simultaneously. The commands are, however, received from both directions. This is to enable the switching of the bus direction. If a command is received on the non-selected receiver, and the command frame initialization byte does NOT identify the frame as a Broadcast Write Reverse Direction command, the command is ignored. If, at any time, commands are received on both buses, only the bus programmed by the CONTROL1[DIR SEL] bit is executed and the other is discarded. The default direction for the stack communication bus is north.

If the user must switch off all devices' COMHTX and COMLTX using COMHTX_EN and COMLTX_EN then it has to be handled by doing individual write to DAISY_CHAIN_CTRL register, one by one starting from top most device instead of attempting a broadcast write.

8.5.1.3.4 Communication Diagnostics

The BQ79606A-Q1 provides comprehensive debugging information for the communication interface. Each communication interface (UART, COML, and COMH) has fault registers to assist with debug during development. The COMM_*_FAULT registers indicate faults that occur at the interface level. Faults indicated here inform the host that the data received is likely wrong and should not be trusted. The COMM_*_RR_FAULT registers indicate faults that occur while receiving a response frame. The COMM_*_RC_FAULT registers indicate faults that occur while receiving a command frame. The COMM_*_TR_FAULT registers indicate faults that occur while transmitting. Additionally, the TONE_FAULT register indicates faults related to the FAULT interface. See the individual register description for specifics on the individual fault conditions. Frame counters are provided for transmitted, received, and discarded frames for each bus.

8.5.1.3.4.1 Byte Errors

General byte errors (COMM_*_R*_FAULT[BERR]) and initialization byte errors (COMM_*_RC_FAULT[IERR]) are the result of improper formatting of a byte. When these occur, the assumption is that the frame timing is incorrect and the information must not be used. Therefore, when a general byte error occurs, all bytes that follow are ignored until a communication break (for UART interface) or start-of-frame bit set (daisy chain interface) is received. As a result, these errors utilize special handling and must be cleared using a communication clear or reset.

COMM COM* R^* FAULT[BERR] is set when a byte error occurs on any byte in a frame received on the COMH/COML interface. The COMM_UART_R*_FAULT[BERR] bit is set when a STOP error occurs on any byte received on the UART interface that is not directly followed by a communication clear. When the byte error occurs, all further bytes received on that interface are ignored. Bytes received on COMH/COML are propagated up the stack, while bytes received on the UART are not propagated. Any other frame errors that occur while the bytes are ignored are not realized or indicated as they are ignored. This includes CRC errors. The bytes are ignored until a SOF byte (COMH/COML) or communication clear (UART interface) is received.

The COMM_COM*_RC_FAULT[IERR] bit is set when a frame initialization byte is expected, but the SOF bit of the received byte is not set or an invalid frame type (one of the reserved commands) is selected. The COMM_UART_RC_FAULT[IERR] bit is set when the frame initialization byte has a stop error, reserved command bits set, or is configured as a response frame (not in multidrop mode). Frame initialization bytes for UART are the 1st byte after a break, or based on frame sequence. When in the multidrop configuration, IERR is also set when the first frame received after a break is a response frame. Bytes received on COMH/COML are propagated up the stack so it is likely all devices in the stack will indicate the IERR fault, bytes received on the UART are not propagated. Any other frame errors that occur while the bytes are ignored are not realized or indicated as they are ignored. This includes CRC errors. The bytes are ignored until a SOF byte (COMH/COML) or communication clear (UART interface) is received.

8.5.1.3.4.2 Frame Counters

The COMM_*_TR_STAT1/COMM_*_TR_STAT2, COMM_*_RR_STAT1/COMM_*_RR_STAT2, COMM_*_RC_STAT1/COMM_*_RC_STAT2 are 16-bit counters that track the number of valid frames received or transmitted. The COMM_*_RR_STAT3 and COMM_*_RC_STAT3 are 8-bit counters that track the number frames that have been discarded for some reason. All counters saturate and do not roll-over. To ensure that all counter data refers to the same period of time, the counters values are latched into registers and the counters are reset upon the user reading the key register. Reading the COMM_UART_RC_STAT3 register latches all of

the COMM_UART_*_STAT* register values and resets all of the UART counters. Reading the COMM_COML_RC_STAT3 register latches all of the COMM_COML_*_STAT* register values and resets all of the COML counters. Reading the COMM_COMH_RR_STAT3 register latches all of the COMM_COMH_*_STAT* register values and resets all of the COMH counters. Each successive read to the key register updates the registers with the current counter value and resets the counters.

The COMM_COM*_TR_STAT1/COMM_COM*_TR_STAT2 counter is incremented whenever a response frame is generated and transmitted over the interface. This does not increment for forwarded response frames (for daisy chain interface), the frame must be generated by the device.

The COMM_*_RR_STAT1/COMM_*_RR_STAT2 counter is incremented whenever a valid (an error free) response frame is received over the interface. Response frames received over the daisy-chain DO increment this counter as they are received and validated during broadcast or stack reads. The counter does NOT increment for individual device responses that are forwarded.

The COMM * RC STAT1/COMM * RC STAT2 counter is incremented whenever a valid (an error free) command frame is received over the interface.

The COMM_*_RR_STAT3 counter is incremented when a received response frame is discarded due to a fault. The discard reason is set in the fault registers when the actual discard event occurs. See the Byte [Errors](#page-64-0) for details on the fault conditions. Note that this counter will not increment in case of IERR error.

The COMM_*_RC_STAT3 counter is incremented when a received command frame is discarded due to a fault. The discard reason is set in the fault registers when the actual discard event occurs. See the Byte [Errors](#page-64-0) for details on the fault conditions. Note that this counter will not increment in case of IERR error.

8.5.1.4 Wakeup and Shutdown

8.5.1.4.1 Base Device Wakeup and Hardware Shutdown

The WAKEUP input pin is used to wake up and reset the base device from SLEEP or SHUTDOWN mode. Additionally, the WAKEUP input defines a "base" device. The WAKEUP input pin is monitored continuously for a low pulse of at least t_{HLD} _{WAKE} (but shorter than t_{HLD SD}) followed by driving the input high. The command is accepted after WAKEUP is high for 30us. This high-low-high (1-0-1) transition (WAKE pulse) signals the BQ79606A-Q1 to enter ACTIVE mode. When a valid WAKEUP signal is received, all settings are reset to the OTP programmed values and the device enters ACTIVE mode and sends a WAKE tone up the stack. If already in ACTIVE mode, the settings are reset and the WAKE tone is sent up the stack. If a command to send a WAKE or SLEEPtoACTIVE tone is received while in the middle of sending a tone (WAKE or SLEEPtoACTIVE), the second command is ignored.

WAKEUP pin must be pulled up to VIO for a base device (for stack devices, connect WAKEUP pin to AVSS). When the IC exits a RESET condition (either through a software RESET, or receiving a WAKE pulse), the WAKEUP pin is sampled. If WAKEUP is high, the device is recognized as a "base" device and disables the COML receiver. This prevents an infinite communication loop when using the ring architecture.

The RX input pin of the UART interface is used to send a SLEEPtoACTIVE signal to the base device of a stack. Hold RX low for $t_{UART(StA)}$ to send a SLEEPtoACTIVE signal. When a valid SLEEPtoACTIVE signal is received in SLEEP mode, the BQ79606A-Q1 transitions to ACTIVE mode without resetting its parameters and sends a SLEEPtoACTIVE tone up the stack. Additionally, a communication clear is detected to clear the bus for new communication traffic. When a SLEEPtoACTIVE signal is received in ACTIVE mode, the BQ79606A-Q1 does not perform any action other than the communication clear and sending a SLEEPtoACTIVE tone up the stack. SLEEPtoACTIVE is ignored in *[SHUTDOWN](#page-44-1) Mode*. COMM_FAULT errors when sending a SLEEPtoACTIVE signal to the base device due to the communication clear. See [Communication](#page-48-0) Clear (Break) Detection for details.

In addition to waking up the device, the WAKEUP input pin is used to send the device to SHUTDOWN mode when it does not respond to a normal reset command (either through the UART or WAKEUP). To send a HARDWARE SHUTDOWN command using WAKEUP pin, drive WAKEUP pin low for t_{HLD_SD} followed by driving it high. The command is accepted after WAKEUP is high for 30us. Upon receiving the SHUTDOWN, the IC immediately enters SHUTDOWN mode. The next time the IC receives a WAKEUP command, it enters ACTIVE mode with the COMH and COML receivers and the COML transmitter are disabled (COMH transmitter is the only one that is enabled). This allows the base device to reject any communication from the stack while it is attempting to be re-initialized. The host must re-enable the necessary receivers before resuming normal operation.

After the wakeup or a shutdown pulse is received on the WAKEUP pin, the user should wait for the device to fully wake up (t_{SUVAKE}) or fully shutdown (t_{SDorSLP}) before sending another pulse in that pin.

Stack devices (devices communicating over the daisy chain only) must connect WAKEUP pin to AVSS to avoid being mis-recognized as a base device.

> 注 When a WAKE or SLEEPtoACTIVE command is sent, the host MUST wait for the device to fully wake up (t_{SU(WAKE)}) before sending additional WAKE, shutdown, or SLEEPtoACTIVE command. Failure to do so may result the device to enter unknown state.

表 **23. Transition Table for Wakeup on Base Device**

8.5.1.4.2 Stack Device Wakeup and Hardware Shutdown

The daisy-chain interface is capable of sending/receiving three different tones. The first, WAKE, resets all settings of the BQ79606A-Q1 and transitions the device to active mode. The second, SLEEPtoACTIVE, only transitions the BQ79606A-Q1 to active mode (if the device in sleep mode) and does NOT reset any settings. The third, SHUTDOWN, transitions the device to shutdown mode. In *[SHUTDOWN](#page-44-1) Mode*, only the WAKE tone is recognized, any SHUTDOWN or SLEEPtoACTIVE tones are ignored. Both WAKE and SLEEPtoACTIVE tones are accepted and propagated during SLEEP and ACTIVE modes. The SHUTDOWN tone is accepted in SLEEP and ACTIVE modes, but NOT propagated up the stack. In ACTIVE mode, SLEEPtoACTIVE causes no action, however, it is propagated up the stack. WAKE tones are sent out under 4 conditions: when a WAKE tone is received, when a WAKEUP pulse occurs on the WAKEUP pin, when a soft reset is commanded through CONTROL1[SOFT_RESET]=1 or when the CONTROL1[SEND_WAKE] bit is set. Similarly, SLEEPtoACTIVE tones are sent out when a SLEEPtoACTIVE tone is received, when a SLEEPtoACTIVE command is received from the UART (RX hold low for t_{UART(StA)}), or when the CONTROL1[SEND_SLPTOACT] bit is set. If a command to send a WAKE, SHUTDOWN, or SLEEPtoACTIVE tone is received while in the middle of sending a tone (WAKE, SHUTDOWN, or SLEEPtoACTIVE), the second command is ignored. A SHUTDOWN tone is only sent when the CONTROL1[SEND SHUTDOWN] bit is set. It is only sent to the next device in the stack and is not propagated. The SHUTDOWN tone command is intended to be a last effort to reset a device that has become unresponsive to normal reset methods (SOFT-RESET or WAKE). Once the SHUTDOWN tone is received, the device immediately transitions to SHUTDOWN mode. Unlike base devices, the receivers and transmitters for stack devices are unaffected by the SHUTDOWN tone.

表 **24. Transition Table for Wake Tones on Stack Devices**

The tones are made up of bit-pair couplets (complementary bits, similar to the daisy chain communication) transmitted at a fixed frequency. WAKE couplets are logic '1', while SHUTDOWN and SLEEPtoACTIVE couplets are logic '0'. All tones are transmitted at t_{COMTONE}. WAKE tones are detected once n_{WAKEDET} WAKE couplets are received. Similarly, a SLEEPtoACTIVE tone is detected once $n_{\sf SLPtoACTDET}$ SLEEPtoACTIVE/SHUTDOWN couplets are received and a SHUTDOWN tone is detected once n_{SDNDET} SLEEPtoACTIVE/SHUTDOWN couplets are received. See \boxtimes [30](#page-68-0) for a graphical representation of the COM* tones.

8.5.1.5 Fault Handling

The BQ79606A-Q1 continuously monitors the battery voltage, battery temperature, die temperature, communications, and internal functions for faults and errors. When one of the monitored faults or errors occurs, the BQ79606A-Q1 alerts the host (with NFAULT for base devices or FAULT tones for stack devices) to allow the host to handle the condition as is necessary. For every fault, there are 3 register bits. The status bit shows the fault is active, the reset bit is used to clear the fault, and the mask bit. Masking a fault prevents the external signaling (NFAULT for base devices or FAULT tones for stack devices). Any time an unmasked fault condition is triggered, the device signals the fault on the NFAULT output (base device) or sends a FAULT tone (stack device) down the stack. Faults are actively monitored in ACTIVE and SLEEP modes when enabled. Faults are NEVER monitored during *[SHUTDOWN](#page-44-1) Mode*.

8.5.1.5.1 Fault Status

When a fault occurs, the fault status bit is updated and if unmasked, the fault is indicated to the host. The host must then poll the status registers to determine which faults have occurred. A summary fault register (FAULT_SUMMARY) is provided to reduce the number of registers to be polled when an error occurs. The summary register only shows UNMASKED faults. The following faults are covered by the summary register:

- FAULT SUMMARY[OTP_FAULT] Contains the aggregation of unmasked faults in the OTP_FAULT register
- FAULT_SUMMARY[SYS_FAULT] Contains the aggregation of unmasked faults in the RAIL_FAULT, SYS_FAULT1, SYS_FAULT2, or SYS_FAULT3 registers
- FAULT SUMMARY[COMM_FAULT] Contains the aggregation of unmasked faults in the TONE_FAULT, COMM_UART_FAULT, COMM_UART_RC_FAULT, COMM_UART_RR_FAULT, COMM_UART_TR_FAULT, COMM_COMH_FAULT, COMM_COMH_RC_FAULT, OMM_COMH_RR_FAULT, COMM_COMH_TR_FAULT, COMM_COML_FAULT,COMM_COML_RC_FAULT, COMM_COML_RR_FAULT, or COMM_COML_TR_FAULT registers.
- FAULT SUMMARY[GPIO_OTUT] Contains the aggregation of unmasked faults in the OT_FAULT, UT_FAULT, or OTUT_BIST_FAULT registers.
- FAULT SUMMARY[CELL_OVUV] Contains the aggregation of unmasked faults in the OV_FAULT, UV_FAULT or OVUV_BIST_FAULT registers.
- FAULT SUMMARY[GPIO FAULT] Contains the aggregation of unmasked faults in the GPIOFAULT registers.

The following registers hold the status bits that create faults when unmasked:

- GPIO_FAULT GPIO input faults (if enabled)
- UV_FAULT Cell under-voltage comparator fault (if enabled)
- OV FAULT Cell over-voltage comparator faults (if enabled)
- UT_FAULT Cell under-temperature comparator fault (if enabled)
- OT FAULT Cell over-temperature comparator faults (if enabled)
- TONE_FAULT FAULT* interface faults (if enabled)
- COMM_UART_FAULT UART bus protocol faults
- COMM_UART_RC_FAULT UART bus command frame receive faults
- COMM_UART_RR_FAULT UART bus response frame receive faults. This register is only valid during multidrop mode.
- COMM_UART_TR_FAULT UART bus transmit faults
- COMM_COMH_FAULT COMH bus protocol faults
- COMM_COMH_RR_FAULT COMH bus response frame receive faults
- COMM_COMH_RC_FAULT COMH bus command frame receive faults
- COMM_COMH_TR_FAULT COMH bus transmit faults
- COMM_COML_FAULT COML bus protocol faults
- COMM_COML_RC_FAULT COML bus command frame receive faults
- COMM_COML_RR_FAULT COML bus response frame receive faults
- COMM_COML_TR_FAULT COML bus transmit faults
- OTP_FAULT OTP load or page faults
- RAIL_FAULT Power supply faults

- SYS_FAULT1 Internal IC faults
- SYS_FAULT2 Internal IC faults
- SYS_FAULT3 Internal IC faults
- OVUV_BIST_FAULT OVUV BIST has failed (if enabled)
- OTUT_BIST_FAULT OTUT BIST has failed (if enabled)

8.5.1.5.1.1 Fault Reset

The fault status bits for the BQ79606A-Q1 are latched until cleared using the reset bit. Once cleared, the NFAULT indication (base device, if enabled) discontinues and the fault heartbeat (stack devices, if enabled) resumes. If the fault condition persists and the reset bit is written, the status bit is not reset (and remains indicated to host using NFAULT or the FAULT* interface), The fault indicator cannot be reset until the underlying fault condition is eliminated. A corresponding group of registers hold reset bits for the fault registers.

- GPIO_FLT_RST Reset bits for GPIO_FAULT
- UV_FLT_RST Reset bits for UV_FAULT
- OV_FLT_RST Reset bits for OV_FAULT
- UT_FLT_RST Reset bits for UT_FAULT
- OT_FLT_RST Reset bits for OT_FAULT
- TONE_FLT_RST Reset bits for FAULTSTAT
- COMM_UART_FLT_RST Reset bits for COMM_UART_FAULT
- COMM_UART_RC_FLT_RST Reset bits for COMM_UART_RC_FAULT
- COMM_UART_RR_FLT_RST- Reset bits for COMM_UART_RR_FAULT
- COMM_UART_TR_FLT_RST- Reset bits for COMM_UART_TR_FAULT
- COMM_COMH_FLT_RST Reset bits for COMM_COMH_FAULT
- COMM_COMH_RR_FLT_RST Reset bits for COMM_COMH_RR_FAULT
- COMM_COMH_RC_FLT_RST Reset bits for COMM_COMH_RC_FAULT
- COMM_COMH_TR_FLT_RST Reset bits for COMM_COMH_TR_FAULT
- COMM_COML_FLT_RST Reset bits for COMM_UART_FAULT
- COMM_COML_RC_FLT_RST Reset bits for COMM_COML_RC_FAULT
- COMM_COML_RR_FLT_RST Reset bits for COMM_COML_RR_FAULT
- COMM_COML_TR_FLT_RST Reset bits for COMM_COML_TR_FAULT
- OTP_FLT_RST Reset bits for OTP_FAULT
- RAIL_FLT_RST Reset bits for RAIL_FAULT
- SYS_FLT1_RST Reset bits for SYS_FAULT1
- SYS_FLT2_RST Reset bits for SYS_FAULT2
- SYS_FLT3_RST Reset bits for SYS_FAULT3
- OVUV_BIST_FLT_RST Reset bits for OVUV_BIST_FAULT
- OTUT_BIST_FLT_RST Reset bits for OTUT_BIST_FAULT

8.5.1.5.2 Fault Masking

All of the possible faults in BQ79606A-Q1 may be masked by the host by setting the corresponding MASK bit. When masked, the FAULT_SUMMARY register does not reflect the bit being set. Additionally, the NFAULT and FAULT* interface do NOT signal when the masked event occurs, however, the status register is updated. NFAULT deasserts once the mask bit is set for the case of an existing fault. Masking bits also prevents cell balancing from terminating when the fault occurs (if enabled). Masking of fault sources is controlled in the following registers:

- GPIO_FLT_MSK Mask bits for GPIO_FAULT
- UV_FLT_MSK Mask bits for UV_FAULT
- OV_FLT_MSK Mask bits for OV_FAULT
- UT_FLT_MSK Mask bits for UT_FAULT
- OT_FLT_MSK Mask bits for OT_FAULT
- TONE_FLT_MSK Mask bits for FAULTSTAT

- COMM_UART_FLT_MSK Mask bits for COMM_UART_FAULT
- COMM_UART_RC_FLT_MSK Mask bits for COMM_UART_RC_FAULT
- COMM_UART_RR_FLT_MSK- Mask bits for COMM_UART_RR_FAULT
- COMM_UART_TR_FLT_MSK- Mask bits for COMM_UART_TR_FAULT
- COMM_COMH_FLT_MSK Mask bits for COMM_COMH_FAULT
- COMM_COMH_RR_FLT_MSK Mask bits for COMM_COMH_RR_FAULT
- COMM_COMH_RC_FLT_MSK Mask bits for COMM_COMH_RC_FAULT
- COMM_COMH_TR_FLT_MSK Mask bits for COMM_COMH_TR_FAULT
- COMM_COML_FLT_MSK Mask bits for COMM_UART_FAULT
- COMM_COML_RC_FLT_MSK Mask bits for COMM_COML_RC_FAULT
- COMM_COML_RR_FLT_MSK Mask bits for COMM_COML_RR_FAULT
- COMM_COML_TR_FLT_MSK Mask bits for COMM_COML_TR_FAULT
- OTP_FLT_MSK Mask bits for OTP_FAULT
- RAIL_FLT_MSK Mask bits for RAIL_FAULT
- SYS_FLT1_MSK Mask bits for SYS_FAULT1
- SYS_FLT2_MSK Mask bits for SYS_FAULT2
- SYS_FLT3_MSK Mask bits for SYS_FAULT3
- OVUV_BIST_FLT_MSK Mask bits for OVUV_BIST_FAULT
- OTUT_BIST_FLT_MSK Mask bits for OTUT_BIST_FAULT

8.5.1.5.3 Fault Signaling

8.5.1.5.3.1 NFAULT Output (Base Device)

The BQ79606A-Q1 integrates an open-drain output (NFAULT) to signal the host processor that a fault has occurred in the battery pack. The NFAULT output is enabled when the COMM_CTRL[NFAULT_EN] bit is set. When the BQ79606A-Q1 detects an unmasked fault, receives a fault tone on the FAULT* interface, or the heartbeat from the device above stops (see *[Daisy-Chain](#page-71-0) FAULT* Interface (Stack Devices)* for heartbeat details), NFAULT asserts low to signal the fault to the host. It is the responsibility of the host to read the stack of devices to determine where the fault occurred. If the FAULT* interface is not enabled, it is the responsibility of the host to poll the status of the stack devices to monitor for faults. The NFAULT output only indicates faults in the base device for this condition.

8.5.1.5.3.2 Daisy-Chain FAULT Interface (Stack Devices)*

The FAULT* interface is used to inform the host of faulted conditions on stack devices. FAULT uses two tones to supply the host with the current FAULT status. A periodic heartbeat tone monitors communication bus integrity, while a FAULTDET tone actively signals a fault has occurred. The FAULT^{*} interface is isolated in the same fashion as the daisy-chain interface. The FAULT* interface transmitters and receivers are individually enabled/disabled using the DAISY_CHAIN_CTRL[FAULTTX_EN] and DAISY_CHAIN_CTRL[FAULTRX_EN] bits, respectively.

8.5.1.5.3.2.1 FAULT* Interface Tones

Similar to the communication bus tones, the FAULT bus uses two tones, a heartbeat tone and a fault detect tone, to communicate information. The tones are made up of bit-pair couplets (complementary bits, similar to the daisy chain communication) transmitted at a fixed frequency. Heartbeat couplets are logic '1', while fault detect couplets are logic '0'. All tones are transmitted at t_{FITIONF} . Heartbeat tones are detected once n_{FITHOPT} heartbeat couplets are received. Similarly, a fault detected tone is detected once $n_{FLTONEDET}$ fault detect couplets are received. See \boxtimes [30](#page-68-0) for a graphical representation of the COM* tones.

The daisy-chain transmits a heartbeat tone from north to south on the FAULT* interface. The heartbeat tone is sent out every t_{WAITHB}. This is to monitor the integrity of the fault bus. The devices continuously monitors for the heartbeat of the device above. If a heartbeat pulse is not received for t_{HBTO} , TONE_FAULT[HB_FAIL] would get set. If it is unmasked and generation of fault tone transmit is enabled (COMM_CTRL[FAULT_HB_EN] bit is enabled), a FAULT tone is sent down the FAULT* interface. The timing allows for one missed heartbeat pulse due to noise. Additionally, during unmasked fault conditions and the heartbeats are enabled, the heartbeat is not generated. The fault must be masked, or cleared, to resume heartbeat generation given the heartbeat is enabled. See the table below for more details.

The device configured as the top of the stack must be set by the user in such a way that it does NOT monitor its FAULTP interface to avoid sending false heartbeat errors. If a heartbeat is received more often than expected (time between heartbeats is less than t_{HBFAST}), the TONE_FAULT[HB_FAST] bit is set to indicate a possible error condition. This error indicates a problem with the FAULT bus. Either a device is damaged, or noise is causing a false receipt of the heartbeat tone. The heart beat counter is a free running counter, it is possible that when the TONE_FAULT[HB_FAIL] is detected, the TONE_FAULT[HB_FAST] can also be set. For that reason, it is recommended to read both HB_FAST and HB_FAIL bit at the same time and every time the TONE_FAULT[HB_FAIL] is detected, the TONE_FAULT[HB_FAST] should be ignored. Note that, if the FAULT line is held high or low for more than 20us (non zero differential value), this can be seen as a heart beat on the south device.

In case an unmasked fault is detected, the device sends a fault tone down the FAULT* interface and stops sending any heartbeat tones until the fault is reset or cleared. As the lower devices receive the fault detected tone, the TONE_FAULT[FF_REC] bit is set and the fault tone is propagated down the stack until ultimately received by the base device, which notifies the host via the NFAULT output. Once the host receives the interrupt, it must read the stack to find the faulted device. Fault detect tones are sent out every t_{FLTRETRY} until the fault is reset and cleared. During SHUTDOWN mode, the FAULT* interface is turned off and does NOT propagate fault detected tones. FAULT tones transmit are enabled/disabled using the COMM_CTRL[FAULT_TONE_EN] bit.

Condition	Unmasked Fault Tone Enabled	Heartbeat Enabled	Fault Generated	Heartbeat Generated
Fault			Yes	No
No Fault			No.	Yes
Fault	0		No	Yes
No Fault	O		No	Yes
Fault			Yes	No
No Fault			No.	No
Fault			No	No
No Fault	0		No	No

表 **25. Fault and Heartbeat Generation**

8.5.1.6 Communication Timeouts

There are two programmable communication timeout thresholds that monitor the absence of a valid frame from either UART or daisy chain communications. A valid frame is defined as any frame (response or command) that does NOT contain any errors that prevent the frame from being processed. These errors include: CRC errors, byte errors (COMM_*_FAULT[BERR] = 1), start of frame errors (COMM_*_FAULT[SOF] = 1), or frame initialization errors(COMM_*_FAULT[IERR] = 1). The communication timeouts are only actively counting while in ACTIVE mode. The counters are disabled and reset during SHUTDOWN mode. In Sleep mode, the last counter values are held frozen.

8.5.1.6.1 Short Communications Timeout Fault

The register COMM_TO[SHORT] sets the acceptable period for no valid communications from either the UART interface or the daisy-chain interface. The timer is reset every time a valid response or 0 command frame is received. If enabled, when the timeout expires, the BQ79606A-Q1 recognizes a communication timeout fault and sets the SYS_FAULT1[CTS] bit. To avoid getting a power-down communications fault before a communications timeout fault, ensure the COMM_TO[SHORT] time is shorter than the COMM_TO[LONG] time.

8.5.1.6.2 Long Communications Timeout Fault

The register COMM_TO[LONG] sets the time period before the BQ79606A-Q1 shuts down due to lack of a valid communication frame from either the UART interface or the daisy-chain interface. Similar to the short communication fault, the timer is reset every time a valid response or command frame is received. If enabled, when the timer expires, the BQ79606A-Q1 enters SHUTDOWN mode. A wake up can recover the device from SHUTDOWN.

To avoid getting a power-down communications fault before a communications timeout fault, ensure the COMM_TO[SHORT] time is shorter than the COMM_TO[LONG] time.

8.5.1.7 Non-Volatile Memory

There are several memory locations that are programmable in non-volatile memory (NVM) using OTP. The OTP is loaded in both the factory and customer space with every reset event to supply the defaults for the corresponding register space. A reset occurs whenever a WAKE tone or WAKEUP is received by the device. Additionally, the host may perform a reset to the OTP defaults by writing the CONTROL1[SOFT RESET] bit. Writing this bit resets all of the registers to the OTP programmed value. Error check and correction (ECC, both single error correction, SEC and double error detection, DED) is performed during both the factory and customer space OTP load. Any load errors of the customer OTP space signal a fault using the OTP_FAULTICUSTLDERRI. Similarly, any load errors of the factory OTP space signal a fault using the OTP_FAULT[FACTLDERR]. Additionally, the OTP space (factory and customer) are protected from data integrity problems using CRC. If any over-voltage error conditions exist in the OTP pages space (factory and customer) , the OTP FAULTIGBLOVERRI bit is set. Information received from the device with this error must not be considered reliable.

8.5.1.7.1 OTP Page Status

Due to the one time programming limitation of OTP NVM, two unused pages of OTP memory are available for the end customer to program. The status of the pages is held in the OTP_CUST1_STAT* and OTP_CUST2_STAT* registers. The OTP_CUST1_STAT1 and OTP_CUST2_STAT1 registers provide information on the current status of the page including the load status (if loaded, if loaded with error, if load failed), whether the page has been programmed successfully and is able to be loaded, or if the page is available for burning. OTP_CUST1_STAT2 and OTP_CUST2_STAT2 registers provide the programmed status.

When a reset occurs, the BQ79606A-Q1 evaluates the OTP page status and chooses the latest, valid OTP page to load. Page 2 has priority over page 1. If both pages have not been written, the factory OTP defaults (as indicated in the summary register table) are loaded. A valid page is one where the OTP_CUST*_STAT1[PROGOK] bit is '1'. When the page is selected for loading, the OTP_CUST*_STAT1[LOADED] bit is set. If a single error occurs in the loading of the page, the page is loaded after the single error is corrected and the OTP_CUST*_STAT1[LOADWRN] bit is set. Additionally, the SEC_BLK register is updated with the location of the error corrected block. If a double error occurs, the loading of that block is terminated and the hardware defaults of that block are loaded (as indicated in the summary register table). The overall page loading process is not terminated for a DED, only the affected block is terminated. When a DED occurs, the OTP_CUST*_STAT1[LOADERR] bit is set. Additionally, the DED_BLK register is updated with the block where the double error occurred. See the Error Check and [Correct](#page-76-0) (ECC) OTP section for more details on error correction.

8.5.1.7.2 Programming NVM

There are two pages of OTP memory available for customer use. To write the NVM, first the desired page is selected using the OTP_PROG_CTRL[PAGESEL] bit. The page must be valid to burn. A valid page is one where the OTP CUST* STAT1[FREE] or OTP CUST* STAT1[RETRY] is '1'. A page with the the OTP_CUST*_STAT1[FREE] or OTP_CUST*_STAT1[RETRY] is '1'. A page with the OTP_CUST*_STAT1[FREE] bit set has never had programming attempted. A page with OTP_CUST*_STAT1[RETRY] bit set has had programming attempted, but an undervoltage error in VPROG occurred and programming was not completed. The status bits in OTP_CUST*_STAT2 indicate the programming history of the page. During programming, if an OV or UV event occurs, the OTP_CUST*_STAT2[UV*OK] and OTP_CUST*_STAT2[OV*OK] bits are set to indicate the VPROG under and over voltage condition during the programing attempts. In addition, the UVERR, OVERR, SUVERR, and SOVERR bits on the OTP_PROG_STAT register indicates if there is VPROG error during programming and stability test.

To start the burn process, use the OTP_PROG_CTRL[PAGESEL] bits to select the page for programming. Next, connect a supply with voltage V_{PROG} to VPROG. This voltage is monitored internally during programming. Programming is aborted when a high/low voltage is connected while a burn is attempted. Once the voltage is connected, the four OTP_PROG_UNLOCK* registers must be written. The registers are separated into two blocks (OTP_PROG_UNLOCK1^{*} and OTP_PROG_UNLOCK2^{*}) with four consecutive registers each (A, B, C, D). Each block of registers must be written in order (i.e. 1,2,3, then 4) with no other writes or reads between. The best practice is to use the same Write command to update. Any attempt to update the registers out of sequence, or if another register is written/read between writes, the entire sequence must be redone. OTP_PROG_UNLOCK1A-OTP_PROG_UNLOCK1D must be written to 0x02B778BC. OTP_PROG_UNLOCK2A-OTP_PROG_UNLOCK2D must be written to 0x7E12086F. Any reads done on the OTP_PROG_UNLOCK* registers result in an all '0' response. Once these registers are written correctly, the OTP_PROG_STAT[UNLOCK] bit is set to signal the host that the OTP burn function is unlocked and enabled. Once the OTP is unlocked, the next write clears the lock condition. Reads can be done after unlocking the OTP (such as confirming the OTP_PROG_STAT[UNLOCK] bit is set). The write following the final unlock command must be to OTP_PROG_CTRL[PROG_GO] to start the programming procedure. A successful program results in the OTP_CUST_STAT1[PROGOK] bit being set and the page is available for loading.

When the OTP programming is enabled, the VPROG voltage is tested in a voltage stability test. The voltage stability test lasts for 300us and checks the voltage for overvoltage and undervoltage conditions. If an overvoltage condition exists, the OTP_PROG_STAT[SOVERR] is set. If an undervoltage condition exists, the OTP_PROG_STAT[SUVERR] is set. If either condition exists during the test, the programming is terminated. Note that this will not set the OTP CUST^{*} STAT2[TRY1] (Meaning there are still two chances to burn the OTP).

Now, If the voltage is good during the stability test, programming proceeds. Once programming is completed, the OTP_PROG_STAT[DONE] bit is set. If any OV or UV errors occurred during the programming, the OTP_PROG_STAT[OVERR] or OTP_PROG_STAT[UVERR] bit (depending on which type of error) is set. If, after the first attempt at programming, the status shows an undervoltage error occured (OTP_CUST*_STAT2[TRY1], OTP_CUST*_STAT2[OV1OK] is '1' and OTP_CUST*_STAT2[UV1OK] is '0'), it is possible to retry the burn on that page with *EXACTLY* the same data only one more time. Note that, when the first attempt to program OTP failed, the user get only one more chance to burn properly the OTP.

If the host incorrectly selected a page for programming, the OTP_PROG_STAT[PROGERR] bit is set. This indicates that the selected page was not available to be programmed. Select the correct page and retry the programming.

8.5.1.7.2.1 CUST OTP Programming

Here is a step by step on how to program customer page 1 or 2:

- Wake up the device and perform auto addressing
	- Apply 18V on BAT pin and wake up the devices
	- Perform Auto Addressing
	- Apply 7.6V on VPROG (With 100mA current Limit)
- Write to 0x100 to 0x103 registers the following values (respectively) to unlock the OTP programing – 0x02, 0xB7, 0x78, 0xBC
- Write to 0x150 to 0x153 register the following values (respectively) to unlock the OTP programing – 0x7E, 0x12, 0x08, 0x6F
- To check if everything is correct, read register 0x27D. This should indicate that there is no error and OTP is unlocked to be programmed (The unlock bit should be "1")
- Write 0x01 on register 0x107 this will program CUST1 (Page 1). Or write 0x03 to 0x107 for CUST2 (Page 2)
- Wait 200ms then read 0x27D to make sure no error occurred and the device programmed successfully.
- Remove 7.6V from VPROG
- Power cycle or soft reset and read the registers that were programmed to make sure they have the proper values

8.5.1.7.3 NVM CRC Testing

To determine register changes, the BQ79606A-Q1 constantly runs a background check on the register contents by computing a CRC and comparing it to a stored value. CRC testing is done for both the customer and factory register space. Customer register changes fall into several categories; intentional (that is, a change written by the host), unintentional (due to an unexpected device or system fault), or the result of an automated operation (such as the status bits for ADC conversion or cell balancing completion). The Register Summary indicates which host programmable registers are included in the CRC. The CUST_CRC_RSLTH and CUST_CRC_RSLTL registers hold the currently computed CRC value. This value is compared against the customer programmed value in the CRC registers. When updating a register covered in the CRC, the customer must update the CRC register. This is done by calculating the CRC, and writing the value to the CUST_CRCH and CUST_CRCL registers. The CRC is updated in the NVM along with the other register updates. The CRC calculation is done in the same manner (including the bit stream ordering) and with the same polynomial as described in *[Calculating](#page-53-0) Frame CRC Value*. The CRC check and comparison is done every $t_{CRC-OTP}$ and the DEV_STAT[CRC_DONE] bit is set after the check is complete. If the bit is already set, it remains set until cleared with a read.

8.5.1.7.4 CRC Faults

When CRC and CRC_RSLT do not match, the SYS_FAULT2[CUST_CRC] flag is set until the condition is corrected. Continuous monitoring of the factory NVM space occurs in a similar fashion, concurrently with the monitoring of the USER space (customer). When a factory register change is detected, the SYS_FAULT2[FACT_CRC] flag is set. When this fault occurs, the host should reset the fault flag to see if the fault persists. If the fault persists, the customer firmware must perform a SOFT_RESET of the part. If SOFT_RESET does not correct the issue, the device is corrupted and must not be used.

8.5.1.7.5 Computing Customer CRC

The CRC check is done on all of the registers in the OTP space (as indicated in the Register Summary table). The register values are concatenated together with the lowest addressed register as the first data byte and the highest addressed register as the last data byte used in the CRC calculation. Using the same bit ordering as described in [Calculating](#page-53-0) Frame CRC Value calculate the CRC on that number in the same manner and with the same polynomial as described in *[Calculating](#page-53-0) Frame CRC Value*.

8.5.1.8 Error Check and Correct (ECC) OTP

Register values for selected registers (0x0000 to 0x00C7) are permanently stored in OTP. All registers also exist as volatile storage locations at the same addresses, referred to as "shadow" registers. The volatile registers are for reading, writing, and device control. For a list of registers included in the OTP, see the Register Summary Table. During wakeup, the BQ79606A-Q1 first loads all shadow registers with hardware default values listed in the Register Summary. Then the BQ79606A-Q1 loads the registers conditionally with OTP contents from the results of the Error Check and Correct (ECC) evaluation of the OTP. The OTP is loaded to shadow registers in 64-bit blocks; each block has its own Error Check and Correct (ECC) value stored. The ECC detects a single-bit (Single-Error-Correction) or double-bit (Double-Error-Detection) changes in OTP stored data. The ECC is calculated for each block, individually. Single-bit errors are corrected, double-bit errors are only detected, not corrected. A block with good ECC is loaded. A block with a single-bit error is corrected, and the SYS_FAULT3[SEC_DET] bit is set to flag the corrected error event. Additionally, the SEC_BLK register is updated with the location of the error corrected block. This enables the host to keep track of potentially damaged memory. The block is loaded to shadow registers after the single-bit error correction. Since the evaluation is on a block-by-block basis, it is possible for multiple blocks to have a single-correctable error and still be loaded correctly. Multiple-bit errors can exist with full correction, as long as they are limited to a single error per block. A block with a bad ECC comparison (two-bit errors in one block) is not loaded and the SYS_FAULT3[DED_DET] bit is set to flag the failed bit-error event. Additionally, the DED_BLK register is updated with the block where the double error occurred. The hardware default value remains in the register. This allows some blocks to be loaded correctly (no fail or single-bit corrected value) and some blocks not to load. When either of the SYS_FAULT3[SEC_DET] or SYS_FAULT3[DED_DET] is set, and the condition is not cleared by a device reset (write CONTROL1[SOFT_RESET] or a WAKE command), the device is corrupted and must not be used.

The ECC engine uses the industry standard 72,64 SEC DEC ECC implementation. The OTP is protected by a (72, 64) Hamming code, providing single error correction, double error detection (SECDED). For each 64-bits of data stored in OTP, an additional 8-bits of parity information are stored. Therefore, the ECC code imposes an area overhead on the OTP of $(72 - 64) / 64$, or 12.5%. The parity bits are designated p0, p1, p2, p4, p8, p16, p32 and p64. Bit p0 covers the entire encoded 72- bit ECC block. The remaining seven parity bits are assigned according to the following rule:

1. Parity bit p1 covers odd bit positions, i.e. bit positions which have the least significant bit of the bit position equal to 1 (1, 3, 5, etc.), including the p1 bit itself (bit 1).

2. Parity bit p2 covers bit positions which have the second least significant bit of the bit position equal to 1 (2, 3, 6, 7, 10, 11, etc.), including the p2 bit itself (bit 2).

The pattern continues for p4, p8, p16, p32 and p64. Table below specifies the complete encoding.

表 **26. (72, 64) Parity Encoding (continued)**

表 **27. Encoder and Decoder Data IN and OUT Positioning**

8.5.1.8.1 ECC Diagnostic Test

The BQ79606A-Q1 provides a diagnostic tool to test the ECC function. There are two modes that are available to run the diagnostic. The first, auto mode (ECC_TEST[MANUAL_AUTO]=0), uses internal data to run the tests. In auto mode, the ECC_TEST[DED_SEC] bit selects the type of test that is to be done and the ECC_TEST[ENC_DEC] bit determines if the encoder or decoder function is to be tested. The result of the ECC test is provided in the ECC_DATAOUT* registers. The expected results from each test are shown in $\frac{1}{5}$ [28](#page-79-0).

The second, manual mode (ECC_TEST[MANUAL_AUTO] = 1) ECC function allows the user to insert their own SEC or DED errors into the ECC tester. The ECC_DATAIN* registers are used to write the values for the test. The ECC is calculated using the information in the previous section. The ECC_DATAOUT* registers output the result of the test. The SYS_FAULT3[SEC_DET] and SYS_FAULT3[DED_DET] bits indicate which type of error (if any) is detected for the decoding test ONLY. Make sure to clear these bits while disabling the ECC test before starting a decoding test. For the encoding test, these bits do not get updated or affected by the encoding test. Once the required test is configured and the SYS_FAULT3 bits above are reset, write the ECC_TEST[ENABLE]=1 to enable the test. Here are the recommended steps to execute the ECC for both the encoder and the decoding tests:

Manual Decoding:

- 1. Pick up any 72-bits value for the test and block write to ECC_DATAIN[8:0]
- 2. Set the ECC_TEST to manual ECC_TEST[MANUAL_AUTO]=1
- 3. Set decoder setting ECC_TEST[ENC_DEC]=0
- 4. Set decoder to single or double encoding setting with ECC_TEST[DED_SEC] (1 for DED or 0 for SEC)
- 5. Enable ECC test ECC_TEST[ENABLE]=1
- 6. Clear all SEC/DED faults by SYS_FLT3_RST[SEC_DET_RST]=1 and SYS_FLT3_RST[DED_DET_RST]=1
- 7. Read SYS_FAULT3[SEC_DETECT] flag for SEC or SYS_FAULT3[DED_DETECT] flag for DED
- 8. Block read ECC_DATAOUT[7:0] to verify the Decoder test results
- 9. Disable ECC test ECC_TEST[ENABLE]=0.
- 10. Clear SEC/DEC faults.

Manual Encoding steps:

- 1. Pick up any 64-bits value for the test and block write to ECC_DATAIN[7:0]
- 2. Set ECC_TEST to manual ECC_TEST[MANUAL_AUTO]=1
- 3. Set the encoder setting using ECC_TEST[ENC_DEC]=1
- 4. Enable the ECC test with ECC_TEST[ENABLE]=1
- 5. Ensure ECC_DATAOUT[8:0] match the value in step "1"
- 6. Disable ECC test ECC_TEST[ENABLE]=0.
- 7. Clear SEC/DEC faults.

Automatic Decoding steps:

- 1. Set ECC_TEST to automatic ECC_TEST[MANUAL_AUTO]=0
- 2. Set decoder setting ECC_TEST[ENC_DEC]=0
- 3. Set decoder to single or double encoding setting with ECC_TEST[DED_SEC] (1 for DED or 0 for SEC)
- 4. Enable ECC test ECC_TEST[ENABLE]=1
- 5. Clear all SEC/DED faults by SYS_FLT3_RST[SEC_DET_RST]=1 and SYS_FLT3_RST[DED_DET_RST]=1
- 6. Read SYS_FAULT3[SEC_DETECT] flag for SEC or SYS_FAULT3[DED_DETECT] flag for DED
- 7. Block read ECC_DATAOUT[7:0] to verify the Decoder test results as in the table below
- 8. Disable ECC test ECC_TEST[ENABLE]=0
- Automatic Encoding steps:
- 1. Set ECC_TEST to automatic ECC_TEST[MANUAL_AUTO]=0
- 2. Set the encoder setting using ECC_TEST[ENC_DEC]=1
- 3. Enable the ECC test with ECC_TEST[ENABLE]=1
- 4. Block read ECC_DATAOUT[8:0] to verify the Encoder test results as in the table below
- 5. Disable ECC test ECC_TEST[ENABLE]=0

表 **28. Automatic (ECC_TEST[MANUAL_AUTO]=0) ECC Diagnostic Results (continued)**

8.5.2 General Purpose IOs and SPI

The BQ79606A-Q1 integrates six general purpose input/outputs (GPIOn). Registers GPIO1_CONF - GPIO6 CONF control the GPIO behavior. Each GPIO is programmable to be an input or an output. Additionally, GPIO1 - GPIO6 are configurable as ADC inputs either for NTC monitoring (ratiometric result) or absolute voltage measurement. GPIO1-GPIO6 are also configurable to be monitored by internal, hardware comparators for over/under-temperature monitoring. See Cell [Over/Under-Temperature](#page-41-0) Comparatorss for more details.

The pullup and pulldowns are configurable (GPIO*_CONF[PUPD_SEL]) to be FET push-pull (between VIO and DVSS), to have an weak pullup (to VIO) or weak pulldown (to DVSS) resistor enabled. Pull-downs must not be used in output mode. Additionally, push-pull mode must not be used in input mode. If either of these configurations are selected, correct operation is not guaranteed and undesirable operation may occur.

図 **32. Acceptable GPIO Input/Output Configurations**

There is a configurable option (GPIO^{*}_CONF[FAULT_EN]) for the GPIO to trigger a FAULT condition when high or low. When enabled, the GPIOs that are in a fault state set a flag in the GPIO_FAULT register. These faults are triggered regardless of the GPIO*_CONF[GPIO_SEL] setting for the GPIO (see the priority ranking below). Additionally, the GPIO_STAT register shows the status ('0' or '1') of the individual GPIO pins regardless of input/output configuration. While configured as an output, the state of the GPIOn is controlled using the GPIO_OUT register.

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There are several functions that utilize the GPIOs as listed below. As many of these functions may mistakenly be enabled simultaneously, there is a priority to the functions. The following list shows the GPIO function priority when multiple function are simultaneously enabled (1 is the highest priority and GPIO* CONF refers to GPIO1_CONF through GPIO6_CONF registers):

- 1. SPI Master enabled (SPI CFG[SPI EN] = 1). GPIO*_CONF[GPIO_SEL], GPIO*_CONF[FLT_EN] and GPIO*_CONF[PUPD_SEL] bits are ignored. This is only valid for GPIO3-GPIO6. GPIO1 and GPIO2 are unaffected when the SPI master is enabled.
- 2. GPIO Addressing enabled (GPIO*_CONF[ADD_SEL] = 1). GPIO automatically setup as input. GPIO* CONF[GPIO_SEL], GPIO* CONF[FLT_EN] and GPIO* CONF[PUPD_SEL] bits are ignored. See the GPIO [Addressing](#page-242-0) section for more details.
- 3. ADC measurements enabled (GPIO*_CONF[PUPD_SEL] = 0b000)
- 4. Normal GPIO behavior (GPIO*_CONF[GPIO_SEL] programmable) and GPIO configured as Fault (GPIO*_CONF[FLT_EN] is set as fault low or high)

Note that the OT/UT function is not affected by the GPIO configuration. If enabled, the OT/UT function will signal faults as normal. For example, if the SPI master is enabled and the OT/UT function is enabled on GPIOs 3-6, faults are indicated as the clock and data are driven by the master (i.e. SCLK idling low trips the OT fault on GPIO6)

8.5.2.1 GPIO ADC Measurements

GPIO1 - GPIO6 are available to measure using the auxiliary ADC. To use the GPIOn as ADC input, first configure the GPIOn as an input using the corresponding GPIO*_CONF register. Enable the ADC conversion on the GPIOn inputs using the AUX_ADC_CTRL1 register. Note If GPIO* is weakly pulled-up (to VIO) and then a GPIO* AUX_ADC conversion is performed, the ADC data will correspond to 96% of VIO. This is due to the resistor divider in the ADCMUX circuit. See *AUX GPIO Input [Measurement](#page-31-0)* for more details.

8.5.2.2 SPI Master Interface

The BQ79606A-Q1 GPIOs are configurable as a SPI master interface. The master is used to control devices such as an external OTP or the Active Balancing Chipset (EMB1428/EMB1499) from Texas Instruments. The SPI interface includes four I/Os: clock (SCLK), master data output (MOSI), master data input (MISO), and the slave select (SS). Three of the lines are shared by all devices on the SPI bus: SCLK, MOSI and MISO. SCLK is generated by the BQ79606A-Q1 (f_{SCLK}) and is used for synchronization. MOSI and MISO are the data lines.

図 **33. SPI Configuration**

Each stack device is configurable to be a SPI master. The result looks something like \boxtimes [34](#page-82-0).

図 **34. SPI Master Stack Configuration**

The SPI timing diagram is shown in \boxtimes [35](#page-83-0).

Clock polarity (CPOL) and clock phase (CPHA) define the SPI bus clock format. These are programmable for the BQ79606A-Q1 using the SPI_CFG[CPOL] and SPI_CFG[CPHA] bits. The SPI clock is inverted/non-inverted depending on CPOL parameter. The CPHA parameter shifts the sampling phase. While SPI_CFG[CPHA]=0, MISO and MOSI are sampled on the leading (first) clock edge. When SPI_CFG[CPHA]=1, MISO and MOSI are sampled on the trailing (second) clock edge, regardless of whether that clock edge is rising or falling. The following sections outline the behavior of CPHA and CPOL.

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8.5.2.2.1 CPOL=0, CPHA=0

The data must be available before the first clock signal rising. The clock idle state is zero. The data on MISO and MOSI lines must be stable while the clock is high and are changed only when the clock is low. The data is captured on the clock's low-to-high transition and propagated on high-to-low clock transition.

図 **36. CPOL=0, CPHA=0 Diagram**

8.5.2.2.2 CPOL=0, CPHA=1

The first clock signal rising is used to prepare the data. The clock idle state is zero. The data on MISO and MOSI lines must be stable while the clock is low and is only changed when the clock is high. The data is captured on the clock's high-to-low transition and propagated on low-to-high clock transition.

図 **37. CPOL=0, CPHA=1 Diagram**

8.5.2.2.3 CPOL=1, CPHA=0

The data must be available before the first clock signal falling. The clock idle state is one. The data on MISO and MOSI lines must be stable while the clock is low and is only changed when the clock is high. The data is captured on the clock's high-to-low transition and propagated on low-to-high clock transition.

図 **38. CPOL=1, CPHA=0 Diagram**

8.5.2.2.4 CPOL=1, CPHA=1

The first clock signal falling is used to prepare the data. The clock idle state is one. The data on MISO and MOSI lines must be stable while the clock is high and can be changed when the clock is low. The data is captured on the clock's low-to-high transition and propagated on high-to-low clock transition.

8.5.2.2.5 SPI Master Protocol

The master is programmed using a combination of writes. A first write must be done to the SPI_CFG register to configure the master for the transaction. The SPI_CFG[SPI_EN] bit is used to enable the SPI master interface, the SPI_CFG[SS_STAT] bit is used to select the slave device, and finally, the SPI_CFG[NUMBITS] sets how many bits the transaction is (1-bit to 8-bit transaction). SPI_CFG[NUMBITS] is only read by the device when the SPI_GO command is executed. After the SPI is configured, write to the SPI_EXE[SPI_GO] bit to execute the transaction. Once the SPI_EXE[SPI_GO] is written to a '1', a SPI transaction of a length set by SPI_CFG[NUMBITS] is executed. The SPI_CFG[SS_STAT] write and the SPI_EXE[SPI_GO] write must be two separate transaction to guarantee a properly executed transaction. The transaction writes the bits in the SPI_TX register to the slave device and simultaneously reads the bits from the slave device to the SPI_RX register. For an 8-bit write, the full byte is used. For less than 8-bit transactions, the write is done starting with the LSB and the read updates starting with LSB. For example, for a 3-bit transaction, bits 2:0 of the register SPI_TX are written to MOSI while the bits 2:0 of SPI_RX updated with the read data from MISO. Due to the simultaneous

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read and write of the data, the SPI master supports both types of SPI devices. For devices where read/write are separate transactions, SPI_RX is a "don't care" when a write is done. Multiple writes or read are possible while the SS pin of a particular device is selected. This enables support for SPI slaves that larger than 8-bit transactions. Multiple transactions must be done while SS is selected to complete larger than 8-bit transactions. Once the read or write is complete, set the SPI_CFG[SS_STAT] bit to end the transaction.

It should be noted that before the SPI_CFG[SPI_EN] bit is set, the SPI interface pins are configured by the GPIO*_CONF registers. This could lead to invalid states on the SPI pins (from the SPI interface perspective). For example, if the GPIO*_CONF registers have GPIO3 configured as an input, with the SPI function disabled GPIO3 (SS) may be low, selecting the slave device without intending to. If this is an issue for the application, use an external pull up to VIO to ensure the correct state for the slave. Once SPI is enabled, all of the GPIOs are set in accordance to the SPI_CFG register.

注 Do not change the CPHA (SPI_CFG[CPHA]/CPOL (SPI_CFG[CPOL]) values and the SS

図 **40. SPI Command Frame Timing**

8.5.2.2.5.1 SPI Write Examples

In the following example, an 8-bit write to the SPI slave of 0x3B is done. The slave has an active-low chip select with a (CPOL, CPHA) requirement of (0,0).

表 **29. 8-Bit SPI Write Transaction**

In the following example, an 12-bit write to the SPI slave of 0x73B is done. The slave has an active-low chip select with a (CPOL, CPHA) requirement of (0,0).

表 **30. 12-Bit SPI Write Transaction**

8.5.2.2.5.2 SPI Read Examples

In the following example, an 8-bit read to the SPI slave done (0x3B is expected result). The slave has an activelow chip select with a (CPOL, CPHA) requirement of (0,0).

表 **31. 8-Bit SPI Read Transaction**

In the following example, an 12-bit read to the SPI slave done (0x73B is expected result). The slave has an active-low chip select with a (CPOL, CPHA) requirement of (0,0).

表 **32. 12-Bit SPI Read Transaction (continued)**

8.5.2.3 SPI Loopback Function

The SPI master has a loopback function that is enabled using the DIAG_CTRL1[SPI_LOOPBACK] bit. When enabled, the byte in the SPI_TX register is clocked directly to the MISO pin of the SPI master to verify the SPI master functionality. This is done internally, so no external connection is required to run this test. This verifies that the SPI function is working correctly. The SPI_CFG, SPI_TX, and SPI_EXE registers are written as a normal SPI transaction, but the external pins do not toggle during this mode. The expected result of the test is that the byte in the SPI_TX register is read into the SPI_RX register. The SS pin is latched to the setting in SPI_CFG[SS_STAT] that existed when the LOOPBACK mode was enabled. The CPHA and CPOL parameters must be set before entering LOOPBACK mode to ensure proper operation. Changing the CPOL or CPHA parameters while in LOOPBACK mode may result in errant pulses on the SPI outputs and is not recommended.

8.5.3 Safety Mechanisms

The BQ79606A-Q1 complies with applicable component level requirements for ASIL-D. The Safety Manual for BQ79606A-Q1 (SLUA822) and the BQ79606A-Q1 FMEDA documents are available separately from Texas Instruments. Contact TI Sales Associate or Applications Engineer for further information.

KEY: ADDR = Address; R = Read; W = Write; R/W = Read/Write; NVM = Non-volatile memory (OTP): 'Various' indicates that the value is set in the factory and is not consistent device to device.

Reserved bits that are located between 0x100 to 0x2E2 are not implemented in the design. Any writes to these bits are ignored. Reads to these bits always return '0'. However the reserved bits located between 0x00 to 0xC7 are implemented and is part of CRC calculation. The user should not write them. Spare bits are implemented in the design, but do not perform a function. These bits are read/write as normal, but do not influence any behaviors, but can be included in CRC calculation depending on the location (as indicated in the summary register table).

General Note on Command Buffers: There are three command buffers (one for UART, COMH, and COML) which assemble frames as they are received. The command buffers check for IERR, SOF, BERR and CRC. If a frame is valid and passes all those checks, then it gets sent to the command processor, which then checks TXDIS and UNEXP.

Register details are shown using the format shown in $\bar{\textbf{x}}$ [33](#page-90-0)

表 **33. Register Details**

8.6.1 Customer Registers

8.6.1.1 Register Summary Table

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[BQ79606A-Q1](http://www.ti.com/product/bq79606a-q1?qgpn=bq79606a-q1)

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8.6.1.2 Register: DEVADD_OTP

8.6.1.3 Register: CONFIG

8.6.1.4 Register: GPIO_FLT_MSK

8.6.1.5 Register: UV_FLT_MSK

8.6.1.6 Register: OV_FLT_MSK

8.6.1.7 Register: UT_FLT_MSK

8.6.1.8 Register: OT_FLT_MSK

8.6.1.9 Register: TONE_FLT_MSK

8.6.1.10 Register: COMM_UART_FLT_MSK

8.6.1.11 Register: COMM_UART_RC_FLT_MSK

8.6.1.12 Register: COMM_UART_RR_FLT_MSK

8.6.1.13 Register: COMM_UART_TR_FLT_MSK

8.6.1.14 Register: COMM_COMH_FLT_MSK

8.6.1.15 Register: COMM_COMH_RC_FLT_MSK

8.6.1.16 Register: COMM_COMH_RR_FLT_MSK

8.6.1.17 Register: COMM_COMH_TR_FLT_MSK

8.6.1.18 Register: COMM_COML_FLT_MSK

8.6.1.19 Register: COMM_COML_RC_FLT_MSK

8.6.1.20 Register: COMM_COML_RR_FLT_MSK

8.6.1.21 Register: COMM_COML_TR_FLT_MSK

8.6.1.22 Register: OTP_FLT_MSK

8.6.1.23 Register: RAIL_FLT_MSK

8.6.1.24 Register: SYS_FLT1_FLT_MSK

8.6.1.25 Register: SYS_FLT2_FLT_MSK

8.6.1.26 Register: SYS_FLT3_FLT_MSK

8.6.1.27 Register: OVUV_BIST_FLT_MSK

8.6.1.28 Register: OTUT_BIST_FLT_MSK

8.6.1.29 Register: SPARE_01

8.6.1.30 Register: SPARE_02

8.6.1.31 Register: SPARE_03

8.6.1.32 Register: SPARE_04

8.6.1.33 Register: SPARE_05

8.6.1.34 Register: COMM_CTRL

8.6.1.35 Register: DAISY_CHAIN_CTRL

8.6.1.36 Register: TX_HOLD_OFF

8.6.1.37 Register: COMM_TO

8.6.1.38 Register: CELL_ADC_CONF1

8.6.1.39 Register: CELL_ADC_CONF2

8.6.1.40 Register: AUX_ADC_CONF

8.6.1.41 Register: ADC_DELAY

8.6.1.42 Register: GPIO_ADC_CONF

8.6.1.43 Register: OVUV_CTRL

8.6.1.44 Register: UV_THRESH

8.6.1.45 Register: OV_THRESH

8.6.1.46 Register: OTUT_CTRL

8.6.1.47 Register: OTUT_THRESH

8.6.1.48 Register: COMP_DG

8.6.1.49 Register: GPIO1_CONF

8.6.1.50 Register: GPIO2_CONF

8.6.1.51 Register: GPIO3_CONF

8.6.1.52 Register: GPIO4_CONF

8.6.1.53 Register: GPIO5_CONF

8.6.1.54 Register: GPIO6_CONF

8.6.1.55 Register: CELL1_GAIN

8.6.1.56 Register: CELL2_GAIN

8.6.1.57 Register: CELL3_GAIN

8.6.1.58 Register: CELL4_GAIN

8.6.1.59 Register: CELL5_GAIN

8.6.1.60 Register: CELL6_GAIN

8.6.1.61 Register: CELL1_OFF

8.6.1.62 Register: CELL2_OFF

8.6.1.63 Register: CELL3_OFF

8.6.1.64 Register: CELL4_OFF

8.6.1.65 Register: CELL5_OFF

8.6.1.66 Register: CELL6_OFF

8.6.1.67 Register: GPIO1_GAIN

8.6.1.68 Register: GPIO2_GAIN

8.6.1.69 Register: GPIO3_GAIN

8.6.1.70 Register: GPIO4_GAIN

8.6.1.71 Register: GPIO5_GAIN

8.6.1.72 Register: GPIO6_GAIN

8.6.1.73 Register: GPIO1_OFF

8.6.1.74 Register: GPIO2_OFF

8.6.1.75 Register: GPIO3_OFF

8.6.1.76 Register: GPIO4_OFF

8.6.1.77 Register: GPIO5_OFF

8.6.1.78 Register: GPIO6_OFF

8.6.1.79 Register: GPAUXCELL_GAIN

8.6.1.80 Register: GPAUXCELL_OFF

8.6.1.81 Register: GPAUX_GAIN

8.6.1.82 Register: GPAUX_OFF

8.6.1.83 Register: VC1COEFF1

8.6.1.84 Register: VC1COEFF2

8.6.1.85 Register: VC1COEFF3

8.6.1.86 Register: VC1COEFF4

8.6.1.87 Register: VC1COEFF5

8.6.1.88 Register: VC1COEFF6

8.6.1.89 Register: VC1COEFF7

8.6.1.90 Register: VC1COEFF8

8.6.1.91 Register: VC1COEFF9

8.6.1.92 Register: VC1COEFF10

8.6.1.93 Register: VC1COEFF11

VC1COEFF11 Register Address: 0x5B

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8.6.1.94 Register: VC1COEFF12

8.6.1.95 Register: VC1COEFF13

8.6.1.96 Register: VC1COEFF14

8.6.1.97 Register: VC2COEFF1

8.6.1.98 Register: VC2COEFF2

VC2COEFF2 Register Address: 0x60

8.6.1.99 Register: VC2COEFF3

VC2COEFF3 Register Address: 0x61

8.6.1.100 Register: VC2COEFF4

8.6.1.101 Register: VC2COEFF5

8.6.1.102 Register: VC2COEFF6

8.6.1.103 Register: VC2COEFF7

8.6.1.104 Register: VC2COEFF8

8.6.1.105 Register: VC2COEFF9

VC2COEFF9 Register Address: 0x67

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8.6.1.106 Register: VC2COEFF10

8.6.1.107 Register: VC2COEFF11

8.6.1.108 Register: VC2COEFF12

8.6.1.109 Register: VC2COEFF13

8.6.1.110 Register: VC2COEFF14

VC2COEFF14 Register Address: 0x6C

8.6.1.111 Register: VC3COEFF1

VC3COEFF1 Register Address: 0x6D

8.6.1.112 Register: VC3COEFF2

8.6.1.113 Register: VC3COEFF3

8.6.1.114 Register: VC3COEFF4

8.6.1.115 Register: VC3COEFF5

8.6.1.116 Register: VC3COEFF6

VC3COEFF6 Register Address: 0x72

8.6.1.117 Register: VC3COEFF7

VC3COEFF7 Register Address: 0x73

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8.6.1.118 Register: VC3COEFF8

8.6.1.119 Register: VC3COEFF9

8.6.1.120 Register: VC3COEFF10

8.6.1.121 Register: VC3COEFF11

8.6.1.122 Register: VC3COEFF12

VC3COEFF12 Register Address: 0x78

8.6.1.123 Register: VC3COEFF13

VC3COEFF13 Register Address: 0x79

8.6.1.124 Register: VC3COEFF14

8.6.1.125 Register: VC4COEFF1

8.6.1.126 Register: VC4COEFF2

8.6.1.127 Register: VC4COEFF3

8.6.1.128 Register: VC4COEFF4

VC4COEFF4 Register Address: 0x7E

8.6.1.129 Register: VC4COEFF5

VC4COEFF5 Register Address: 0x7F

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8.6.1.130 Register: VC4COEFF6

8.6.1.131 Register: VC4COEFF7

8.6.1.132 Register: VC4COEFF8

8.6.1.133 Register: VC4COEFF9

8.6.1.134 Register: VC4COEFF10

8.6.1.135 Register: VC4COEFF11

VC4COEFF11 Register Address: 0x85

8.6.1.136 Register: VC4COEFF12

8.6.1.137 Register: VC4COEFF13

8.6.1.138 Register: VC4COEFF14

8.6.1.139 Register: VC5COEFF1

8.6.1.140 Register: VC5COEFF2

VC5COEFF2 Register Address: 0x8A

8.6.1.141 Register: VC5COEFF3

VC5COEFF3 Register Address: 0x8B

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8.6.1.142 Register: VC5COEFF4

8.6.1.143 Register: VC5COEFF5

8.6.1.144 Register: VC5COEFF6

8.6.1.145 Register: VC5COEFF7

8.6.1.146 Register: VC5COEFF8

8.6.1.147 Register: VC5COEFF9

VC5COEFF9 Register Address: 0x91

8.6.1.148 Register: VC5COEFF10

8.6.1.149 Register: VC5COEFF11

8.6.1.150 Register: VC5COEFF12

8.6.1.151 Register: VC5COEFF13

8.6.1.152 Register: VC5COEFF14

VC5COEFF14 Register Address: 0x96

8.6.1.153 Register: VC6COEFF1

VC6COEFF1 Register Address: 0x97

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8.6.1.154 Register: VC6COEFF2

8.6.1.155 Register: VC6COEFF3

8.6.1.156 Register: VC6COEFF4

8.6.1.157 Register: VC6COEFF5

8.6.1.158 Register: VC6COEFF6

VC6COEFF6 Register Address: 0x9C

8.6.1.159 Register: VC6COEFF7

VC6COEFF7 Register Address: 0x9D

8.6.1.160 Register: VC6COEFF8

8.6.1.161 Register: VC6COEFF9

8.6.1.162 Register: VC6COEFF10

8.6.1.163 Register: VC6COEFF11

8.6.1.164 Register: VC6COEFF12

VC6COEFF12 Register Address: 0xA2

8.6.1.165 Register: VC6COEFF13

VC6COEFF13 Register Address: 0xA3

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8.6.1.166 Register: VC6COEFF14

8.6.1.167 Register: VAUXCOEFF1

8.6.1.168 Register: VAUXCOEFF2

8.6.1.169 Register: VAUXCOEFF3

8.6.1.170 Register: VAUXCOEFF4

8.6.1.171 Register: VAUXCOEFF5

VAUXCOEFF5 Register Address: 0xA9

8.6.1.172 Register: VAUXCOEFF6

8.6.1.173 Register: VAUXCOEFF7

8.6.1.174 Register: VAUXCOEFF8

8.6.1.175 Register: VAUXCOEFF9

8.6.1.176 Register: VAUXCOEFF10

8.6.1.177 Register: VAUXCOEFF11

VAUXCOEFF11 Register Address: 0xAF

8.6.1.178 Register: VAUXCOEFF12

8.6.1.179 Register: VAUXCOEFF13

8.6.1.180 Register: VAUXCOEFF14

8.6.1.181 Register: VAUXCELLCOEFF1

8.6.1.182 Register: VAUXCELLCOEFF2

8.6.1.183 Register: VAUXCELLCOEFF3

VAUXCELLCOEFF3 Register Address: 0xB5

8.6.1.184 Register: VAUXCELLCOEFF4

8.6.1.185 Register: VAUXCELLCOEFF5

8.6.1.186 Register: VAUXCELLCOEFF6

VAUXCELLCOEFF6 Register Address: 0xB8

8.6.1.187 Register: VAUXCELLCOEFF7

8.6.1.188 Register: VAUXCELLCOEFF8

8.6.1.189 Register: VAUXCELLCOEFF9

VAUXCELLCOEFF9 Register Address: 0xBB

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8.6.1.190 Register: VAUXCELLCOEFF10

8.6.1.191 Register: VAUXCELLCOEFF11

8.6.1.192 Register: VAUXCELLCOEFF12

8.6.1.193 Register: VAUXCELLCOEFF13

8.6.1.194 Register: VAUXCELLCOEFF14

VAUXCELLCOEFF14 Register Address: 0xC0

8.6.1.195 Register: SPARE_6

SPARE_6 Register Address: 0xC1

8.6.1.196 Register: CUST_MISC1

8.6.1.197 Register: CUST_MISC2

8.6.1.198 Register: CUST_MISC3

8.6.1.199 Register: CUST_MISC4

8.6.1.200 Register: CUST_CRCH

8.6.1.201 Register: CUST_CRCL

STRUMENTS

EXAS

8.6.1.202 Register: OTP_PROG_UNLOCK1A

8.6.1.203 Register: OTP_PROG_UNLOCK1B

8.6.1.204 Register: OTP_PROG_UNLOCK1C

8.6.1.205 Register: OTP_PROG_UNLOCK1D

8.6.1.206 Register: DEVADD_USR

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8.6.1.207 Register: CONTROL1

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8.6.1.208 Register: CONTROL2

8.6.1.209 Register: OTP_PROG_CTRL

8.6.1.210 Register: GPIO_OUT

8.6.1.211 Register: CELL_ADC_CTRL

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8.6.1.212 Register: AUX_ADC_CTRL1

8.6.1.213 Register: AUX_ADC_CTRL2

8.6.1.214 Register: AUX_ADC_CTRL3

8.6.1.215 Register: CB_CONFIG

8.6.1.216 Register: CB_CELL1_CTRL

8.6.1.217 Register: CB_CELL2_CTRL

8.6.1.218 Register: CB_CELL3_CTRL

8.6.1.219 Register: CB_CELL4_CTRL

8.6.1.220 Register: CB_CELL5_CTRL

8.6.1.221 Register: CB_CELL6_CTRL

8.6.1.222 Register: CB_DONE_THRESH

8.6.1.223 Register: CB_SW_EN

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8.6.1.224 Register: DIAG_CTRL1

8.6.1.225 Register: DIAG_CTRL2

8.6.1.226 Register: DIAG_CTRL3

8.6.1.227 Register: DIAG_CTRL4

8.6.1.228 Register: VC_CS_CTRL

8.6.1.229 Register: CB_CS_CTRL

8.6.1.230 Register: CBVC_COMP_CTRL

8.6.1.231 Register: ECC_TEST

8.6.1.232 Register: ECC_DATAIN0

EXAS STRUMENTS

8.6.1.233 Register: ECC_DATAIN1

8.6.1.234 Register: ECC_DATAIN2

8.6.1.235 Register: ECC_DATAIN3

8.6.1.236 Register: ECC_DATAIN4

8.6.1.237 Register: ECC_DATAIN5

8.6.1.238 Register: ECC_DATAIN6

8.6.1.239 Register: ECC_DATAIN7

8.6.1.240 Register: ECC_DATAIN8

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8.6.1.241 Register: GPIO_FLT_RST

8.6.1.242 Register: UV_FLT_RST

8.6.1.243 Register: OV_FLT_RST

8.6.1.244 Register: UT_FLT_RST

8.6.1.245 Register: OT_FLT_RST

8.6.1.246 Register: TONE_FLT_RST

8.6.1.247 Register: COMM_UART_FLT_RST

8.6.1.248 Register: COMM_UART_RC_FLT_RST

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8.6.1.249 Register: COMM_UART_RR_FLT_RST

8.6.1.250 Register: COMM_UART_TR_FLT_RST

8.6.1.251 Register: COMM_COMH_FLT_RST

8.6.1.252 Register: COMM_COMH_RC_FLT_RST

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8.6.1.253 Register: COMM_COMH_RR_FLT_RST

8.6.1.254 Register: COMM_COMH_TR_FLT_RST

COMM_COMH_TR_FLT_RST Register Address: 0x134 B7 B6 B5 B4 B3 B2 B1 B0 RSVD[5] | RSVD[4] | RSVD[3] | RSVD[2] | RSVD[1] | RSVD[0] | SPARE | WAIT_RST 0 0 0 0 0 0 0 0 R | R | R | R | RW | RW RSVD[5:0] reserved SPARE Spare WAIT_RST Resets COMM_COMH_TR_FAULT[WAIT] to '0' 0: Do not reset 1: Reset Always reads '0'

8.6.1.255 Register: COMM_COML_FLT_RST

8.6.1.256 Register: COMM_COML_RC_FLT_RST

8.6.1.257 Register: COMM_COML_RR_FLT_RST

8.6.1.258 Register: COMM_COML_TR_FLT_RST

8.6.1.259 Register: OTP_FLT_RST

8.6.1.260 Register: RAIL_FLT_RST

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8.6.1.261 Register: SYS_FLT1_RST

8.6.1.262 Register: SYS_FLT2_RST

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8.6.1.263 Register: SYS_FLT3_RST

8.6.1.264 Register: OVUV_BIST_FLT_RST

8.6.1.265 Register: OTUT_BIST_FLT_RST

8.6.1.266 Register: OTP_PROG_UNLOCK2A

8.6.1.267 Register: OTP_PROG_UNLOCK2B

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8.6.1.268 Register: OTP_PROG_UNLOCK2C

8.6.1.269 Register: OTP_PROG_UNLOCK2D

8.6.1.270 Register: SPI_CFG

8.6.1.271 Register: SPI_TX

8.6.1.272 Register: SPI_EXE

8.6.1.273 Register: PARTID

8.6.1.274 Register: SYS_FAULT1

8.6.1.275 Register: SYS_FAULT2

8.6.1.276 Register: SYS_FAULT3

8.6.1.277 Register: DEV_STAT

8.6.1.278 Register: LOOP_STAT

8.6.1.279 Register: FAULT_SUMMARY

8.6.1.280 Register: VCELL1_HF

8.6.1.281 Register: VCELL1_LF

8.6.1.282 Register: VCELL2_HF

8.6.1.283 Register: VCELL2_LF

8.6.1.284 Register: VCELL3_HF

8.6.1.285 Register: VCELL3_LF

8.6.1.286 Register: VCELL4_HF

8.6.1.287 Register: VCELL4_LF

8.6.1.288 Register: VCELL5_HF

8.6.1.289 Register: VCELL5_LF

8.6.1.290 Register: VCELL6_HF

8.6.1.291 Register: VCELL6_LF

8.6.1.292 Register: CONV_CNTH

8.6.1.293 Register: CONV_CNTL

8.6.1.294 Register: VCELL1H

8.6.1.295 Register: VCELL1L

8.6.1.296 Register: VCELL2H

8.6.1.297 Register: VCELL2L

8.6.1.298 Register: VCELL3H

8.6.1.299 Register: VCELL3L

8.6.1.300 Register: VCELL4H

8.6.1.302 Register: VCELL5H

8.6.1.303 Register: VCELL5L

8.6.1.304 Register: VCELL6H

8.6.1.305 Register: VCELL6L

8.6.1.306 Register: VCELL_FACTCORRH

EXAS

8.6.1.307 Register: VCELL_FACTCORRL

8.6.1.308 Register: AUX_CELLH

8.6.1.309 Register: AUX_CELLL

8.6.1.310 Register: AUX_BATH

AUX_BATH Register Address: 0x225

8.6.1.311 Register: AUX_BATL

8.6.1.312 Register: AUX_REF2H

8.6.1.313 Register: AUX_REF2L

8.6.1.314 Register: AUX_ZEROH

8.6.1.315 Register: AUX_ZEROL

8.6.1.316 Register: AUX_AVDDH

8.6.1.317 Register: AUX_AVDDL

8.6.1.318 Register: AUX_GPIO1H

8.6.1.319 Register: AUX_GPIO1L

8.6.1.320 Register: AUX_GPIO2H

8.6.1.321 Register: AUX_GPIO2L

8.6.1.322 Register: AUX_GPIO3H

8.6.1.323 Register: AUX_GPIO3L

8.6.1.324 Register: AUX_GPIO4H

8.6.1.325 Register: AUX_GPIO4L

8.6.1.326 Register: AUX_GPIO5H

8.6.1.327 Register: AUX_GPIO5L

8.6.1.328 Register: AUX_GPIO6H

8.6.1.329 Register: AUX_GPIO6L

8.6.1.330 Register: AUX_FACTCORRH

8.6.1.331 Register: AUX_FACTCORRL

8.6.1.332 Register: DIE_TEMPH

8.6.1.333 Register: DIE_TEMPL

8.6.1.334 Register: AUX_REF3H

8.6.1.335 Register: AUX_REF3L

8.6.1.336 Register: AUX_OV_DACH

8.6.1.337 Register: AUX_OV_DACL

8.6.1.338 Register: AUX_UV_DACH

8.6.1.339 Register: AUX_UV_DACL

8.6.1.340 Register: AUX_OT_DACH

8.6.1.341 Register: AUX_OT_DACL

8.6.1.342 Register: AUX_UT_DACH

8.6.1.343 Register: AUX_UT_DACL

8.6.1.344 Register: AUX_TWARN_PTATH

8.6.1.345 Register: AUX_TWARN_PTATL

8.6.1.346 Register: AUX_DVDDH

8.6.1.347 Register: AUX_DVDDL

8.6.1.348 Register: AUX_TSREFH

8.6.1.349 Register: AUX_TSREFL

8.6.1.350 Register: AUX_CVDDH

8.6.1.351 Register: AUX_CVDDL

8.6.1.352 Register: AUX_AVAO_REFH

8.6.1.353 Register: AUX_AVAO_REFL

8.6.1.354 Register: SPI_RX

8.6.1.355 Register: CB_DONE

8.6.1.356 Register: GPIO_STAT

8.6.1.357 Register: CBVC_COMP_STAT

8.6.1.358 Register: CBVC_VCLOW_STAT

8.6.1.359 Register: COMM_UART_RC_STAT3

8.6.1.360 Register: COMM_COML_RC_STAT3

8.6.1.361 Register: COMM_COMH_RR_STAT3

8.6.1.362 Register: COMM_COML_RR_STAT3

8.6.1.363 Register: COMM_COMH_RC_STAT3

8.6.1.364 Register: COMM_UART_RR_STAT3

8.6.1.365 Register: COMM_UART_RC_STAT1

8.6.1.366 Register: COMM_UART_RC_STAT2

8.6.1.367 Register: COMM_COML_RC_STAT1

8.6.1.368 Register: COMM_COML_RC_STAT2

8.6.1.369 Register: COMM_COMH_RR_STAT1

8.6.1.370 Register: COMM_COMH_RR_STAT2

STRUMENTS

EXAS

8.6.1.371 Register: COMM_UART_TR_STAT1

8.6.1.372 Register: COMM_UART_TR_STAT2

8.6.1.373 Register: COMM_COML_TR_STAT1

8.6.1.374 Register: COMM_COML_TR_STAT2

8.6.1.375 Register: COMM_COMH_RC_STAT1

8.6.1.376 Register: COMM_COMH_RC_STAT2

8.6.1.377 Register: COMM_COML_RR_STAT1

8.6.1.378 Register: COMM_COML_RR_STAT2

8.6.1.379 Register: COMM_COMH_TR_STAT1

8.6.1.380 Register: COMM_COMH_TR_STAT2

STRUMENTS

EXAS

8.6.1.381 Register: COMM_UART_RR_STAT1

8.6.1.382 Register: COMM_UART_RR_STAT2

8.6.1.383 Register: OTP_PROG_STAT

8.6.1.384 Register: OTP_CUST1_STAT1

8.6.1.385 Register: OTP_CUST1_STAT2

8.6.1.386 Register: OTP_CUST2_STAT1

8.6.1.387 Register: OTP_CUST2_STAT2

8.6.1.388 Register: CB_SW_STAT

8.6.1.389 Register: GPIO_FAULT

8.6.1.390 Register: UV_FAULT

8.6.1.391 Register: OV_FAULT

8.6.1.392 Register: UT_FAULT

8.6.1.393 Register: OT_FAULT

8.6.1.394 Register: TONE_FAULT

8.6.1.395 Register: COMM_UART_FAULT

8.6.1.396 Register: COMM_UART_RC_FAULT

8.6.1.397 Register: COMM_UART_RR_FAULT

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8.6.1.398 Register: COMM_UART_TR_FAULT

8.6.1.399 Register: COMM_COMH_FAULT

8.6.1.400 Register: COMM_COMH_RC_FAULT

8.6.1.401 Register: COMM_COMH_RR_FAULT

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Instruments

8.6.1.402 Register: COMM_COMH_TR_FAULT

8.6.1.403 Register: COMM_COML_FAULT

8.6.1.404 Register: COMM_COML_RC_FAULT

8.6.1.405 Register: COMM_COML_RR_FAULT

8.6.1.406 Register: COMM_COML_TR_FAULT

8.6.1.407 Register: OTP_FAULT

8.6.1.408 Register: RAIL_FAULT

8.6.1.409 Register: OVUV_BIST_FAULT

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8.6.1.410 Register: OTUT_BIST_FAULT

8.6.1.411 Register: ECC_DATAOUT0

8.6.1.412 Register: ECC_DATAOUT1

8.6.1.413 Register: ECC_DATAOUT2

8.6.1.414 Register: ECC_DATAOUT3

8.6.1.415 Register: ECC_DATAOUT4

8.6.1.416 Register: ECC_DATAOUT5

8.6.1.417 Register: ECC_DATAOUT6

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NSTRUMENTS

8.6.1.418 Register: ECC_DATAOUT7

8.6.1.419 Register: ECC_DATAOUT8

8.6.1.420 Register: SEC_BLK

8.6.1.421 Register: DED_BLK

8.6.1.422 Register: DEV_ADD_STAT

8.6.1.423 Register: COMM_STAT

8.6.1.424 Register: DAISY_CHAIN_STAT

8.6.1.425 Register: VCELL1_HU

8.6.1.426 Register: VCELL1_MU

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8.6.1.427 Register: VCELL1_LU

8.6.1.428 Register: VCELL2_HU

8.6.1.429 Register: VCELL2_MU

8.6.1.430 Register: VCELL2_LU

RESULT[7:0] Cell 2 Voltage Low Byte 2s complement (Reference Uncorrected)

8.6.1.431 Register: VCELL3_HU

8.6.1.432 Register: VCELL3_MU

8.6.1.433 Register: VCELL3_LU

8.6.1.434 Register: VCELL4_HU

8.6.1.435 Register: VCELL4_MU

8.6.1.436 Register: VCELL4_LU

8.6.1.437 Register: VCELL5_HU

8.6.1.438 Register: VCELL5_MU

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8.6.1.439 Register: VCELL5_LU

8.6.1.440 Register: VCELL6_HU

8.6.1.441 Register: VCELL6_MU

8.6.1.442 Register: VCELL6_LU

8.6.1.443 Register: AUX_BAT_HU

8.6.1.444 Register: AUX_BAT_LU

8.6.1.445 Register: AUX_GPIO1_HU

8.6.1.446 Register: AUX_GPIO1_MU

8.6.1.447 Register: AUX_GPIO1_LU

8.6.1.448 Register: AUX_GPIO2_HU

8.6.1.449 Register: AUX_GPIO2_LU

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8.6.1.450 Register: AUX_GPIO3_HU

8.6.1.451 Register: AUX_GPIO3_LU

8.6.1.452 Register: AUX_GPIO4_HU

8.6.1.453 Register: AUX_GPIO4_LU

8.6.1.454 Register: AUX_GPIO5_HU

8.6.1.455 Register: AUX_GPIO5_LU

8.6.1.456 Register: AUX_GPIO6_HU

8.6.1.457 Register: AUX_GPIO6_LU

8.6.1.458 Register: CUST_CRC_RSLTH

8.6.1.459 Register: CUST_CRC_RSLTL

FXAS NSTRUMENTS

9 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The BQ79606A-Q1 device provides simultaneous, high accuracy, channel measurements for three to six battery cells.

9.2 Typical Applications

9.2.1 Base Device with Measurement Applications Circuit

図 **41. Typical Base Device with Measurement Applications Circuit**

9.2.1.1 Design Requirements

 $\frac{1}{3}$ [34](#page-228-0) below shows the design parameters

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9.2.1.2 Detailed Design Procedure

9.2.1.2.1 LDO Output Bypass

AVDD, VLDO, and DVDD require a decoupling capacitor of no greater than 2.2μF, with minimum temperature stability rating of X7R (COG/NPO provide better performance). C_VLDO can be as high as 4uF but it will cause slower start up time.

9.2.1.2.2 Reference Bypass

REF1 requires a decoupling capacitor of no greater than 2.2μF, with minimum temperature stability rating of X7R (COG/NPO provide better performance).

9.2.1.2.3 CVDD and VIO Supply Inputs

Connect CVDD to VLDO through a 0Ω resistor (with the exception of Bridge Device of input supply from 4.75V to 5.5V, it must be supplied from an external power supply). Connect VIO to the system rail between 1.8V and 5.25V. VIO is supplied from the system logic supply or is connected to VLDO or CVDD for stack devices (or systems without a logic supply). Both CVDD and VIO require a decoupling capacitor of no greater than 2.2μF, with minimum temperature stability rating of X7R (COG/NPO provide better performance).

9.2.1.2.4 BAT Input

The BAT input must include a low-pass filter using a 0.33- μ F capacitor and a 100 Ω resistor to avoid voltage stress during cell connection (hot-plug). 図 [41](#page-228-1) illustrates the correct VBAT connection. If voltage spikes greater than 36V are expected, connect a transient suppression diode (TVS) to TOP to clamp the voltage to below 36 V to prevent an over-voltage condition on BAT during these events.

9.2.1.2.5 LDOIN Supply Input Bypass

The LDOIN input must include a low-pass filter using a 0.33µF capacitor and a 40 Ω to 50 Ω resistor to avoid voltage stress during cell connection (hot-plug). 図 [41](#page-228-1) illustrates the correct LDOIN connection.

9.2.1.2.6 CB Input

The Cell Balancing input are connected to internal balance FET through balancing resistor. The resistor sets the balance current. Connect CBn to VCn if not used. The CB pins must NEVER be connected to cell voltages (module connectors) that are expected to be less than the recommended operating condition. The internal FET diode will conduct and likely damage the FET in reverse voltage conditions. CB0 can not be left floating at any condition.

If a connection to cell1 negative terminal is open the IC bias current will flow through the CB1/VC1 pins and then to the cell2 negative module terminal, causing CB1 and VC1 pins to go below the minimum voltage recommended with respect to pin AVSS. This violates device spec. If the module connector ground pin can float while the other module terminals are still connected it is recommended that a schottky diode be added between CB1 and device GND (AVSS) to ensure that CB1 and VC1 pin voltage does not violate the absolute maximum limits.

図 **42. CB Input Connections**

9.2.1.2.7 VC* Inputs

While the BQ79606A-Q1 does contain an internal, anti-aliasing RC filter for the cell inputs, many applications experience transient spikes above the absolute maximum rating of the BQ79606A-Q1. For these applications, an additional ESD or a differential RC filter can be connected to reduce voltage spikes that may exceed the absolute maximum voltage ratings. \boxtimes [43](#page-232-0) provides a reference for the VC* input filter. The voltage from VCn to VCn-1 is limited by the cell voltage, see the pin functions table for more details on voltage rating and values. The resistor values are selected based on the values selected for the CB* (cell balancing) inputs. The values for the VC and CB resistors must be at least 4 times the value of each other in order for the best hot plug performance. Larger values for VC can be always be used, however, the larger the value, the more effect it has on the measurement accuracy. The recommended procedure after the CB resistor is selected, is to select the VC resistor value to be 4 times (recommended to improve SNR and hot pug performance) the value for CB resistor values. See *Selecting Cell Balance [Resistors](#page-239-0)* for details on the selecting the cell balance resistor value.

The recommended filter capacitor on VC0 to VC6 listed in \boxtimes [43](#page-232-0) (they are different from pin to the other). It is recommended in these combinations for better transient response. If transient response is not a concern, the capacitor valued from 0.47uF to 1uF can be used on all VC pins.

図 **43. Input Filter Connections**

9.2.1.2.7.1 Unused VC Inputs (Modules with less than 6 cells)

The device is capable of operation with 3 to 6 cells. For modules with less than 6 cells, the VC* inputs must be used in ascending order, with all unused inputs connected together with the input to the highest used VC* input. For example, in a 4- cells design, inputs VC5, and VC6 are not used. These VC inputs must be connected together with VC4 for proper operation. The same with CB pins. See \boxtimes [44](#page-233-0) for an example.

9.2.1.2.8 GPIO* Inputs

The GPIO* inputs are configurable to provide measurement results in ratio-metric form, when measuring an external temperature sensor, or absolute voltage, when measuring an external rail.

9.2.1.2.8.1 Ratiometric Measurement Configuration

When measuring an external temperature sensor, the GPIO connections require a resistor divider from TSREF to AVSS, with the GPIO input connected to the center tap. The NTC is connected from TSREF to GPIO or from GPIO to AVSS, depending on the application requirements. The connections are shown in \boxtimes [45.](#page-234-0) The resistors linearize the NTC curve to provide the best accuracy over the temperature range of interest.

図 **45. GPIO Ratiometric Measurement**

The resistors, R1 and R2, are calculated based on the desired temperature range of interest and the NTC used. For the following calculations, the linearization is highest between 10% and 90% of full scale. First, the temperature range of interest must be selected. This range sets the best resolution (and therefore accuracy) of the temperature sensor. The resistance of the NTC must be calculated for the extremes of this range. Use the following equation to calculate R_{HOT} (the resistance at the hottest temperature) and R_{COID} (the resistance at the coldest temperature):

$$
R_{TS} = R_0 \times e^{\beta \times \left(\frac{1}{T} - \frac{1}{25^{\circ}C}\right)}
$$
\n(9)

Where $R_{\sf TS}$ is the calculated NTC resistance, R_0 is the room temperature value of the thermistor, β is the temperature coefficient of the thermistor and T is the temperature for the calculated resistance.

Once RHOT and RCOLD are calculated, use the following equations to calculate R1 and R2. For the case where the NTC is connected from GPIO to AVSS, R1 and R2 are calculated using:

$$
R_2 = \frac{80 \times R_{HOT} \times R_{COLD}}{R_{COLD} - 81 \times R_{HOT}}
$$
\n(10)

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STRUMENTS

$$
R_1 = \frac{9 \times R_{HOT} \times R_2}{R_2 + R_{HOT}}
$$
\n
$$
\tag{11}
$$

For the case where the NTC is connected between TSREF and GPIO, R1 and R2 are calculated using:

$$
R_{2} = \frac{80 \times R_{HOT} \times R_{COLD}}{9 \times R_{COLD} - 9 \times R_{HOT}}
$$

\n
$$
R_{1} = \frac{9 \times R_{COLD} \times R_{2}}{R_{COLD} - 9 \times R_{2}}
$$
\n(12)

Additionally, connect a 1- kΩ resistor from the center tap of the resistor divider to the GPIO input (GPIO pin used as input to AUX ADC to measure the temperature) and bypass VGPIO to AVSS with a 1-μF capacitor.

When the NTC is connected from GPIO to AVSS the temperature of the sensor is calculated as:

$$
Temp = \frac{1}{\ln\left(\frac{R1 \times R2 \times RATIO _ ADC}{R0 \times (R1 \times RATIO _ ADC - R2 \times (1 - RATIO _ ADO))}\right) + \frac{1}{25}}
$$
\n(14)

When the NTC is connected from TSREF to GPIO the temperature of the sensor is calculated as:

$$
Temp = \frac{1}{\ln\left(\frac{R1 \times R2 \times (1 - RATIO _ ADC)}{R0 \times (R1 \times RATIO _ ADC - R2 \times (1 - RATIO _ ADC))}\right)} + \frac{1}{25}
$$
\n(15)

Where RATIO ADC is the result of \vec{x} 3, R1 and R2 are the linearization resistor values, R0 is the NTC value at room temperature (25C), and $β$ is the temperature coefficient of the NTC.

When measuring a voltage, these channels require a simple external low-pass filter to reduce high frequency noise for best operation. The RC values correspond to the customer's application requirements.

9.2.1.2.8.2 Absolute Measurement Configuration

When measuring a voltage, GPIO* connections require a series resistor and bypass capacitor for filtering to ensure best results. See \boxtimes [46](#page-236-0) for connection example.

図 **46. GPIO Voltage Measurement**

9.2.1.2.8.3 Unused GPIO Inputs*

Connect GPIO* to AVSS through a 10-kΩ resistor if unused.

9.2.1.2.9 UART Communication Bus

The UART interface requires the that TX and RX are pulled-up to VIO through a 10-kΩ to 100-kΩ resistor. Do not leave TX and RX unconnected. The TX must be pulled high to prevent triggering an invalid communications frame during the idle state when TX is high. When using a serial cable to connect to the host controller, connect the TX pull up on the host side and the RX pull up on the BQ79606A-Q1side.

9.2.1.2.10 Daisy-Chain Differential Bus

9.2.1.2.10.1 Devices on Same PCB

For applications where multiple BQ79606A-Q1 IC's are daisy chained on the same board, a single level-shifting capacitor is connected between the COM_ and FAULT_ pins of the devices. The capacitor value is 1000pF to 2500pF (2200pF typical) with a voltage rating of at least two times the total stack of cells voltage (for 400V system a 800V is required). In a case of the devices are not on the same PCB. The level shifting capacitors should be connected on both sides as shown below:

Components Required for Capacitive Coupled Daisy Chain in the same PCB 図 **47. Connections for Stacked Devices on the Same PCB**

9.2.1.2.10.2 Devices Separated by Cabling (Not on the Same PCB)

Many applications require multiple, daisy-chained BQ79606A-Q1 devices that are separated by cables. The cable introduces additional challenges to the application. To provide proper isolation for these applications, the BQ79606A-Q1 supports both transformer and capacitor isolation.

9.2.1.2.10.2.1 Capacitor Isolation (Not the same PCB)

The drivers and protocol for the BQ79606A-Q1 is suitable to drive transformer and capacitor isolation for the daisy chain communication. The following sections detail the implementation for capacitor isolation. Note that both types of isolation are possible in a system, with no differences in the setup of each device. For example, it is possible to use transformer isolation between the low-voltage and high-voltage boundary for galvanic isolation, while using capacitor isolation between modules in the stack. The figure below shows capacitive isolation with and without choke. The choke adds additional robustness during BCI noise and long cable applications. With the capacitor plus choke, a 300mA BCI noise can easily be achieved. For capacitive only isolation, up to 200mA BCI with 1.7m cable can be achieved.

A. Components Required for Capacitive Coupled Daisy Chain with Cabling (200mA BCI)

B. Components Required for Capacitive+ Choke Coupled Daisy Chain with Cabling (300mA BCI)

図 **48. Capacitor Isolation Circuit**

Isolation Capacitor

The differential signal lines are isolated between ICs by a DC blocking capacitor. The capacitor must be rated with a high enough voltage to provide standoff margin in the event of a fault in the system that exposes the device to a local hazardous voltage. Selecting a capacitor rated at a minimum of two times the stack voltage is the recommended practice. Ideally, only one 1000pF to 2500pF (2200pF typical) capacitor is sufficient for the normal operation of the device. However, two capacitors may be used (one at each end of the cable or PCB wiring) for an additional safety factor and proper coupling on both sides of the cable.

The capacitance on the daisy chain bus has a direct effect on performance. All parasitic capacitances from the support components and cabling must be taken into consideration when designing for communication robustness to EMC. Capacitance from the cables, ESD diodes, bypass capacitance, and chokes, form a capacitive divider with the isolation capacitors that may affect performance. Additionally, the amount of capacitance on the bus has a direct impact to the operating current during communication (the capacitor charging/ discharging).

Common-Mode Filter

While not required for cable lengths less than 2m and BCI performance of less than 200mA, longer cable lengths, or abnormally noisy applications may require the use of a common-mode choke filter. Capacitive isolation plus choke has better noise immunity than capacitor only. For 1.7m cable and according to ISO 11452-4 BCI spec, the capacitor only isolation can pass up to 200mA BCI noise and if a choke is added, a 300mA BCI noise can be handled. For these applications, use an automotive grade from 100uH to 500 μH common-mode filter minimum for proper operation. To achieve the best performance in noisy environments, use dual commonmode filters (470 μH). The recommended impedance of the choke is at least 1KΩ from 1MHz to 100MHz and

above 300 Ω for higher frequencies **9.2.1.2.10.2.2 Transformer Isolation**

The drivers and protocol for the BQ79606A-Q1 is suitable to drive transformer and capacitor isolation for the daisy chain communication. The following sections detail the implementation for transformer isolation. Note that both types of isolation are possible in a system, with no differences in the setup of each device. For example, it is possible to use transformer isolation between the low-voltage and high-voltage boundary for galvanic isolation, while using capacitor isolation between modules in the stack. If transformer isolation is used, a 1K Ω termination resistor is required between the COM P and COM N

図 **49. Transformer Isolation Circuit**

Transformer Specifications

The BQ79606A-Q1 has been designed and tested with transformers ranging from 150uH to 650uH. The recommended parameters for the isolation transformer are as follows:

- Inductance: 150uH to 650µH
- Leakage Inductance: ~20µH
- Automotive rated
- Operating Temperature: -40C to 125C
- Isolation voltage: Depends on total stack voltage (example 2500V AC, 1000V DC for an 400V system) .

9.2.1.2.10.2.3 Daisy-Chain Cables

When selecting the cabling, keep in mind that the cable adds parasitics to the system. For capacitively isolated systems, the capacitance of the cable forms a divider with the isolation capacitance. See the [Capacitor](#page-237-0) Isolation (Not the [same](#page-237-0) PCB) section for details. The capacitance of the cable is calculated using the equation:

$$
C = \frac{2.2\epsilon}{Log\left(\frac{1.3 \text{ D}}{f \times d}\right)}
$$

where

- $C =$ mutual capacitance, pF/ft
- ϵ = insulation dielectric constant (for example: PVC = 5)
- $f =$ stranding factor (for example: 1 strand = 1, 7 strands = 0.939, 19 strands = 0.97, 37 strands = 0.98)
- $D =$ diameter over the insulation, inches
- $d =$ diameter of the conductor, inches (12)

The unshielded twisted cable used for bench testing (Alpha Wire 3050 series, Digi-Key part number +A2015W-1000-ND) has the following specifications:

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(16)

- ϵ = 5 (PVC)
- $f = 0.939$ (7 strand)
- $D = 0.056"$
- $d = 0.024$ " (0.056" 2 x 0.016" insulation thickness)
- conductor DCR = 25 $Ω/1000$ ft

The resulting capacitance is \approx 21.6 pF/ft.

The best choice of differential cable is an automotive-grade, unshielded, twisted cable designed for CAN, such as the Waytek SAE J1939/15 CAN data bus cable. The capacitance for this cable is approximately 17 pF/ft.

9.2.1.2.10.3 Daisy Chain System Components

9.2.1.2.10.3.1 Series Termination Resistance

Select the series termination resistors for each COML_, COMH_, FAULTL_, or FAULTH_ lines between devices to be 120 Ω (~50Ω on each end of the signal connection between BQ79606A-Q1 devices plus the 10Ω internal resistance). This series resistance also limits the in-rush current during a service disconnect/reconnect event.

9.2.1.2.10.3.2 Bypass Capacitance

Select the bypass capacitors for each COML_, COMH_, FAULTL_, or FAULTH_ lines between devices to be 51pF. This bypass capacitance provides filtering as well as improved performance during BCI testing.

9.2.1.2.10.3.3 Daisy Chain System ESD Protection

The common-mode range for the BQ79606A-Q1 is suitable for common ESD protection diodes used for CAN applications. The ESD protector should provide protection to the communication interface pins during hot plug events and also for absorption of high-voltage transients during service disconnect/reconnect. Select the ESD diodes to limit the maximum voltage on the COM* or the FAULT* bus to below the maximum rating. A voltage rating close the maximum voltage to provide the highest possible common-mode voltage range is recommended for best EMC performance. The capacitance must be low compared to the coupling capacitance (if using capacitor coupling).

9.2.1.2.10.4 Unused Differential Communications Pins

Unused stack communications pins (COML_, COMH_, FAULTL_, or FAULTH_) have internal terminations; no external pull up or pull down resistors are required on these pins. If not used, leave the unused pins unconnected. The daisy chain transmitter and receiver enable/ disable control is found in the DAISY_CHAIN_CTRL register.

9.2.1.2.11 Cell Balancing

9.2.1.2.11.1 Selecting Cell Balance Resistors

 $\overline{}$

The cell balancing current, I_{FQ} , is set using the resistors, R_{FQ} . All cell balancing resistors must be the same value. The value for R_{FO} is calculated as:

$$
R_{EQ} = \frac{1}{2} \times \left(\frac{V_{BAT}}{I_{EQ}} - R_{DS\ (ON)} \right)
$$
 (17)

9.2.1.2.11.2 Differential Filter Capacitor Selection

Connect a 0.47uF to 1µF, 10V capacitor between CBn and CBn-1 to filter out high voltage, high frequency voltage transients that may exceed the absolute maximum rating for the CB voltage.

9.2.1.2.11.3 Cell Balancing External MOSFET Selection (optional)

For applications that require more balancing current, the BQ79606A-Q1supports external FETs. Select the Balance FET based on the following criteria:

- 1. The VDS must be selected based on derating requirements determined by the stack voltage.
- 2. The VGS threshold must be low enough to turn on with the lowest battery voltage planned for balancing. The

gate of the MOSFET sees half of the battery voltage, so the VGS of the MOSFET must be selected to provide sufficiently low RDSON at half of the lowest battery voltage.

 R_{DSON} is not a major concern, but must be taken into account when choosing the resistors. Power dissipation of the FET is a function of discharge current selected and the resistance value of FET at that worst-case condition, usually at hot temperature. I²R calculates the power dissipated. Take care in selecting size if using very small packages. A series resistor between the CB pin and the FET gate limits current going into the FET during hot plug or other transient events. The VGS capacitor ensures the FET is not turned on during hotplug due to the miller capacitance of the FET. Also note that P and N FET combination can be used.

図 **50. Cell Balancing Circuit with External MOSFETs**

9.2.1.2.12 Post-Assembly Calibration

9.2.1.2.12.1 Cell ADC Post-Assembly Calibration

Use of post-assembly calibration adjustment can improve device accuracy further after exposure to soldering and/or bake cycles in the manufacturing process. ADC gain and offset-correction factors are programmable for each cell in the BQ79606A-Q1 to allow for post-assembly calibration. The total range of adjustment limitation for the gain factor is -19.4mV to 19.4mV and the offset factor is -24.2mV to 24.2mV. Application of the corrections is to the raw ADC values after application of the factory stored offset and gain corrections. Perform the correction procedures at room temperature (RT) using a stable, high-accuracy DC source and / or voltmeter. The registers contain signed 2's complement values. A zero value in either register indicates no correction. Measurement of two voltage points, VIN1 and VIN2, occurs for each correction. The expected minimum and maximum values for the cell can be used.

9.2.1.2.12.1.1 Gain Error Correction

Gain Error Correction: For a 5V cell voltage, -19.4 mV to 19.4 mV in 255 steps (8 bits) in the CELL^{*}_GAIN registers (one per channel) Procedure:

1. Set the CELL ADC to 1MHz frequency, 256 Decimation Ration, Corner freqeuncy to 1.2 Hz for best results.

- 2. Apply voltage VIN1, read back from ADC VOUT1 in the VCELL*_LF, VCELL*_HF registers, and record both.
- 3. Apply voltage VIN2, read back from ADC VOUT2 in the VCELL^{*}_LF, VCELL^{*}_HF registers, and record both.
- 4. Find the gain error correction (GEC) at 5 V (5V is used regardless of VINx value) and write the 8-bit value to the CELL*_GAIN register.
	- 1. Calculate slope m = (VOUT2–VOUT1) / (VIN2–VIN1)
	- 2. The gain error is calculated at 5V. Thus Gain Error=[(5V*m)-5V]
	- 3. The Gain Shift value is 19.4mV*2/255=0.15mV
	- 4. Then take the negative of the gain and divide it by the gain shift to find bit shift required Bit Shift=(-Gain Error)/(Gain Shift)
	- 5. Then convert bit shift to a two's complement hex value
	- 6. Make sure that if the bit shift is greater than "127", the hex value will be "7F"
	- 7. Make sure that if the bit shift is less than "-128", the hex value will be "80"
	- 8. Finally enter the calculated Hex value to CELL*_Gain
- 5. Repeat steps 1-3 on each cell voltage
- 6. Perform the steps in Offset Error Correction.

9.2.1.2.12.1.2 Offset Error Correction

Offset Error Correction: –24.2 mV to +24.2 mV in 255 steps (8 bits) in the CELL*_OFF registers (one per channel) Procedure: (Use recorded, VIN1, and VOUT1 from the Gain Error Correction procedure.)

- 1. Find the offset value based on the VIN1 value, Offset=(VIN1-VOUT1)/(190.7348uV)
- 2. Convert to a two's complement hex
- 3. Make sure that if the offset is greater than "127", the hex value will be "7F"
- 4. Make sure that if the offset is less than "-128", the hex value will be "80"
- 5. Write the 8-bit value to the CELL* OFF register
- 6. Repeat steps 1-5 on each cell voltage
- 7. Save the new values to OTP by following the NVM programming procedure.
- 8. The OTP CRC must be re-calculation and saved due to this (or any) change.

9.2.1.2.12.2 GPIO Post-Assembly Calibration*

Using post-assembly calibration adjustment can also improve the GPIO channel accuracy further after exposure to soldering and/or bake cycles in the manufacturing process. The process is the same as the steps for the VC* channel correction. Perform the correction procedures at room temperature (RT) using a stable, high-accuracy DC source and / or voltmeter. The registers contain 10-bit, signed, 2's-complement values. A zero value in any register indicates no correction. Each correction measures two voltage points. The procedure can use the expected minimum and maximum values for the cell. The gain values are updated in the GPIO*_GAIN registers and the offset values are updated in the GPIO* OFF registers.

9.2.1.2.13 Device Addressing

Every device must have a unique address for the read functionality to work. If, for any reason, two devices are assigned with the same address, it is likely that broadcast and stack reads do not work. Additionally, reads to the doubled address result in destroyed communication. Care must be taken to assign independent address for every device. There are three ways to address the device: using NVM burn on the DEVADD_OTP[ADD], using auto-addressing, and using GPIO addressing.

9.2.1.2.13.1 NVM Stored Address

The user can program the device address on the DEVADD_OTP register. As part of the reset process, the OTP restores the value in DEVADD_OTP[ADD]. This address is saved in the OTP as part of the NVM burn.

9.2.1.2.13.2 Auto Addressing

Prior to using the Auto-Addressing function in a stack, all devices must be awake and ready for communication. The steps necessary for this state are detailed elsewhere in this document, but typically require a few milliseconds per device (t_{SUVMAKE}) . Very simple "stacks" consisting of a single device may use address 0x00 (or any other valid address) for the device. The first device in stacks of more than one device may also use Address 0x00.

When CONFIGIGPIO ADD SEL] = 0 and CONTROL1[ADD WRITE EN] is set, the device enters automatic addressing mode. In this mode, the device turns off the daisy-chain transmitters for one frame (so the next frame received is not propagated to the next device) and enables writes to DEVADD USR[ADD]. The next frame sent must set the address. Once the next frame is received (this frame must be the address or it will save the address currently in the register), the CONTROL1[ADD_WRITE_EN] bit is self cleared and the address is not writeable. Additionally, the result is reflected in the DEV ADD_STAT[ADD] bits indicating the address is updated. At this time, the user may write to the DEVADD_OTP[ADD] bits to save the address, or the addressing may be done as part of the initialization process. When the CONTROL1[ADD_WRITE_EN] bit is self cleared, the transmitter is turned on. This allows the host to use a Broadcast write transaction and only affect the one part waiting for an address. To auto-address the stack of BQ79606A-Q1 devices, use the following procedure (assumes CONFIG[GPIO ADD SEL] = 0 in the OTP):

- 1. Broadcast write CONTROL1[ADD_WRITE_EN] = 1
- 2. Broadcast write consecutive addresses to DEVADD_USR[ADD] until all parts have been assigned a valid address.
- 3. Single device write "0x00" to the base device to set the as BASE device in the CONFIG[STACK_DEV] register bit.
- 4. Single device write "0x02" to to all devices except the top and bottom of stack to set them as stack devices in the CONFIG[STACK_DEV] register bit..
- 5. Single device write "0x03" to the top device in the stack to set the CONFIG[TOP_STACK] bit and update the CRC for that device

Good practice dictates that all devices be checked by reading back their address registers, at a minimum, to establish that the addressing functions worked properly. Subsequent reading and writing depend on correctly addressed devices in the stack or executing any customer-initiated tests, such as the checksum test.

9.2.1.2.13.3 GPIO Addressing

Prior to using the GPIO addressing function in a stack, all devices must be awake and ready for communication. The steps necessary for this state are detailed elsewhere in this document, but typically require a few milliseconds per device. Very simple "stacks" consisting of a single device may use address 0x00 (or any other valid address) for the device. The first device in stacks of more than one device may also use address 0x00. GPIO1 to GPIO6 are programmable to be addressing inputs using the GPIO*_CONF[ADD_SEL] bit. When fewer stack devices are used, fewer GPIOs are required for addressing. For example, if 10 device address are required, only GPIO1 through GPIO4 are required for addressing. The additional GPIOs are still available for the additional functionality. The GPIO number corresponds to the bit number in the DEV ADD STAT register (i.e. GPIO2 is bit 2). The GPIO is automatically setup as input when addressing is enabled (GPIO*_CONF[ADD_SEL]=1). GPIO*_CONF[GPIO_SEL] bit is ignored.

When CONFIG[GPIO_ADD_SEL] = 1 and CONTROL1[ADD_WRITE_EN] is set, the device enters GPIO addressing mode. In this mode, the device samples the enabled GPIO and updates the DEV ADD STAT[ADD] bits. Any GPIOs that do not have GPIO addressing mode enabled are read as '0'. At this time, the user may write to the DEVADD_OTP[ADD] bits to save the address, or the addressing may be done as part of the initialization process. Once the address is updated, the CONTROL1[ADD_WRITE_EN] bit is self cleared and the address is not writeable. It should be noted that once the GPIOs are used for the addressing, they may be reconfigured to be used in a different function without affecting the addressing. To GPIO-address the stack of BQ79606A-Q1 devices, use the following procedure

- 1. Configure the addressing GPIOs in hardware to the required address. The addressing must be sequential from the first to the last device
- 2. Broadcast write to the GPIO^{*} CONF[ADD_SEL] bits to enable the required addressing GPIOs
- 3. Broadcast write CONFIG[GPIO_ADD_SEL] = 1 (if not already set by OTP default)
- 4. Broadcast write CONTROL1[ADD_WRITE_EN] = 1

- 5. Set the CONFIG[STACK_DEV] register bit as base for base device and as stack for stack devices.
- 6. Single device write to the top device in the stack to set the CONFIG[TOP_STACK] bit and update CRC for that device

Good practice dictates that all devices be checked by reading back their address registers, at a minimum, to establish that the addressing functions worked properly. Subsequent reading and writing depend on correctly addressed devices in the stack or executing any user-initiated tests.

9.2.1.2.14 Calculating Wakeup Timing

9.2.1.2.14.1 Wakeup Timing in SHUTDOWN Mode (or Initial Powerup)

When power is applied to the IC, the internal analog supply AVAO_REF is turned on. After AVAO_REF is turned on, the IC transitions to SHUTDOWN mode. The VLDO turn ON after t_{PORtoWKRDY}. Once that happened, the device is ready for communication. The wake up process is as follows:

- 1. The host microcontroller pulses the WAKEUP input on the base device to initiate the wakeup sequence
- 2. IC enables the AVDD and DVDD LDOs as well as all of the required references and enters ACTIVE mode.
- 3. The IC sends a WAKE tone to the next device in the stack. The WAKE tone is received in n_{WAKFDFT} t_{COMTONE}
- 4. The next IC repeats steps 2 and 3.
- 5. The process repeats until all devices transition to ACTIVE mode.

The total time to transition a full stack from POR to ACTIVE is calculated as: $n_{devices}^*t_{SU(WAKE)}$

The total time to transition a full stack from SHUTDOWN to ACTIVE is calculated as: ndevices*tSU(WAKE)

9.2.1.2.14.2 Wakeup Timing in SLEEP Mode

There are two methods to transition the stack from SLEEP mode to ACTIVE mode. The first method is to send a WAKE command. This resets the entire stack to the OTP defaults. The second is to send a SLEEPtoACTIVE command. This command only transitions the device to ACTIVE mode and does NOT reset the register content.

9.2.1.2.14.2.1 Wake Up Command

When sending a WAKE command, the process is as follows:

- 1. The host microcontroller pulses the WAKEUP input on the base device to initiate the wakeup sequence
- 2. IC enters ACTIVE mode and loads the registers with the default values from OTP. This transition takes tSU(SLPtoACT)2
- 3. The IC sends a WAKE tone to the next device in the stack. The WAKE tone is received in $n_{WAKEDET}$ *t_{COMTONE}
- 4. The next IC repeats steps 2 and 3.
- 5. The process repeats until all devices transition to ACTIVE mode.

9.2.1.2.14.2.2 SLEEPtoACTIVE command

When sending a SLEEPtoACTIVE command, the process is as follows:

- 1. The host microcontroller holds the RX input low $(t_{UART(STA)})$ on the base device to initiate the sleep to active sequence
- 2. IC enters ACTIVE mode. This transition takes $t_{\text{SUSLPtoACT}1}$
- 3. The IC sends a SLEEPtoACTIVE tone to the next device in the stack. The SLEEPtoACTIVE tone is received in n_{SLPtoACTDET} * t_{COMTONE}
- 4. The next IC repeats steps 2 and 3.
- 5. The process repeats until all devices transition to ACTIVE mode.

The total time to transition a full stack from SLEEP to ACTIVE with a SLEEPtoACTIVE command is calculated as: $t_{\text{UART}(StA)} + n_{\text{devices}} * t_{\text{SU}(SLPtoACT)1} + (n_{\text{devices}} - 1) * n_{\text{SLPtoACTDET}} * t_{\text{COMTONE}}$

The total time to transition a full stack from SLEEP to ACTIVE with a WAKE command is calculated as: $2*$ t $_{\text{HLD}}$ wake + $n_{\text{devices}}*$ t_{SU(SLPtoACT)2} + (n_{devices} -1)* $n_{\text{WAKEDET}}*$ t_{COMTONE}

The plots below shows the wake up timing of 17 devices. One device is used as a base and 16 devices as stack. The WAKEUP pin of the base device is hold low for approximately 270us and base send wake up tone upstream. The wake up tone is $t_{COMTONF}$ long. SLEEP to ACTIVE tone sending is 40 tones at max. The experiment below show 4.4ms time for each device to wake up. It took total of 75ms for 17 devices to wake up.

Channel 1: WAKEUP pin of the base device. **Channel 2**: COML* pin of the device 16. **Channel 3**: COML* pin of the device 15. **Channel 4**: AVDD pin of device 16.

9.2.2 Bridge Mode

The BQ79606A-Q1 supports low voltage operation from a 4.75V power supply, such as a CAN power supply when used as bridge device. For this application, the some of the power supplies for the device must be powered by the external supply for best operational results. Connect CVDD supply directly to the input supply. Note that in this configuration, the power supply range is limited to 4.75V to 5.5V.

[BQ79606A-Q1](http://www.tij.co.jp/product/jp/bq79606a-q1?qgpn=bq79606a-q1)

図 **55. Typical Application Circuit for Bridge Device for Input Supply From 4.75V to 5.5V**

The BQ79606A-Q1 also supports high voltage operation from a 5.5V power supply to 30V. For such application, the CVDD must connect to VLDO (NOT from VLDOIN).

図 **56. Typical Application Circuit for Bridge Device for Input Supply From 5.5V to 30V**

9.2.2.1 Design Requirements

 $\bar{\ddot{\mathcal{R}}}$ [35](#page-246-0) below shows the design requirements.

表 **35. Recommended Design Requirements**

9.2.2.2 Detailed Design Procedure

See Detailed Design [Procedure](#page-229-0) for information.

9.2.2.3 Application Curves

The plots below show the positive effect of re-clocking. The figure on the left captures the communication line of the first device in the stack of 16 (channel 1). The figure on the right shows the communication line of the last device in the stack (in this case device 16) channel 3. Both plots shows 250ns pulse duration. Bit compression is not present and the difference between bit-widths is 0, even with higher device counts. Without re-clocking, the pulse width of the last device in the stack will experience bit compression and eventually communication loss. With re-clocking this issue is solved and the number of device in the stack can increase as high as 64 devices without experiencing any communication loss. The other benefit of this feature is the ability to support longer cable length.

9.2.3 Capacitor Isolated System

Capacitive only isolation is recommended for same board communication, short cable, or in low noise applications. However, capacitor plus choke can be used for communication between boards. With a choke added, the capacitive isolation shows a very robust communication of up to 300mA BCI noise with 2m cable.

図 **59. Typical Module Application Circuit with Capacitor Isolation without Ring Configuration**

9.2.3.1 Design Requirements

9.2.3.2 Detailed Design Procedure

See Detailed Design [Procedure](#page-229-0) for information.

9.2.3.3 Application Curves

The picture below shows the advantage of the integrated digital low pass filter (the filter comes free as it is already integrated into the device). It compares a results 1.2Hz filter vs. 180Hz filter when a 50Hz/6Vpp noise injected into the sense lines. The 1.2Hz filter filters all noise whereas the 180Hz passes all the noise to the output.

図 **60. Digital Low Pass Filter Results**

9.2.4 Transformer Isolated System

The figure below shows a typical application circuit for 14 channels Module. The high voltage to low voltage connection must be done with transformer isolation. The same PCB connection can be done with capacitor only isolation. The connection between boards can be done with capacitor plus choke isolation. The module is a 14 channels where 3 devices of BQ79606A-Q1 are used. In the first two devices 5 channels are connect to each device. The third device has only 4 channels(5 by 5 by 4). A 6 by 4 by 4 configuration can also be done to support 14 channels. The VC and CB pins that are not required are shorted to the highest connection.

9.2.4.1 Design Requirements

9.2.4.2 Detailed Design Procedure

See Detailed Design [Procedure](#page-229-0) for information.

9.2.4.3 Application Curves

The figure below shows BCI results for capacitive, capacitive plus choke, and transformer isolation. The test are done according the ISO 11452-4 standard. The cable length is 1.7m and baud rate is set to 1Mbps. The BCI noise is injected on the communication lines.

9.2.5 Multi-Drop System

9.2.5.1 Design Requirements

9.2.5.2 Detailed Design Procedure

See Detailed Design [Procedure](#page-229-0) for information.

9.2.5.3 Application Curves

The figure below shows a single read of register C2 of device 5 in Multi drop communication.

[BQ79606A-Q1](http://www.tij.co.jp/product/jp/bq79606a-q1?qgpn=bq79606a-q1)

www.tij.co.jp JAJSH94 –APRIL 2019

10 Power Supply Recommendations

10.1 Communication Bridge System

The most common automotive battery system places a device on the low voltage bus (i.e. 5-V CAN supply or 12 V) where it interfaces with the stack across the daisy-chain interface, but is not connected to the stack itself.

A) with Transformer Isolation between high to low voltage boundary

10.2 Integrated Base Device System

A second application for smaller stacks has the base device integrated into the stack. It monitors the bottom cells in the stack as well handles the communication bus with the stack devices and the uC through UART. Note that the digital isolation is supplied from the BQ79606A-Q1 LDO. The load on the LDO from the digital isolator should not be more than 5mA.

Integrated Base Device System (continued)

図 **66. System Application with Integrated Base Device**

10.3 Multi-Drop System

A third application does not use the daisy-chain interface. Instead, all devices on the bus are seen as base devices. In this mode, all devices are connected in parallel and do not support the auto-addressing scheme. The addressing must be done sequentially using the GPIOs or individual writes before assembly. No specific bus arbitration is done, however, broadcast reads are supported using a similar methodology as the stack interface. In the multi-drop setup where a CAN transceiver is used (as in \boxtimes [66\)](#page-254-0), all devices RX inputs receive the TX communications from the other devices on the bus. It this configuration, the IC waits for the next highest address device to respond. Once it receives that response (must be CRC validated), it send its own response. The host must leave the bus clear during responses. There is no collision arbitration built in, where the BQ79606A-Q1 knows its communication has been stepped on. If the communication is interrupted (either by collision or failed CRC check) before all devices have responded, none of the remaining devices respond. A communication clear must be sent to clear the bus. Stack Read, Stack Write, and Write Reverse Direction are not supported in multidrop configuration.

Texas INSTRUMENTS

Multi-Drop System (continued)

図 **67. System Application with Multi-Drop Base Devices**

11 Layout

11.1 Layout Guidelines

The layout of BQ79606A-Q1 must be designed carefully. Design outside these guidelines can affect the ADC accuracy, cell balancing thermal performance, EMI performance and so on. Care must be taken in the layout of signals to and from the device to avoid coupling noise onto sensitive inputs. The layout of ground and power connections, as well as communication signals should also be made carefully.

11.1.1 Grounding

The BQ79606A-Q1 has two analog ground pins termed AVSS pin 15 and 45. AVSS of pin 15 is a generalpurpose analog ground associated with quiet grounds for sensitive internal analog circuitry and circuits supplied by VIO. The AVSS of pin 45 is used for the ADC internally, connect the decoupling capacitor of the REF1 to this pin for best ADC accuracy. The BQ79606A-Q1 device also has one CVSS pin for the daisy chain communication supply (CVDD). One DVSS pin is also present, supplying the ground for the internal digital core and supporting circuitry. In addition to these 4 ground pins, a power pad is located on the bottom of the device, and should be included in the GND plane to facilitate heat dissipation.

Creation of a good ground plane in the layout is crucial to getting optimal performance from the part. A good ground plane on a dedicated layer will improve measurement accuracy, reduce noise, and provide the necessary ESD, EMI, and EMC performance. There is a strong recommendation to have a minimum of four layers in the PCB, with one fully dedicated as an unbroken ground plane (except thermal reliefs). Avoid placing tracks on this layer to maintain the unbroken integrity of the plane structure.

All 4 device grounds, as well as the power pad, should connect to the ground plane with as short as possible track sections to minimize the effects of stray inductance on noise performance.

If more than one BQ79606A-Q1 is included on a single PCB assembly, each will require its own plane in the area surrounding the device. This is required because each device has its own VSS reference, often separated by more than 21V from VSS-to-VSS of adjacent ICs in the stack. These can exist on the same physical layer, with correct separation and clearance requirements.

Although the plane is employed as a solid GND reference with all grounds connected to it, good layout practice still requires locating any decoupling capacitors as close to the pin they are associated with as possible. This reduces inductance and keeps the loop area as small as possible, which in turn keeps the capacitors as effective as possible in reducing noise. In this document, the reference term for combined grounds connected to the ground plane is ground or GND.

The layout of BQ79606A-Q1 has 3 grounds:

- 1. AVSS (pin 15): This is an Analog Ground. This pin must not be left unconnected and must be connected to the CVSS and DVSS externally. This ground is the ground connection for internal analog circuits.
- 2. AVSS (pin 45): This is an analog Ground. Pin 45 is not connected to pin 15 internally. Ground connection for internal ADC circuits. It is important for best ADC accuracy to connect as close as possible the decoupling capacitor of the REF1 to this pin. Connect CVSS, DVSS, and AVSS externally. This pin must not be left unconnected and must be connected to the CVSS and DVSS externally.
- 3. CVSS (pin 26): This is the ground for the Daisy chain communication. Connect AVSS, CVSS, and DVSS externally. CVSS must NOT be left unconnected.
- 4. DVSS (pin 35):This is digital ground. Connect AVSS, CVSS, and DVSS externally. DVSS must NOT be left unconnected.

11.1.2 Differential Communication

The BQ79606A-Q1 uses two differential communications links to transmit signals between ICs in a stack. Employing differential links provides superior noise immunity. The base device then translates the differential signals back to a single-ended signal. It is important to maintain the signal integrity of each differential pair to maximize immunity to interfering signals from external sources.

- 1. Keep wires and PCB traces as short as possible. Do not exceed datasheet recommendations.
- 2. For any single-signal pair between two nodes (ICs), individual wires and traces should have the same length.
- 3. Unshielded, twisted-pair wiring is required for any cable runs.
- 4. Run PCB traces in parallel, on the same layer, without any other traces or planes in between. Long runs

should avoid noisy traces and/or be stitched at intervals similar to twisted-pair wire.

5. Use high-quality capacitors for voltage isolation between ICs and place in close physical proximity to each other as part of the parallel-track layout.

In addition to capacitor based communication, the BQ79606A-Q1 also supports transformer based communications. In general, the recommendations above still apply, except for item 5. For transformer based communication, be sure to select a transformer that provides isolation appropriate for the specific application.

11.1.3 Power Supplies and Reference

The layout for the BQ79606A-Q1 power supplies and references must be done properly to minimize noise.

- 1. REF1 (pin 46): This is High-Power Reference Bypass Connection. Make sure to connect the cap as close as possible to the REF1 and AVSS pin 45 and the trace is noise free.
- 2. TSREF (pin 43): Bias Voltage for temperature sensing (NTC) Monitor. The decoupling capacitor must be placed as close as possible to the pin. Leave TSREF unconnected if the NTC monitoring is not used.
- 3. DVDD (pin 36): This is a digital 1.8V regulator. The decoupling capacitor must be placed as close as possible to the pin and make the trace noise free as possible.
- 4. CVDD (pin 25): This is Daisy Chain Communication Power. The decoupling capacitor must be placed as close as possible to the pin and make the trace noise free as possible.
- 5. AVDD (pin 44): This is 5-V Regulator Output. The decoupling capacitor must be placed as close as possible to the pin and make the trace noise free as possible.
- 6. VLDO (pin 39): This is a 5-V Regulator Output. VLDO supplies CVDD. Bypass VLDO to AVSS with ceramic capacitor of typical value of 2.2μ F and place it as close as possible to the pin.

11.2 Layout Example

To ensure the best possible accuracy performance, TI recommends following some basic layout guidelines for the bq769606-Q1 to provide best EMI and BCI performance. The isolation caps must be placed close to the edge of the board. The Common Mode Chokes must be close to the daisy-chain cable connector to provide a high-impedance path to common-mode noise as it enters the board. Place the series resistors and TVS diodes next to the BQ79606A-Q1.

An unbroken ground plane layer as part of a four or more layer board is recommended, with all AVSS, CVSS, DVSS, and power pad connections made directly to the plane. The common GND planes, the cell balance 0 pin (CB0), and cell voltage sense 0 pin (VC0) are all three star connected directly to BAT0. There should also be a keep-out area on plane area adjacent to the isolation capacitors or transformers if daisy-chain communication is implemented. The following is a list of grounds.

- 1. AVSS (pin 15)– Power section (noisy GND) and VIO circuitry.
- 2. AVSS (pin 45)– Power section (noisy free GND) used for REF1 and the internal ADC circuitry. Any noise injected into this pin will affect the ADC accuracy and performance.
- 3. CVSS Power Section for Daisy Chain.
- 4. DVSS Digital GND.

Layout Example (continued)

Keep as many signal traces as possible on Top and Bottom Layers and an unbroken internal GND Plane

図 **68. Layout Example**

the IC pin as possible

12 デバイスおよびドキュメントのサポート

12.1 ドキュメントの更新通知を受け取る方法

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12.5 Glossary

[SLYZ022](http://www.ti.com/lit/pdf/SLYZ022) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

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(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures. "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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PACKAGE OPTION ADDENDUM

TEXAS

TAPE AND REEL INFORMATION

ISTRUMENTS

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Feb-2023

*All dimensions are nominal

7 x 7, 0.5 mm pitch QUAD FLATPACK

GENERIC PACKAGE VIEW

PHP 48 TQFP - 1.2 mm max height

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

PHP0048N PowerPAD HTQFP - 1.2 mm max height TM

PLASTIC QUAD FLATPACK

PACKAGE OUTLINE

NOTES:

PowerPAD is a trademark of Texas Instruments.

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- 4. Reference JEDEC registration MS-026.
- 5. Feature may not be present.

EXAMPLE BOARD LAYOUT

PHP0048N PowerPAD HTQFP - 1.2 mm max height TM

PLASTIC QUAD FLATPACK

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
- 8. This package is designed to be soldered to a thermal pad on the board. See technical brief, Powerpad thermally enhanced package, Texas Instruments Literature No. SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
- 9. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.
- 10. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

PHP0048N PowerPAD HTQFP - 1.2 mm max height TM

PLASTIC QUAD FLATPACK

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

12. Board assembly site may have different recommendations for stencil design.

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